

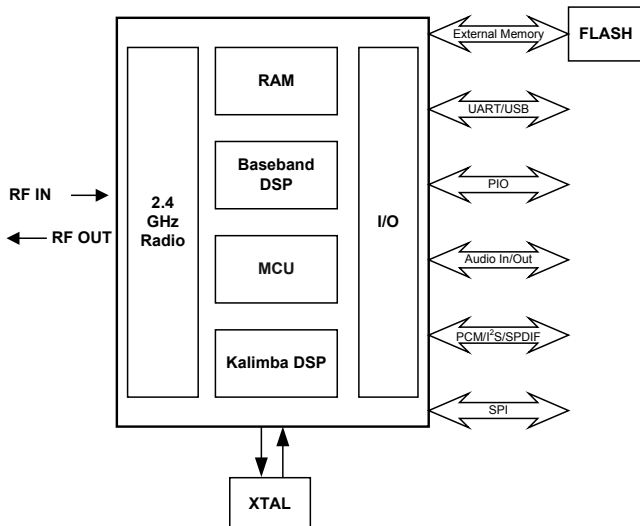
Device Features

- Fully Qualified Bluetooth v2.1 + EDR Specification System
- Best in Class Bluetooth Radio with +8dBm Transmit Power and -90dBm Receive Sensitivity
- 64MIPS Kalimba DSP Co-processor
- 16-bit Internal Stereo CODEC - 95dB SNR for DAC
- Low-power 1.5V Operation, 1.8V to 3.6V I/O
- Integrated 1.5V and 1.8V Linear Regulators
- Integrated Switched-mode Regulator
- Integrated Battery Charger
- USB, I²C and UART with Dual-port Bypass Mode to 4Mbits/s
- Supports up to 32-Mbit of External Flash Memory (8-Mbit Typical Requirement)
- Multi-configurable I²S, PCM or SPDIF Interface
- Enhanced Audibility and Noise Cancellation
- 8 x 8 x 1.2mm TFBGA
- Support for 802.11 Co-existence
- RoHS Compliant

General Description

The BlueCore™5-Multimedia External is a single-chip radio and baseband IC for Bluetooth 2.4GHz systems.

BlueCore5-Multimedia External interfaces up to 32-Mbit of external Flash memory. When used with the CSR Bluetooth stack, it provides a fully compliant Bluetooth v2.1 + EDR specification system for data and voice.



BlueCore™5-Multimedia External

Single Chip Bluetooth® v2.1+EDR System

Production Information

BC57E687B

September 2007

Applications

- High-quality Stereo Wireless Headsets
- High-quality Mono Headsets
- Hands-free Car Kits
- Wireless Speakers
- VoIP Handsets
- Analogue and USB Multimedia Dongles
- Bluetooth-enabled Automotive Wireless Gateways

BlueCore5-Multimedia External contains the Kalimba DSP co-processor with double the MIPS of BlueCore3-Multimedia External, supporting enhanced audio applications.

BlueCore5-Multimedia External is designed to reduce the number of external components required which ensures production costs are minimised. The device incorporates auto-calibration and *built-in self-test* (BIST) routines to simplify development, type approval and production test.

To improve the performance of both Bluetooth and 802.11b/g co-located systems a wide range of co-existence features are available including a variety of hardware signalling: basic activity signalling, Intel WCS activity and channel signalling.

For additional performance information refer to the *BlueCore5-Multimedia External Performance Specification*.

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Status Information

The status of this Data Sheet is **Production Information**.

CSR Product Data Sheets progress according to the following format:

Advance Information

Information for designers concerning CSR product in development. All values specified are the target values of the design. Minimum and maximum values specified are only given as guidance to the final specification limits and must not be considered as the final values.

All detailed specifications including pinouts and electrical specifications may be changed by CSR without notice.

Pre-Production Information

Pinout and mechanical dimension specifications finalised. All values specified are the target values of the design. Minimum and maximum values specified are only given as guidance to the final specification limits and must not be considered as the final values.

All electrical specifications may be changed by CSR without notice.

Production Information

Final Data Sheet including the guaranteed minimum and maximum limits for the electrical specifications.

Production Data Sheets supersede all previous document versions.

ESD Precautions

BlueCore5-Multimedia External is classified as a JESD22-A224 class 0 product. Apply ESD static handling precautions during manufacturing.

Life Support Policy and Use in Safety-Critical Applications

CSR's products are not authorised for use in life-support or safety-critical applications. Use in such applications is done at the sole discretion of the customer. CSR will not warrant the use of its devices in such applications.

RoHS Compliance

BlueCore5-Multimedia External devices meet the requirements of Directive 2002/95/EC of the European Parliament and of the Council on the Restriction of Hazardous Substance (RoHS).

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1 Device Details

Radio

- Common TX/RX terminal simplifies external matching; eliminates external antenna switch
- BIST minimises production test time
- Bluetooth v2.1 + EDR specification compliant

Transmitter

- +8dBm RF transmit power with level control from on-chip 6-bit DAC over a dynamic range >30dB
- Class 2 and Class 3 support without the need for an external power amplifier or TX/RX switch

Receiver

- Receiver sensitivity of -90dBm
- Integrated channel filters
- Digital demodulator for improved sensitivity and co-channel rejection
- Real-time digitised RSSI available on HCI interface
- Fast AGC for enhanced dynamic range

Synthesiser

- Fully integrated synthesiser requires no external VCO, varactor diode, resonator or loop filter
- Compatible with crystals 16MHz to 26MHz or an external clock 12MHz to 52MHz
- Accepts 14.40, 15.36, 16.2, 16.8, 19.2, 19.44, 19.68, 19.8 and 38.4MHz TCXO frequencies for GSM and CDMA devices with sinusoidal or logic level signals

Baseband and Software

- 32-Mbit of external Flash
- 48-Kbyte of internal RAM, allows full-speed data transfer, mixed voice/data and full piconet support
- Logic for forward error correction, header error control, access code correlation, CRC, demodulation, encryption bit stream generation, whitening and transmit pulse shaping
- Transcoders for A-law, μ -law and linear voice from host and A-law, μ -law and CVSD voice over air

Physical Interfaces

- *Serial peripheral interface (SPI)* with clock speeds up to 64MHz in Master mode⁽¹⁾ and 32MHz in Slave mode
- I²C master compatible interface
- UART interface with programmable data rate up to 3Mbits/s with an optional bypass mode
- Full speed USB v1.1 interface
- Bi-directional serial programmable audio interface supporting PCM, I²S and SPDIF formats
- Two LED drivers with faders

⁽¹⁾ Requires firmware support

Kalimba DSP

- Very low power Kalimba DSP co-processor, 64MIPS, 24-bit fixed point core
- *Sub-band coding (SBC)* decode takes approximately 4mW power consumption while streaming music
- Single-cycle MAC; 24 x 24-bit multiply and 56-bit accumulator
- 32-bit instruction word, dual 24-bit data memory
- 24-Kbyte (6-Kword) program RAM, 36-Kbyte + 48-Kbyte (16-Kword + 12-Kword) data RAM
- 64-word x 32-bit program memory cache when executing from Flash

Stereo Audio CODEC

- 16-bit internal stereo CODEC
- Dual ADC and DAC for stereo audio
- Integrated amplifiers for driving 16 Ω speakers; no need for external components
- Support for single-ended speaker termination and line output
- Integrated low-noise microphone bias
- ADC sample rates are 8, 11.025, 16, 22.05, 32 and 44.1kHz
- DAC sample rates are 8, 11.025, 16, 22.05, 32 and 44.1kHz

Auxiliary Features

- User space on processor for customer applications
- Crystal oscillator with built-in digital trimming
- Power management includes digital shutdown and wake-up commands with an integrated low-power oscillator for ultra-low power Park/Sniff/Hold mode
- Clock request output to control external clock
- On-chip regulators: 1.5V output from 1.8V to 2.7V input and 1.8V output from 2.7V to 4.5V input
- On-chip high-efficiency switched-mode regulator; 1.8V output from 2.7V to 4.4V input
- Power-on-reset cell detects low supply voltage
- 10-bit ADC and 8-bit DAC available to applications
- On-chip charger for lithium ion/polymer batteries

Bluetooth Stack

CSR's Bluetooth Protocol Stack runs on the on-chip MCU in a variety of configurations:

- Standard HCI (UART or USB)
- Audio CODEC and echo-noise suppression or customer-specific algorithms running on the DSP

Package Option

- TFBGA 169-ball, 8 x 8 x 1.2mm, 0.5mm pitch

2 Device Diagram

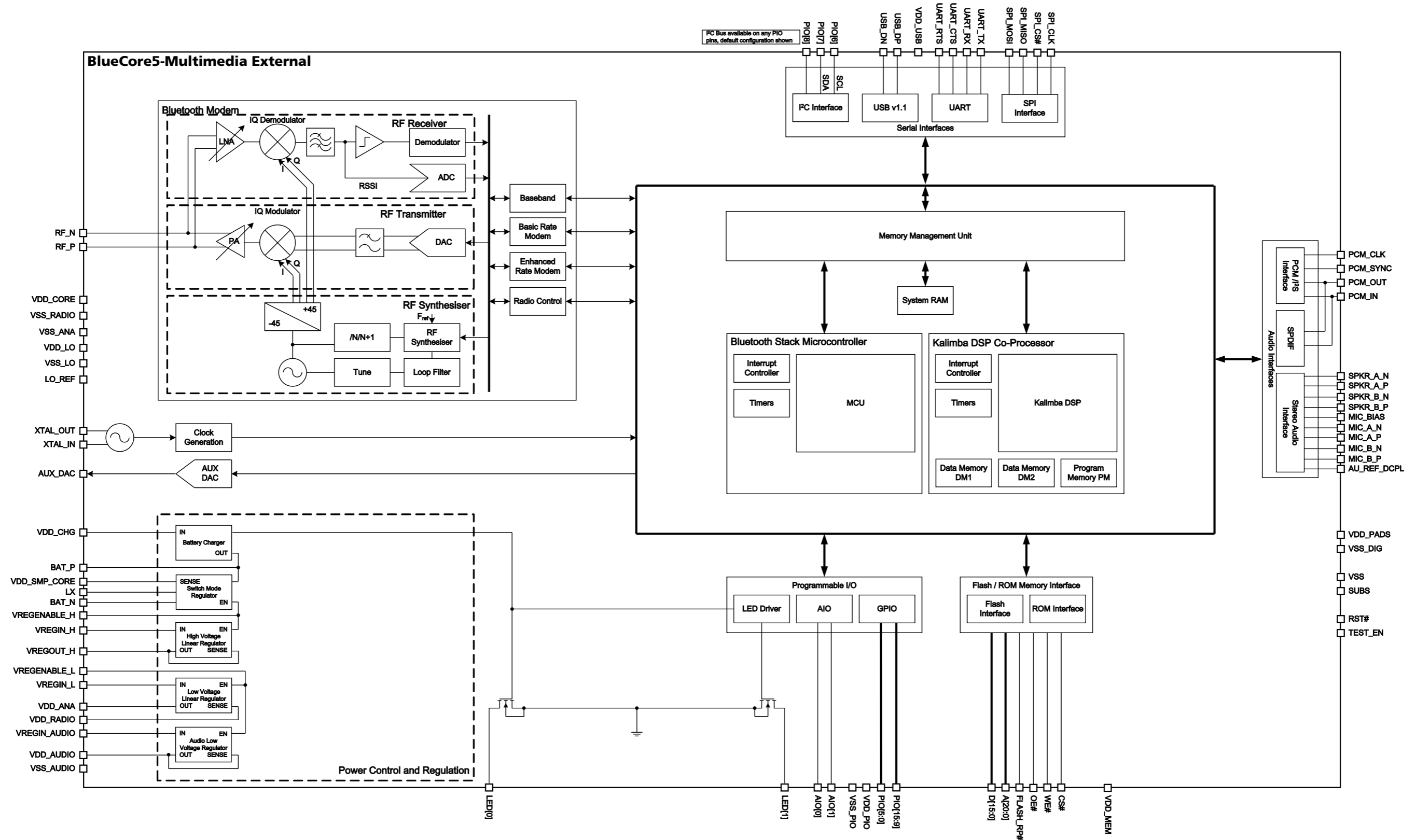


Figure 2.1: BlueCore5-Multimedia External Device Diagram

3 Package Information

3.1 Pinout Diagram

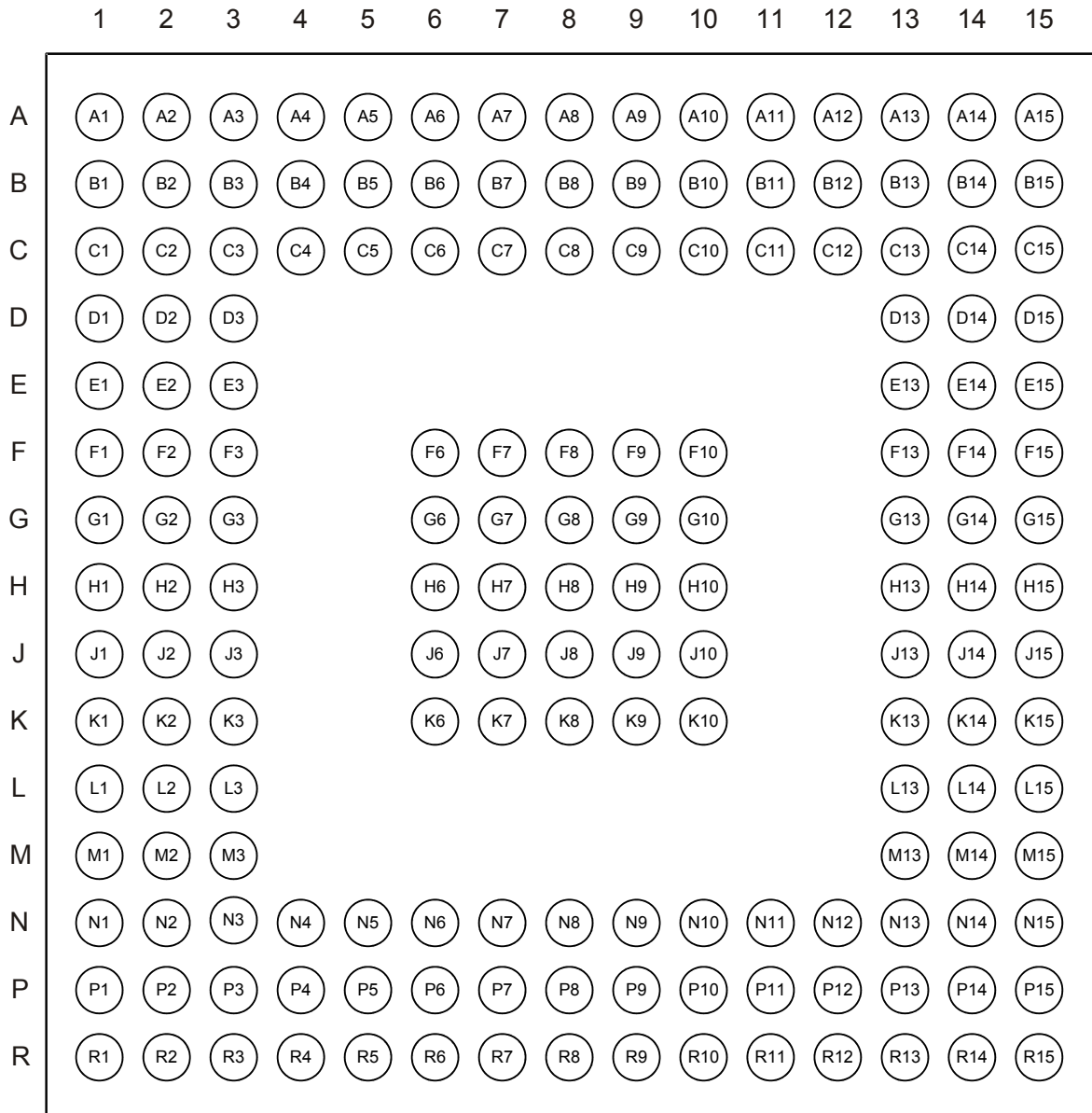


Figure 3.1: BlueCore5-Multimedia External Device Pinout

3.2 Device Terminal Functions

Radio	Ball	Pad Type	Supply Domain	Description
RF_P	K1	RF	VDD_RADIO	Transmitter output/switched receiver input
RF_N	L1	RF	VDD_RADIO	Complement of RF_P
AUX_DAC	H2	Analogue	VDD_PIO	8-bit voltage-output DAC

Synthesiser and Oscillator	Ball	Pad Type	Supply Domain	Description
XTAL_IN	R1	Analogue	VDD_ANA	For crystal or external clock input
XTAL_OUT	R2	Analogue	VDD_ANA	Drive for crystal
LO_REF	P3	Analogue	VDD_ANA	Reference voltage to decouple the synthesiser

USB and UART	Ball	Pad Type	Supply Domain	Description
UART_TX	N15	Bi-directional CMOS output, tri-state, with weak internal pull-up	VDD_USB	UART data output
UART_RX	N14	CMOS input with weak internal pull-down	VDD_USB	UART data input
UART_RTS	R15	Bi-directional CMOS output, tri-state, with weak internal pull-up	VDD_USB	UART request to send active low
UART_CTS	P15	CMOS input with weak internal pull-down	VDD_USB	UART clear to send active low
USB_DP	P14	Bi-directional	VDD_USB	USB data plus with selectable internal 1.5kΩ pull-up resistor
USB_DN	P13	Bi-directional	VDD_USB	USB data minus

PCM Interface	Ball	Pad Type	Supply Domain	Description
PCM_OUT	F15	CMOS output, tri-state, with weak internal pull-down	VDD_PADS	Synchronous data output
PCM_IN	G15	CMOS input, with weak internal pull-down	VDD_PADS	Synchronous data input
PCM_SYNC	F14	Bi-directional with weak internal pull-down	VDD_PADS	Synchronous data sync
PCM_CLK	F13	Bi-directional with weak internal pull-down	VDD_PADS	Synchronous data clock

SPI Interface	Ball	Pad Type	Supply Domain	Description
SPI_MISO	D15	CMOS output, tri-state, with weak internal pull-down	VDD_PADS	SPI data output
SPI_MOSI	E13	CMOS input, with weak internal pull-down	VDD_PADS	SPI data input
SPI_CS#	E15	Input with weak internal pull-up	VDD_PADS	Chip select for Serial Peripheral Interface (SPI), active low
SPI_CLK	E14	Input with weak internal pull-down	VDD_PADS	SPI clock

PIO Port	Ball	Pad Type	Supply Domain	Description
PIO[15]	M15	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[14]	J15	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[13]	K14	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[12]	K13	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[11]	L14	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[10]	M13	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[9]	M14	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[8]	J14	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[7]	J13	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line

PIO Port	Ball	Pad Type	Supply Domain	Description
PIO[6]	H15	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[5]	H14	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[4]	H13	Bi-directional with programmable strength internal pull-up/down	VDD_PADS	Programmable input/output line
PIO[3]	F3	Bi-directional with programmable strength internal pull-up/down	VDD_PIO	Programmable input/output line
PIO[2]	G3	Bi-directional with programmable strength internal pull-up/down	VDD_PIO	Programmable input/output line
PIO[1]	F2	Bi-directional with programmable strength internal pull-up/down	VDD_PIO	Programmable input/output line (external TXEN)
PIO[0]	F1	Bi-directional with programmable strength internal pull-up/down	VDD_PIO	Programmable input/output line (external RXEN)
AIO[1]	N3	Bi-directional	VDD_ANA	Analogue programmable input/output line
AIO[0]	R4	Bi-directional	VDD_ANA	Analogue programmable input/output line

Test and Debug	Ball	Pad Type	Supply Domain	Description
RST#	G13	CMOS input with weak internal pull-up	VDD_PADS	Reset if low. Input debounced so must be low for >5ms to cause a reset
TEST_EN	G14	CMOS input with strong internal pull-down	VDD_PADS	For test purposes only (leave unconnected)

External Memory Address Interface	Ball	Pad Type	Supply Domain	Description
A[20]	N12	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[19]	P8	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[18]	N9	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[17]	R10	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[16]	P9	CMOS output, tri-state, weak pull-up	VDD_MEM	Address line
A[15]	R5	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[14]	P5	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[13]	N5	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[12]	R6	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[11]	P6	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[10]	N6	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[9]	R7	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[8]	P7	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[7]	P10	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[6]	N10	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line

External Memory Address Interface	Ball	Pad Type	Supply Domain	Description
A[5]	R11	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[4]	P11	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[3]	N11	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[2]	R12	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[1]	P12	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line
A[0]	C9	CMOS output, tri-state, weak pull-down	VDD_MEM	Address line

External Memory Data Interface	Ball	Pad Type	Supply Domain	Description
D[15]	A5	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[14]	C5	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[13]	B6	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[12]	A7	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[11]	C7	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[10]	C8	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[9]	B10	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[8]	A11	Bi-directional with weak internal pull-down	VDD_MEM	Data line

External Memory Data Interface	Ball	Pad Type	Supply Domain	Description
D[7]	B5	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[6]	A6	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[5]	C6	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[4]	B7	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[3]	B8	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[2]	A9	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[1]	C10	Bi-directional with weak internal pull-down	VDD_MEM	Data line
D[0]	B11	Bi-directional with weak internal pull-down	VDD_MEM	Data line

External Memory Interface	Ball	Pad Type	Supply Domain	Description
FLASH_RP#	R9	CMOS output, tri-state with internal weak pull-up	VDD_MEM	Flash reset
OE#	C11	CMOS output, tri-state with internal weak pull-up	VDD_MEM	Output enable for external memory, active low
WE#	N7	CMOS output, tri-state with internal weak pull-up	VDD_MEM	Flash write enable for external memory, active low
CS#	A10	CMOS output, tri-state with internal weak pull-up	VDD_MEM	Chip select for external memory, active low

CODEC	Ball	Pad Type	Supply Domain	Description
MIC_A_P	C2	Analogue	VDD_AUDIO	Microphone input positive, left
MIC_A_N	C1	Analogue	VDD_AUDIO	Microphone input negative, left
MIC_B_P	B2	Analogue	VDD_AUDIO	Microphone input positive, right
MIC_B_N	B1	Analogue	VDD_AUDIO	Microphone input negative, right

CODEC	Ball	Pad Type	Supply Domain	Description
SPKR_A_P	E1	Analogue	VDD_AUDIO	Speaker output positive, left
SPKR_A_N	E2	Analogue	VDD_AUDIO	Speaker output negative, left
SPKR_B_P	D1	Analogue	VDD_AUDIO	Speaker output positive, right
SPKR_B_N	D2	Analogue	VDD_AUDIO	Speaker output negative, right
MIC_BIAS	B3	Analogue	VDD_AUDIO, BAT_P	Microphone bias
AU_REF_DCPL	E3	Analogue	VDD_AUDIO	Decoupling of audio reference (for high-quality audio)

LED Drivers	Ball	Pad Type	Supply Domain	Description
LED[1]	D14	Open drain output	See Section 11.10	LED driver
LED[0]	D13	Open drain output	See Section 11.10	LED driver

Power Supplies and Control	Ball	Pad Type	Description
VREGENABLE_H	B14	Analogue	Take high to enable high-voltage linear regulator and switch-mode regulator
VREGIN_H	A15	Regulator input	Input to internal high-voltage linear regulator
VREGOUT_H	B15	Supply	High-voltage linear regulator output
VREGENABLE_L	M2	Analogue	Take high to enable both low-voltage regulator and audio low-voltage regulator
VREGIN_L	N2	Regulator input	Input to internal low-voltage linear regulator for non-audio core circuitry
VDD_ANA	P1	VDD/Low-voltage regulator output	Positive supply output for analogue circuitry and 1.5V regulated output (from internal low-voltage regulator)
VREGIN_AUDIO	A3	Regulator input	Input to internal audio low-voltage linear regulator
VDD_AUDIO	A2	VDD/Low-voltage regulator output	Positive supply output for audio circuitry and 1.5V regulated output (from internal low-voltage regulator)
VDD_CHG	A12	Charger input	Lithium ion/polymer battery charger input
BAT_P	B13	Battery terminal +ve	Lithium ion/polymer battery positive terminal. Battery charger output and input to switch-mode regulator
VDD_SMP_CORE	A14	VDD	Positive supply for switch mode control circuitry
LX	A13	Switch-mode power regulator output	Switch-mode power regulator output

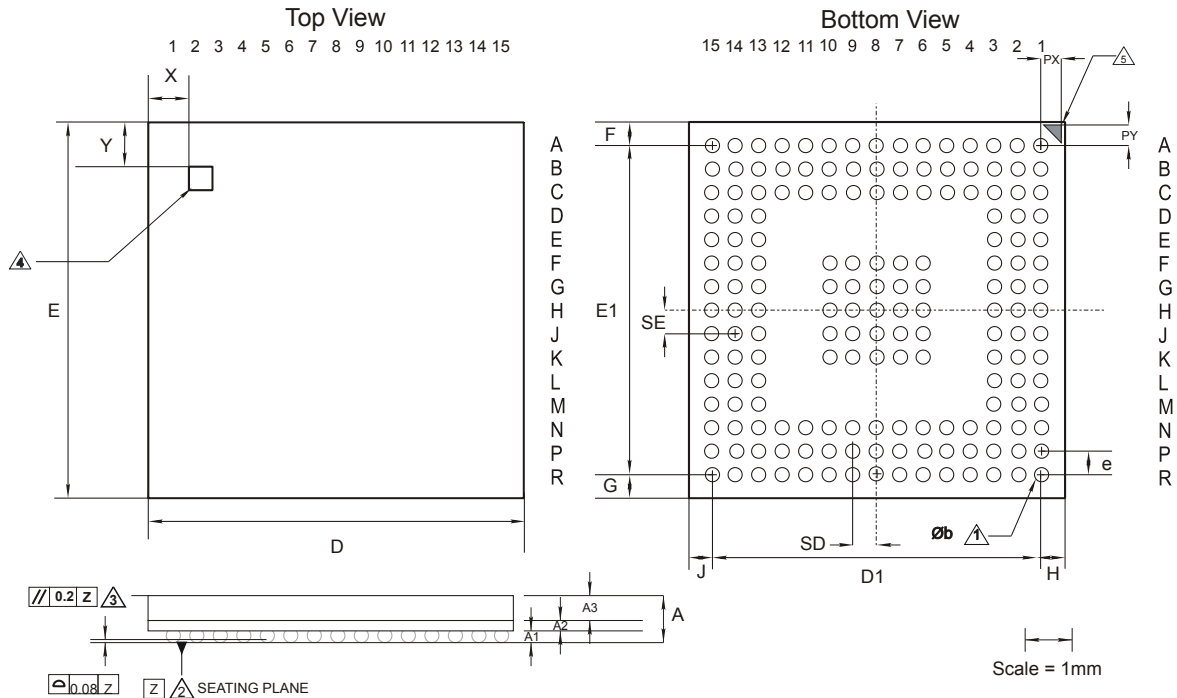
Power Supplies and Control	Ball	Pad Type	Description
VDD_CORE	C15, K15	VDD	Positive supply for internal digital circuitry, 1.5V
VDD_RADIO	M1	VDD/Low-voltage regulator sense	Positive supply for RF circuitry, 1.5V
VDD_LO	N1	VDD	Positive supply for local oscillator circuitry, 1.5V
VDD_USB	R14	VDD	Positive supply for UART/USB ports
VDD_PIO	G1	VDD	Positive supply for PIO and AUX DAC ^(a)
VDD_PADS	L15	VDD	Positive supply for all other digital Input/Output ports ^(b)
VDD_MEM	A4, A8, B9, R8, R13	VDD	Positive supply for Flash pads
VSS_DIG	B4, C4, C12, C13, C14, H3, L13, N4, N8, N13,	VSS	Ground connection for internal digital circuitry
VSS_RADIO	J2, K2, L2	VSS	Ground connections for RF circuitry
VSS_LO	K3, L3	VSS	Ground connections for local oscillator
VSS_ANA	P2	VSS	Ground connections for analogue circuitry
VSS_AUDIO	A1, D3	VSS	Ground connection for audio
VSS	C3, F6-F10, G6-G10, H6-H10, J3, J6-J10, K6-10, M3	VSS	Ground connection
BAT_N	B12	Battery terminal -ve	Lithium ion/polymer battery negative terminal. Ground connection for switch-mode regulator
SUBS	R3	VSS	Connection to internal die substrate Connect to lowest possible potential

^(a) Positive supply for PIO[3:0]

^(b) Positive supply for SPI/PCM ports and PIO[15:4]

Unconnected Terminals	Ball	Description
N/C	G2, H1, J1, P4	Leave unconnected

3.3 Package Dimensions



Description		169-Ball Thin Fine-Pitch Ball Grid Array (TFBGA)		
Size		8 x 8 x 1.2mm		
Pitch		0.5mm		
Package Ball Land		Solder mask defined. Solder mask aperture 275 μ m \varnothing		
Dimension	Minimum	Typical	Maximum	Notes
A			1.2	① Dimension b is measured at the maximum solder ball diameter parallel to datum plane Z
A1	0.16	0.21	0.26	
A2		0.21		② Datum Z is defined by the spherical crowns of the solder balls
A3		0.7		
b	0.27	0.32	0.37	③ Parallelism measurement shall exclude any effect of mark on top surface of package
D	7.90	8.00	8.10	
E	7.90	8.00	8.10	④ Top-side polarity mark. The dimensions of the square polarity mark are 0.75 x 0.75mm.
e		0.5		
D1		7.00		⑤ Bottom-side polarity mark. The dimensions of the triangular polarity mark are 0.3 x 0.3 x 0.42mm.
E1		7.00		
F		0.50		
G		0.50		
H		0.50		
J		0.50		
PX		0.35		
PY		0.35		
SD		0.5		
SE		0.5		
X		1.35		
Y		0.85		
JEDEC	MO-195			
Unit	mm			

Figure 3.2: BlueCore5-Multimedia External 169-ball TFBGA Package Dimensions

3.4 PCB Design and Assembly Considerations

This section lists recommendations to achieve maximum board-level reliability of the 8 x 8 x 1.2mm TFBGA 169-ball package:

- *Non solder mask defined* (NSMD) lands (that is, lands smaller than the solder mask aperture) are preferred because of the greater accuracy of the metal definition process compared to the solder mask process. With solder mask defined pads, the overlap of the solder mask on the land creates a step in the solder at the land interface, which can cause stress concentration and act as a point for crack initiation.
- Ideally, via-in-pad technology should be used to achieve truly NSMD lands. Where this is not possible, a maximum of one trace connected to each land is preferred and this trace should be as thin as possible – taking into consideration its current carrying and the *radio frequency* (RF) requirements.
- 35µm thick (1oz) copper lands are recommended rather than 17µm thick (0.5oz). This results in a greater standoff which has been proven to provide greater reliability during thermal cycling.
- Land diameter should be the same as that on the package to achieve optimum reliability.
- Solder paste is preferred to flux during the assembly process because this adds to the final volume of solder in the joint, increasing its reliability.
- Where a nickel gold plating finish is used, the gold thickness should be kept below 0.5µm to prevent brittle gold/tin intermetallics forming in the solder.

3.4.1 ESD, EMI and EMC Considerations

In a commercial application, considerations must be made to:

- Protect BlueCore5-Multimedia External from *electrostatic discharge* (ESD). For more information see *BlueCore5-Multimedia External Recommendations for ESD Protection*
- Reduce interference with consideration for *electromagnetic interference* (EMI) and *electromagnetic compatibility* (EMC).

3.4.2 Thermal Resistance

By simulation to JEDEC JESD-51 the Theta Ja of the BlueCore5-Multimedia External 8 x 8 x 1.2mm TFBGA 169-ball package is 38°C/W, on a 4-layer PCB with zero air flow.

3.5 Typical Solder Reflow Profile

See *Typical Solder Reflow Profile for Lead-free Device* for information.

4 Bluetooth Modem

4.1 RF Ports

4.1.1 RF_N and RF_P

RF_N and RF_P form a complementary balanced pair and can be used for both transmit and receive. On transmit their outputs are combined using a balun into the single-ended output required for the antenna. Similarly, on receive their input signals are combined internally. Both terminals present similar complex impedances that require matching networks between them and the balun. Starting from the substrate (chip side), the outputs can each be modelled as an ideal current source in parallel with a lossy resistance and a capacitor. The package parasitics can be represented as an equivalent series inductance.

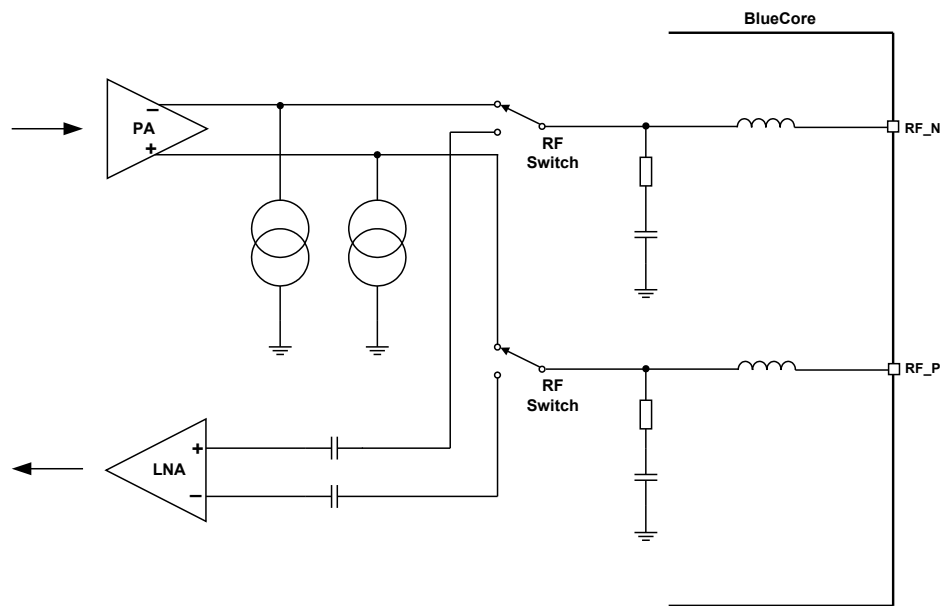


Figure 4.1: Simplified Circuit RF_N and RF_P

The DC level must be set at VDD_RADIO.

4.2 RF Receiver

The receiver features a near-zero *intermediate frequency* (IF) architecture that allows the channel filters to be integrated onto the die. Sufficient out-of-band blocking specification at the *low-noise amplifier* (LNA) input allows the receiver to be used in close proximity to *Global System for Mobile Communications* (GSM) and *Wideband Code Division Multiple Access* (W-CDMA) cellular phone transmitters without being desensitised. The use of a digital Frequency Shift Keying (FSK) discriminator means that no discriminator tank is needed and its excellent performance in the presence of noise allows BlueCore5-Multimedia External to exceed the Bluetooth requirements for co-channel and adjacent channel rejection.

For EDR, an ADC is used to digitise the IF received signal.

4.2.1 Analogue to Digital Converter

The *Analogue to Digital Converter* (ADC) implements fast *Automatic Gain Control* (AGC). The ADC samples the *received signal strength indicator* (RSSI) voltage on a slot-by-slot basis. The front-end LNA gain is changed according to the measured RSSI value, keeping the first mixer input signal within a limited range. This improves the dynamic range of the receiver, improving performance in interference limited environments.

4.3 RF Transmitter

4.3.1 IQ Modulator

The transmitter features a direct IQ modulator to minimise the frequency drift during a transmit timeslot, which results in a controlled modulation index. Digital baseband transmit circuitry provides the required spectral shaping.

4.3.2 Power Amplifier

The internal *Power Amplifier* (PA) has a maximum output power that allows BlueCore5-Multimedia External to be used in Class 2 and Class 3 radios without an external RF PA.

4.3.3 Transmit RF Power Control for Class 1 Applications (TX_PWR)

An 8-bit voltage DAC (AUX_DAC) controls the amplification level of the external PA for Class 1 operation. The DAC output is derived from the on-chip band gap and is virtually independent of temperature and supply voltage. Equation 4.1 and Equation 4.2 show the the output voltage:

$$V_{\text{DAC}} = \text{MIN} \left(\left(3.7\text{V} \times \frac{\text{EXT_PA_GAIN}}{255} - 0.008 \times I \right), V_{\text{DD_PIO}} - 0.008 \times I \right)$$

Equation 4.1: Output Voltage with Load Current I

or

$$V_{\text{DAC}} = \text{MIN} \left(\left(3.7\text{V} \times \frac{\text{EXT_PA_GAIN}}{255} - 0.008 \times I \right), V_{\text{DD_PIO}} \right)$$

Equation 4.2: Output Voltage with No Load Current

BlueCore5-Multimedia External enables the external PA only when transmitting. Before transmitting, the chip normally ramps up the power to the internal PA, then it ramps it down again afterwards. However, if a suitable external PA is used, it may be possible to ramp the power externally by driving the TX_PWR pin on the PA from AUX_DAC.

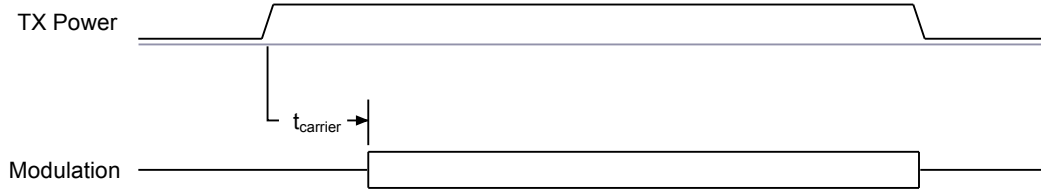


Figure 4.2: Internal Power Ramping

The *Persistent Store Key* (PS Key) PSKEY_TX_GAINRAMP (0x1d), is used to control the delay (in units of μs) between the end of the transmit power ramp and the start of modulation.

PS Key TXRX_PIO_CONTROL (0x209) controls external RF components such as a switch, an external PA or an external LNA. PIO[0], PIO[1] and the AUX_DAC can be used for this purpose, as Table 4.1 shows.

TXRX_PIO_CONTROL Value	PIO and AUX_DAC Use
0	PIO[0], PIO[1], and AUX_DAC not used to control RF. Power ramping is internal.
1	PIO[0] is high during RX, PIO[1] is high during TX. AUX_DAC not used. Power ramping is internal.
2	PIO[0] is high during RX, PIO[1] is high during TX. AUX_DAC used to set gain of external PA. Power ramping is external.
3	PIO[0] is low during RX, PIO[1] is low during TX. AUX_DAC used to set gain of external PA. Power ramping is external.
4	PIO[0] is high during RX, PIO[1] is high during TX. AUX_DAC used to set gain of external PA. Power ramping is internal.

Table 4.1: TXRX_PIO_CONTROL Values

4.4 Bluetooth Radio Synthesiser

The Bluetooth radio synthesiser is fully integrated onto the die with no requirement for an external *Voltage Controlled Oscillator* (VCO) screening can, varactor tuning diodes, LC resonators or loop filter. The synthesiser is guaranteed to lock in sufficient time across the guaranteed temperature range to meet the Bluetooth v2.1 + EDR specification.

4.5 Baseband

4.5.1 Burst Mode Controller

During transmission the *Burst Mode Controller* (BMC) constructs a packet from header information previously loaded into memory-mapped registers by the software and payload data/voice taken from the appropriate ring buffer in the RAM. During reception, the BMC stores the packet header in memory-mapped registers and the payload data in the appropriate ring buffer in RAM. This architecture minimises the intervention required by the processor during transmission and reception.

4.5.2 Physical Layer Hardware Engine DSP

Dedicated logic performs the following:

- Forward error correction
- Header error control
- Cyclic redundancy check
- Encryption
- Data whitening
- Access code correlation
- Audio transcoding

Firmware performs the following voice data translations and operations:

- A-law/ μ -law/linear voice data (from host)
- A-law/ μ -law/*Continuously Variable Slope Delta* (CVSD) (over the air)
- Voice interpolation for lost packets
- Rate mismatches

The hardware supports all optional and mandatory features of Bluetooth v2.1 + EDR specification including AFH and eSCO.

4.6 Basic Rate Modem

The Basic Rate modem satisfies the basic data rate requirements of the Bluetooth v2.1 + EDR specification. The basic rate was the standard data rate available on the Bluetooth v1.2 specification and below, it is based on *Gaussian Frequency Shift Keying* (GFSK) modulation scheme.

The inclusion of the basic rate modem allows BlueCore5-Multimedia External compatibility with earlier Bluetooth products.

The basic rate modem uses the RF Ports, Receiver, Transmitter and Synthesiser, alongside the baseband components described in Section 4.5.

4.7 Enhanced Data Rate Modem

The *Enhanced Data Rate* (EDR) modem satisfies the requirements of the Bluetooth v2.1 + EDR specification. EDR has been introduced to provide 2x and 3x data rates with minimal disruption to higher layers of the Bluetooth stack. BlueCore5-Multimedia External supports both the basic and enhanced data rates and is compliant with the Bluetooth v2.1 + EDR specification.

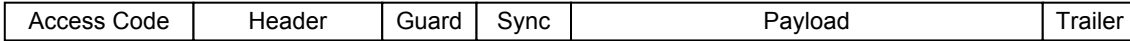
At the baseband level, EDR utilises both the same 1.6kHz slot rate and the 1MHz symbol rate as defined for the basic data rate. EDR differs in that each symbol in the payload portion of a packet represents 2 or 3-bits. This is achieved using two new distinct modulation schemes. Table 4.2 and Figure 4.3 summarise these. Link Establishment and management are unchanged and still use GFSK for both the header and payload portions of these packets.

The enhanced data rate modems uses the RF Ports, Receiver, Transmitter and Synthesiser, with the baseband components described in Section 4.5.

Data Rate Scheme	Bits Per Symbol	Modulation
Basic Data Rate	1	GFSK
EDR	2	$\pi/4$ DQPSK
EDR	3	8DPSK (optional)

Table 4.2: Data Rate Schemes

Basic Rate

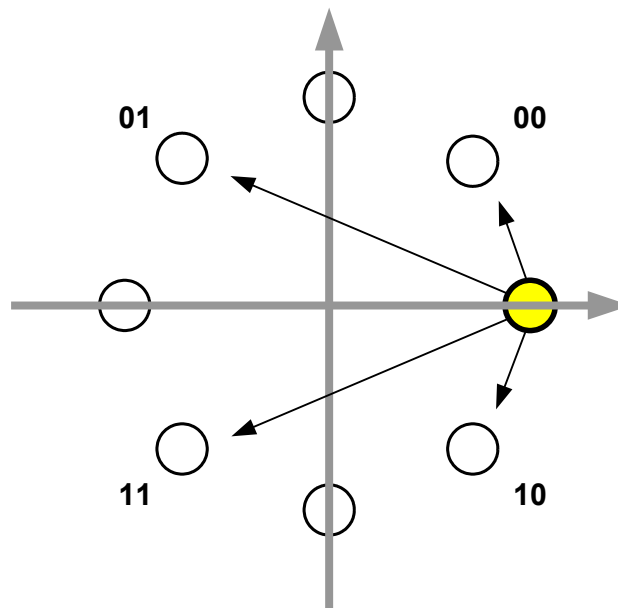
Enhanced Data Rate

Figure 4.3: Basic Rate and Enhanced Data Rate Packet Structure
4.7.1 Enhanced Data Rate $\pi/4$ DQPSK

The 2x data rate for EDR uses a $\pi/4$ -DQPSK. Each symbol represents 2-bits of information. Figure 4.4 shows the constellation. It has two planes, each having four points. Although it seems there are eight possible phase states, the encoding ensures that the trajectory of the modulation between symbols is restricted to the four states in the other plane.

For a given starting point, each phase change between symbols is restricted to $+3\pi/4$, $+\pi/4$, $-\pi/4$ or $-3\pi/4$ radians ($+135^\circ$, $+45^\circ$, -45° or -135°). For example, the arrows shown in Figure 4.4 represent trajectory to the four possible states in the other plane. Table 4.3 shows the phase shift encoding of symbols.

There are two main advantages in using $\pi/4$ DQPSK modulation:

- The scheme avoids the crossing of the origin (a $+\pi$ or $-\pi$ phase shift) and therefore minimises amplitude variations in the envelope of the transmitted signal. This in turn allows the RF power amplifiers of the transmitter to be operated closer to their compression point without introducing spectral distortions. Consequently, the DC to RF efficiency is maximised.
- The differential encoding also allows for the demodulation without the knowledge of an absolute value for the phase of the RF carrier.


Figure 4.4: $\pi/4$ DQPSK Constellation Pattern

Bit Pattern	Phase Shift
00	$\pi/4$
01	$3\pi/4$
11	$-3\pi/4$
10	$-\pi/4$

Table 4.3: 2-Bits Determine Phase Shift Between Consecutive Symbols

4.7.2 Enhanced Data Rate 8DPSK

The 3x data rate modulation uses eight phase differential phase shift keying (8DPSK). Each symbol in the payload portion of the packet represents 3 baseband bits. Although it seems the 8DPSK is similar to $\pi/4$ DQPSK, the differential phase shifts between symbols are now permissible between any of the eight possible phase states. This reduces the separation between adjacent symbols on the constellation to $\pi/4$ (45°) and thereby reduces the noise and interference immunity of the modulation scheme. Nevertheless, because each symbol now represents 3 baseband bits, the actual throughput of the data is 3x when compared with the basic rate packet.

Figure 4.5 shows the 8DPSK constellation and Table 4.4 shows the phase encoding.

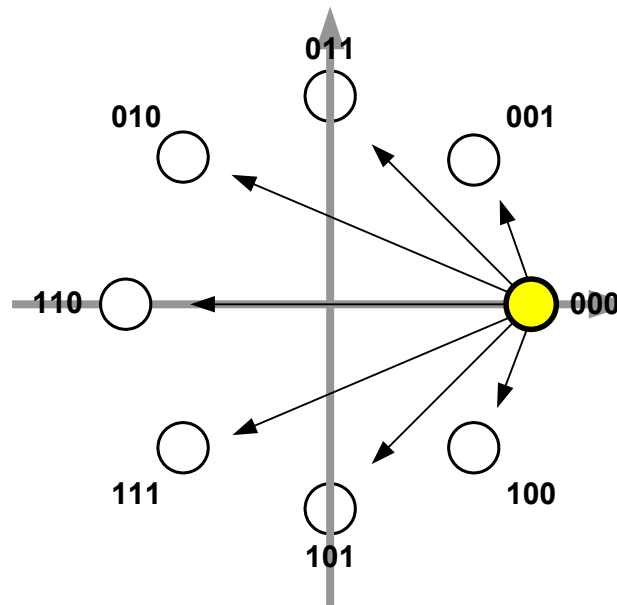


Figure 4.5: 8DPSK Constellation Pattern

Bit Pattern	Phase Shift
000	0
001	$\pi/4$
011	$\pi/2$
010	$3\pi/4$
110	π
111	$-3\pi/4$
101	$-\pi/2$
100	$-\pi/4$

Table 4.4: 3-Bits Determine Phase Shift Between Consecutive Symbols

5 Clock Generation

BlueCore5-Multimedia External requires a Bluetooth reference clock frequency of 12MHz to 52MHz from either an externally connected crystal or from an external TCXO source.

All BlueCore5-Multimedia External internal digital clocks are generated using a phase locked loop, which is locked to the frequency of either the external 12MHz to 52MHz reference clock source or an internally generated watchdog clock frequency of 1kHz.

The Bluetooth operation determines the use of the watchdog clock in low-power modes.

5.1 Clock Architecture

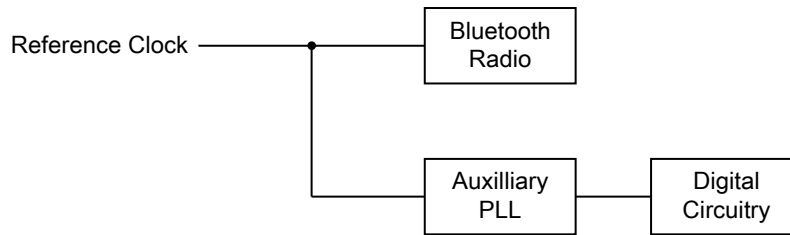


Figure 5.1: Clock Architecture

5.2 Input Frequencies and PS Key Settings

BlueCore5-Multimedia External should be configured to operate with the chosen reference frequency. Do this by setting the PS Key PSKEY_ANA_FREQ (0x01FE) for all frequencies with an integer multiple of 250kHz. The input frequency default setting in BlueCore5-Multimedia External is 26MHz depending on the software build. Full details are in the software release note for the specific build from www.csrsupport.com.

The following CDMA/3G phone TCXO frequencies are also catered for: 14.40, 15.36, 16.2, 16.8, 19.2, 19.44, 19.68, 19.8 and 38.4MHz. The value of the PS Key is a multiple of 1kHz, so 38.4MHz is selected by using a PS Key value of 38400.

Reference Crystal Frequency (MHz)	PSKEY_ANA_FREQ (0x1fe) (Units of 1kHz)
14.40	14400
15.36	15360
16.20	16200
16.80	16800
19.20	19200
19.44	19440
19.68	19680
19.80	19800
38.40	38400
n x 0.25	n x 250
26.00 (default)	26000

Table 5.1: PS Key Values for CDMA/3G Phone TCXO

5.3 External Reference Clock

5.3.1 Input (XTAL_IN)

The external reference clock is applied to the BlueCore5-Multimedia External XTAL_IN input.

BlueCore5-Multimedia External is configured to accept the external reference clock at XTAL_IN by connecting XTAL_OUT to ground. The external clock can be either a digital level square wave or sinusoidal, and this may be directly coupled to XTAL_IN without the need for additional components. A digital level reference clock gives superior noise immunity, as the high slew rate clock edges have lower voltage to phase conversion. If peaks of the reference clock are either below VSS_ANA or above VDD_ANA, it must be driven through a DC blocking capacitor (approximately 33pF) connected to XTAL_IN.

The external reference clock signal should meet the specifications outlined in Table 5.2.

		Min	Typ	Max
Frequency ^(a)		12MHz	26MHz	52MHz
Duty cycle		20:80	50:50	80:20
Edge Jitter (At Zero Crossing)		-	-	15ps rms
Signal Level	AC coupled sinusoid	400mV pk-pk	-	VDD_ANA ^(b)
	DC coupled digital	V _{IL}	-	VSS_ANA ^(c)
		V _{IH}	-	VDD_ANA ^{(b) (c)}

Table 5.2: External Clock Specifications

^(a) The frequency should be an integer multiple of 250kHz except for the CDMA/3G frequencies

^(b) VDD_ANA is 1.5V nominal

^(c) If driven via a DC blocking capacitor max amplitude is reduced to 750mV pk-pk for non 50:50 duty cycle

5.3.2 XTAL_IN Impedance in External Mode

The impedance of XTAL_IN does not change significantly between operating modes, typically 10fF. When transitioning from Deep Sleep to an active state a spike of up to 1pC may be measured. For this reason CSR recommends that a buffered clock input is used.

5.3.3 Clock Start-up Delay

BlueCore5-Multimedia External hardware incorporates an automatic 5ms delay after the assertion of the system clock request signal before running firmware. This is suitable for most applications using an external clock source. However, there may be scenarios where the clock cannot be guaranteed to either exist or be stable after this period. Under these conditions, BlueCore5-Multimedia External firmware provides a software function that extends the system clock request signal by a period stored in PSKEY_CLOCK_STARTUP_DELAY. This value is set in milliseconds from 1-31ms. Zero is the default entry for 5ms delay.

This PS Key allows the designer to optimise a system where clock latencies may be longer than 5ms while still keeping the current consumption of BlueCore5-Multimedia External as low as possible.

BlueCore5-Multimedia External consumes about 2mA of current for the duration of PSKEY_CLOCK_STARTUP_DELAY before activating the firmware.

5.3.4 Clock Timing Accuracy

As Figure 5.2 shows, the 250ppm timing accuracy on the external clock is required 2ms after the firmware begins to run. This is to guarantee that the firmware can maintain timing accuracy in accordance with the Bluetooth v2.1 + EDR specification. Radio activity may occur after 6ms after the firmware starts. Therefore, at this point the timing accuracy of the external clock source must be within ± 20 ppm.

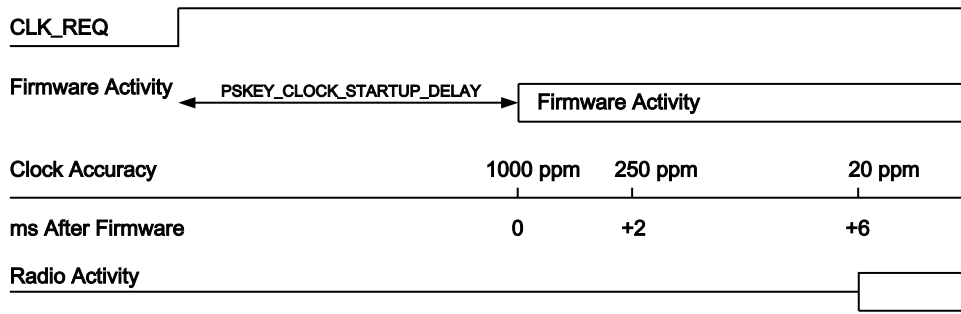


Figure 5.2: TCXO Clock Accuracy

5.4 Crystal Oscillator (XTAL_IN, XTAL_OUT)

BlueCore5-Multimedia External contains a crystal driver circuit. This operates with an external crystal and capacitors to form a Pierce oscillator. The external crystal is connected to pins XTAL_IN, XTAL_OUT.

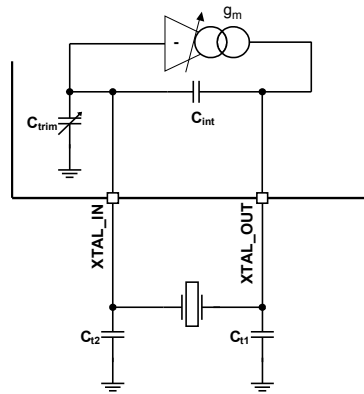


Figure 5.3: Crystal Driver Circuit

Figure 5.4 shows an electrical equivalent circuit for a crystal. The crystal appears inductive near its resonant frequency. It forms a resonant circuit with its load capacitors.

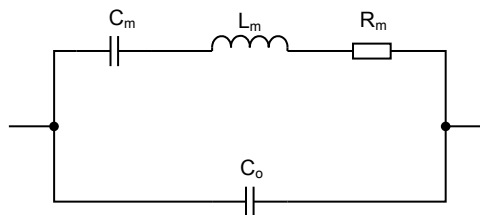


Figure 5.4: Crystal Equivalent Circuit

The resonant frequency may be trimmed with the crystal load capacitance. BlueCore5-Multimedia External contains variable internal capacitors to provide a fine trim.

Parameter	Min	Typ	Max	Unit
Frequency	16	26	26	MHz
Initial Tolerance	-	±25	-	ppm
Pullability	-	±20	-	ppm/pF
Transconductance	2.0	-	-	mS

Table 5.3: Crystal Specification

The BlueCore5-Multimedia External driver circuit is a transconductance amplifier. A voltage at XTAL_IN generates a current at XTAL_OUT. The value of transconductance is variable and may be set for optimum performance.

5.4.1 Load Capacitance

For resonance at the correct frequency the crystal should be loaded with its specified load capacitance, which is defined for the crystal. This is the total capacitance across the crystal viewed from its terminals. BlueCore5-Multimedia External provides some of this load with the capacitors C_{trim} and C_{int} . The remainder should be from the external capacitors labelled C_{t1} and C_{t2} . C_{t1} should be three times the value of C_{t2} for best noise performance. This maximises the signal swing, hence slew rate at XTAL_IN (to which all on-chip clocks are referred).

Crystal load capacitance, C_l is calculated with Equation 5.1:

$$C_l = C_{int} + \frac{(C_{t2} + C_{trim})C_{t1}}{C_{t2} + C_{trim} + C_{t1}}$$

Equation 5.1: Load Capacitance

Note:

$C_{trim} = 3.4\text{pF}$ nominal (mid-range setting)

$C_{int} = 1.5\text{pF}$

C_{int} does not include the crystal internal self capacitance; it is the driver self capacitance.

5.4.2 Frequency Trim

BlueCore5-Multimedia External enables frequency adjustments to be made. This feature is typically used to remove initial tolerance frequency errors associated with the crystal. Frequency trim is achieved by adjusting the crystal load capacitance with an on-chip trim capacitor, C_{trim} . The value of C_{trim} is set by a 6-bit word in the PS Key PSKEY_ANA_FTRIM ($0 \times 1 \text{f} 6$). Its value is calculated as follows:

$$C_{trim} = 125\text{fF} \times \text{PSKEY_ANA_FTRIM}$$

Equation 5.2: Trim Capacitance

The C_{trim} capacitor is connected between XTAL_IN and ground. When viewed from the crystal terminals, the combination of the tank capacitors and the trim capacitor presents a load across the terminals of the crystal which varies in steps of typically 125fF for each least significant bit increment of PSKEY_ANA_FTRIM.

Equation 5.3 describes the frequency trim.

$$\frac{\Delta(F_x)}{F_x} = \text{pullability} \times 0.110 \times \left(\frac{C_{t1}}{C_{t1} + C_{t2} + C_{trim}} \right) \text{ (ppm / LSB)}$$

Equation 5.3: Frequency Trim

Note:

F_x = crystal frequency

Pullability is a crystal parameter with units of ppm/pF.

Total trim range is 0 to 63.

If not specified, the pullability of a crystal may be calculated from its motional capacitance with Equation 5.4.

$$\frac{\partial(F_x)}{\partial(C_l)} = F_x \cdot \frac{C_m}{2(C_l + C_0)^2}$$

Equation 5.4: Pullability

Note:

C_0 = Crystal self capacitance (shunt capacitance)

C_m = Crystal motional capacitance (series branch capacitance in crystal model). See Figure 5.4.

It is a Bluetooth requirement that the frequency is always within $\pm 20\text{ppm}$. The trim range should be sufficient to pull the crystal within $\pm 5\text{ppm}$ of the exact frequency. This leaves a margin of $\pm 15\text{ppm}$ for frequency drift with ageing and temperature. A crystal with an ageing and temperature drift specification of better than $\pm 15\text{ppm}$ is required.

5.4.3 Transconductance Driver Model

The crystal and its load capacitors should be viewed as a transimpedance element, whereby a current applied to one terminal generates a voltage at the other. The transconductance amplifier in BlueCore5-Multimedia External uses the voltage at its input, XTAL_IN, to generate a current at its output, XTAL_OUT. Therefore, the circuit will oscillate if the transconductance, transimpedance product is greater than unity. For sufficient oscillation amplitude, the product should be greater than three. The transconductance required for oscillation is defined by the relationship shown in Equation 5.5.

$$g_m > 3 \frac{(2 \pi F_x)^2 R_m \left((C_0 + C_{int}) (C_{t1} + C_{t2} + C_{trim}) + C_{t1} (C_{t2} + C_{trim}) \right)}{C_{t1} (C_{t2} + C_{trim})}$$

Equation 5.5: Transconductance Required for Oscillation

BlueCore5-Multimedia External guarantees a transconductance value of at least 2mA/V at maximum drive level.

Note:

More drive strength is required for higher frequency crystals, higher loss crystals (larger R_m) or higher capacitance loading.

Optimum drive level is attained when the level at XTAL_IN is approximately 1V pk-pk. The drive level is determined by the crystal driver transconductance.

5.4.4 Negative Resistance Model

An alternative representation of the crystal and its load capacitors is a frequency dependent resistive element. The driver amplifier may be considered as a circuit that provides negative resistance. For oscillation, the value of the negative resistance must be greater than that of the crystal circuit equivalent resistance. Although the BlueCore5-Multimedia External crystal driver circuit is based on a transimpedance amplifier, an equivalent negative resistance can be calculated for it using Equation 5.6.

$$R_{neg} > \frac{C_{t1} (C_{t2} + C_{trim})}{g_m (2 \pi F_x)^2 (C_0 + C_{int}) \left((C_{t1} + C_{t2} + C_{trim}) + C_{t1} (C_{t2} + C_{trim}) \right)^2}$$

Equation 5.6: Equivalent Negative Resistance

This formula shows the negative resistance of the BlueCore5-Multimedia External driver as a function of its drive strength.

The value of the driver negative resistance may be easily measured by placing an additional resistance in series with the crystal. The maximum value of this resistor (oscillation occurs) is the equivalent negative resistance of the oscillator.

5.4.5 Crystal PS Key Settings

The BlueCore5-Multimedia External firmware automatically controls the drive level on the crystal circuit to achieve optimum input swing. The PS Key PSKEY_XTAL_TARGET_AMPLITUDE (0x24b) is used by the firmware to servo the required amplitude of crystal oscillation. Refer to the software build release note for a detailed description.

BlueCore5-Multimedia External should be configured to operate with the chosen reference frequency as shown in Table 5.1.

6 Bluetooth Stack Microcontroller

The *microcontroller unit* (MCU), interrupt controller and event timer run the Bluetooth software stack and control the Bluetooth radio and host interfaces. A 16-bit *reduced instruction set computer* (RISC) microcontroller is used for low power consumption and efficient use of memory.

6.1 Programmable I/O (PIO) Parallel Ports

18 lines of programmable bi-directional *input/outputs* (I/O) are provided. PIO[15:4] are powered from VDD_PADS and PIO[3:0] are powered from VDD_PIO. AIO[0:1] are powered from VDD_ANA.

Any of the PIO lines can be configured as interrupt request lines or as wake-up lines from sleep modes. PIO[6] or PIO[2] can be configured as a request line for an external clock source. Using PSKEY_CLOCK_REQUEST_ENABLE (0x246), this terminal can be configured to be low when BlueCore5-Multimedia External is in Deep Sleep and high when a clock is required.

CSR cannot guarantee that the PIO assignments remain as described. Refer to the relevant software release note for the implementation of these PIO lines, as they are firmware build-specific.

BlueCore5-Multimedia External has two general-purpose analogue interface pins, AIO[0:1], used to access internal circuitry and control signals. Auxiliary functions available on the analogue interface include a 10-bit ADC and a 8-bit DAC. Signals selectable on this interface include the band gap reference voltage and a variety of clock signals: 64, 48, 32, 24, 16, 12, 8, 6 and 2MHz (outputted from AIO[0] only) and the XTAL and XTAL/2 clock frequency (outputted from AIO[0] and AIO[1]). When used with analogue signals the voltage range is constrained by the analogue supply voltage. When configured to drive out digital level signals (clocks) generated from within the analogue part of the device, the output voltage level is determined by VDD_ANA.

6.2 TCXO Enable OR Function

An OR function exists for clock enable signals from a host controller and BlueCore5-Multimedia External where either device can turn on the clock without having to wake up the other device, see Figure 6.1. PIO[3] can be used as the host clock enable input and PIO[2] can be used as the OR output with the TCXO enable signal from BlueCore5-Multimedia External.

Note:

To turn on the clock, the clock enable signal on PIO[3] must be high.

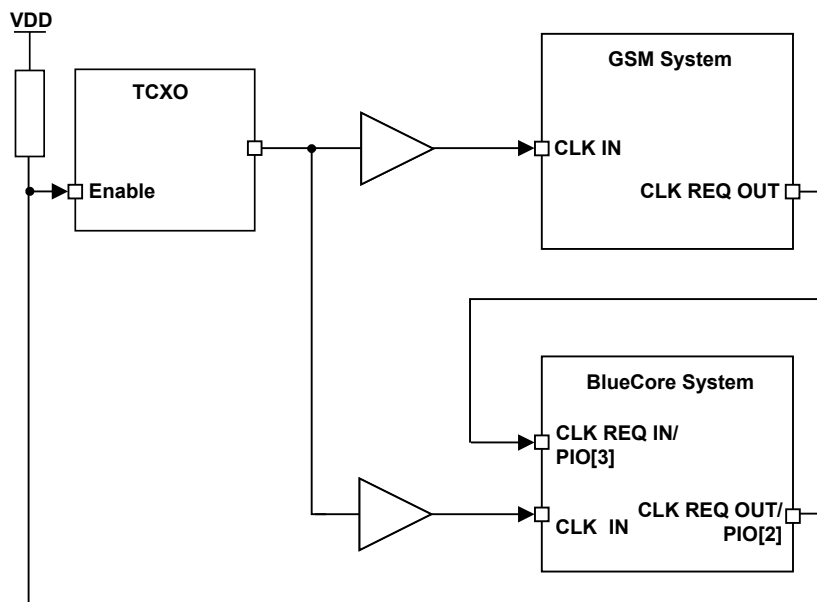


Figure 6.1: Example TCXO Enable OR Function

On reset and up to the time the PIO has been configured, PIO[2] is tri-state. Therefore, the developer must ensure that the circuitry connected to this pin is pulled via a 470kΩ resistor to the appropriate power rail. This ensures that the TCXO is oscillating at start up.

6.3 WLAN Co-existence Interface

Dedicated hardware is provided to implement a variety of co-existence schemes. Channel skipping AFH, priority signalling, channel signalling and host passing of channel instructions are all supported. The features are configured in firmware.

For more information see *Bluetooth and IEEE 802.11 b/g Co-existence Solutions Overview*.

7 Kalimba DSP

The Kalimba DSP is an open platform Kalimba DSP allowing signal processing functions to be performed on over air data or CODEC data in order to enhance audio applications. The Kalimba DSP interfaces to other functional blocks within BlueCore5-Multimedia External as shown in Figure 7.1.

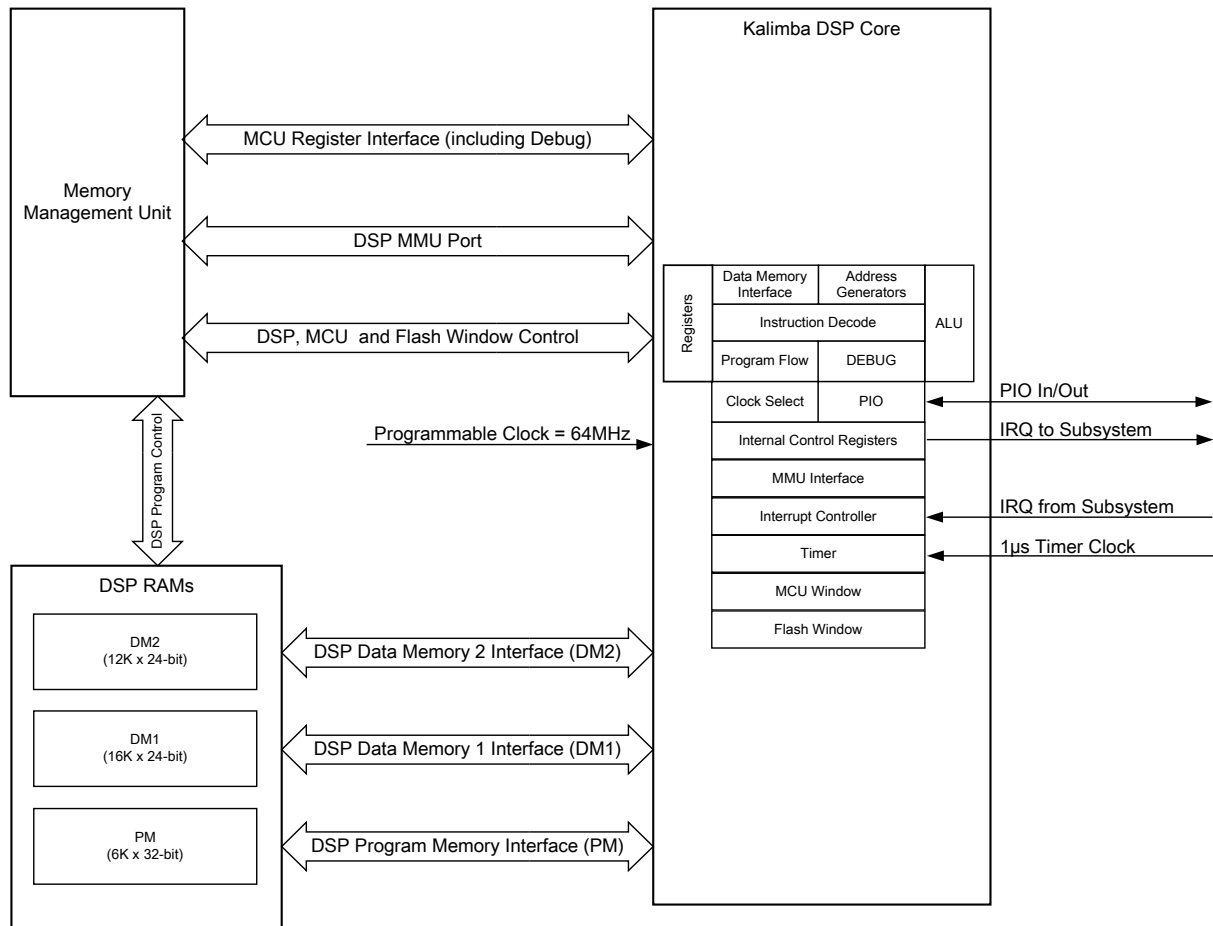


Figure 7.1: Kalimba DSP Interface to Internal Functions

The key features of the DSP include:

- 64MIPS performance, 24-bit fixed point DSP Core
- Single cycle MAC of 24 x 24-bit multiply and 56-bit accumulate
- 32-bit instruction word
- Separate program memory and dual data memory, allowing an ALU operation and up to two memory accesses in a single cycle
- Zero overhead looping
- Zero overhead circular buffer indexing
- Single cycle barrel shifter with up to 56-bit input and 24-bit output
- Multiple cycle divide (performed in the background)
- Bit reversed addressing
- Orthogonal instruction set
- Low overhead interrupt

8 Memory Interface and Management

8.1 Memory Management Unit

The *Memory Management Unit* (MMU) provides a number of dynamically allocated ring buffers that hold the data that is in transit between the host, the air or the Kalimba DSP. The dynamic allocation of memory ensures efficient use of the available *Random Access Memory* (RAM) and is performed by a hardware MMU to minimise the overheads on the processor during data/voice transfers.

8.2 System RAM

48-Kbyte of on-chip RAM supports the RISC MCU and is shared between the ring buffers used to hold voice/data for each active connection and the general-purpose memory required by the Bluetooth stack.

8.3 Kalimba DSP RAM

Additional on-chip RAM is provided to support the Kalimba DSP:

- 16K x 24-bit for data memory 1 (DM1)
- 12K x 24-bit for data memory 2 (DM2)
- 6K x 32-bit for program memory (PM)

Note:

The DSP can also execute directly from Flash, using a 64-instruction on-chip cache.

8.4 External Memory Driver

The External Memory Driver interface can be used to connect to the external Flash memory and also to the optional external RAM for memory intensive applications.

8.5 Flash Memory (32-Mbit)

Up to 32-Mbit of external Flash is available (though typically 8-Mbit is used) on the BlueCore5-Multimedia External. The external Flash memory is provided for system firmware and the Kalimba DSP co-processor code implementation.

FLASH_RP# is the flash reset signal. This behaves in the same way as the hard reset but is delayed by a couple of clock cycles. It only moves during boot.

8.6 Off-chip Program Memory

The external memory port provides a facility to interface up to 32-Mbit of 16-bit external memory. This off-chip storage stores BlueCore5-Multimedia External settings and program code. Flash is the storage mechanism typically used by BlueCore5-Multimedia External modules. However external masked ROM may also be used if the host takes over responsibility for storing configuration data.

The external memory port is:

- 16 bi-directional data lines, D[15:0]
- 21 output address lines, A[20:0]
- 3 active low output control signals, WE#, CE# and OE#
 - WE# is asserted when data is written to external memory
 - OE# is asserted when data is read from external memory
 - The chip select line CS# is asserted when any data transfer (read or write) is required

All of the external memory port connections are implemented using CMOS technology and use standard 0V to VDD_MEM signal levels.

Note:

In addition to these hardware requirements, take care to ensure that the sector organisation of the extended memory has the correct format. A sector is defined as an individually erasable area of external Flash.

Ensure that external memory devices meet certain minimum specifications, see Table 8.1.

Parameter	Value
Data width	16-bit
Minimum capacity	4Mbits (256kWord)
Maximum access time	90ns @125°C 50pF load
	110ns @85°C 10pF load

Table 8.1: Flash Device Hardware Requirements

8.6.1 Minimum Flash Specification

The flash device used with BlueCore5-Multimedia External must meet the following criteria:

- Either standard or extended form of the JEDEC (AMD/Fujitsu/SST) or Intel command set
- Access time must be $\leq 90\text{ns}$ @125°C 50pF load or $\leq 110\text{ns}$ @85°C 10pF load (typically $\leq 70\text{ns}$)
- Write strobe of 100ns
- Accessible in word mode, i.e., via a 16-bit data bus
- Support changing different bits within each word from 1 to 0 in at least two separate programming operations
- Programming and erase times must have fixed upper limits
- Must be bottom boot or uniform sector
- Must have independently erasable sectors with at least the following boundaries (see Memory Map for more information)

Word Address	Size (kWords)
0x00000 - 0x01FFF	8
0x02000 - 0x02FFF	4
0x03000 - 0x03FFF	4
0x04000 - 0x07FFF	16
0x08000 - 0x0FFFF	32
0x10000 - 0x17FFF	32
0x18000 -	Don't care

Table 8.2: Flash Sector Boundaries

Important Note:

As well as satisfying the criteria in Section 8.6.1 a device must also support the Common Flash Interface described in Section 8.6.3 or be supported in the BlueCore5-Multimedia External firmware and host-side tools.

8.6.2 Virtual Machine (VM) Requirements

Although the minimum requirements for external Flash are shown in Table 8.1 and Section 8.6.1, these figures are based on running Bluetooth HCI stack. BlueCore5-Multimedia External can run VM applications and as part of the VM configuration the internal processing clock speed and number of memory wait states can be set. To maximise VM application performance it may be necessary to:

- Use 70ns Flash devices
- Set 2 wait states
- Set the clock to 32MHz

8.6.3 Common Flash Interface

The firmware can adapt automatically to work with some Flash devices, when the Flash device satisfies the minimum Flash specification described in Section 8.6.1 and it meets the following criteria:

- The device must support the Common Flash Interface, as defined by JEDEC standard JESD68.
- The device must return one of the following codes for either the Primary or Alternative Algorithm Command Set (offset 0x13b or 0x17 of the Query Structure Output):

Code	Description
0x0001	Intel/Sharp Extended Command Set
0x0002	AMD/Fujitsu Standard Command Set
0x0003	Intel Standard Command Set
0x0701	AMD/Fujitsu Extended Command Set

Table 8.3: Common Flash Interface Algorithm Command Set Codes

- The device must return one of the following patterns of Erase Block Region Information (beginning at offset 0x2d of the Query Structure Output).

Erase Block Region	Number of Erase Blocks	Block Size
1	128, 256, 512 or 1024	4kbytes

Table 8.4: Erase Block Region Information for Uniform 2kword Sectors

Erase Block Region	Number of Erase Blocks	Block Size
1	256, 512, 1024 or 2048	2kbytes

Table 8.5: Erase Block Region Information for Uniform 1kword Sectors

Erase Block Region	Number of Erase Blocks	Block Size
1	8	8kbytes
2	7, 15, 31 or 63	64kbytes

Table 8.6: Erase Block Region Information for 8 x 4kword, n x 32kword Sectors

Erase Block Region	Number of Erase Blocks	Block Size
1	1	16kbytes
2	2	8kbytes
3	1	32kbytes
4	7, 15, 31 or 63	64kbytes

Table 8.7: Erase Block Region Information for 1 x 8kword, 2x 4kword, 1 x 16kword, n x 32kword Sectors

Important Note:

If any of these criteria is not met, then the device will not work unless it supported by the BlueCore5-Multimedia External firmware.

8.6.4 Memory Timing

Table 8.8 and Figure 8.1 show memory write cycle timing for BlueCore5-Multimedia External.

Symbol	Parameter	Minimum ^(a)	Typical	Maximum ^(a)	Unit
t_{wc}	Write cycle time	300	-	-	ns
$t_{dat:su}$	Data set-up time	150	-	-	ns
$t_{dat:hd}$	Data hold time	150	-	-	ns
$t_{addr:su}$	Address set-up time	150	-	-	ns
$t_{we:low}$	WE# low	100	-	-	ns

Table 8.8: Memory Write Cycle

^(a) Valid for temperatures between -30°C and +85°C

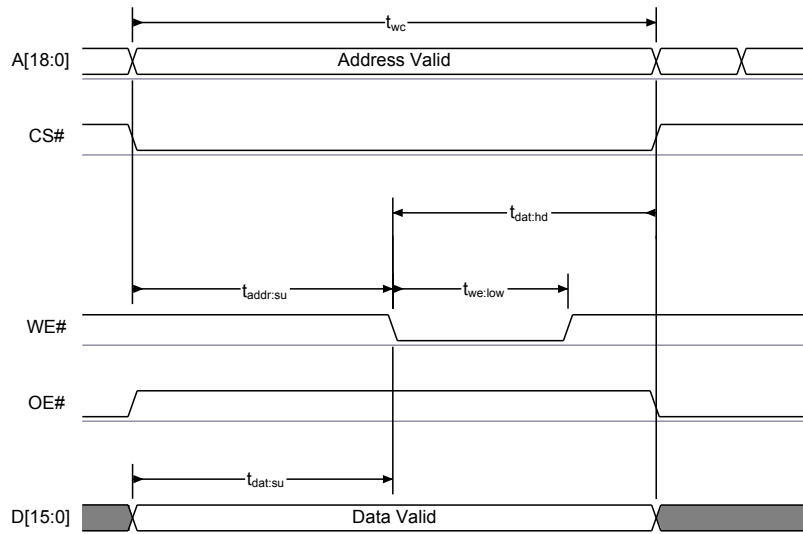

Figure 8.1: Memory Write Cycle

Table 8.9 and Figure 8.2 show memory read cycle timing for BlueCore5-Multimedia External.

Symbol	Parameter	Minimum ^(a)	Typical	Maximum ^(a)	Unit
t_{rc}	Read cycle time	114	125	-	ns
t_{aa}	Address access time	-	-	110	ns
t_{re}	Read enable access time	-	-	110	ns
$t_{dat:hd}$	Data hold time from address line	0	-	-	ns

Table 8.9: Memory Read Cycle

^(a) Valid for temperatures between -30°C and +85°C

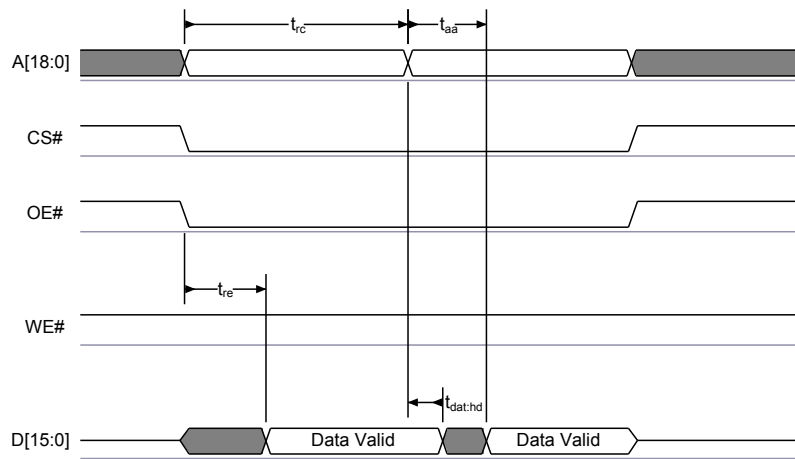


Figure 8.2: Memory Read Cycle

9 Serial Interfaces

9.1 UART Interface

This is a standard UART interface for communicating with other serial devices.

BlueCore5-Multimedia External UART interface provides a simple mechanism for communicating with other serial devices using the RS232 protocol.

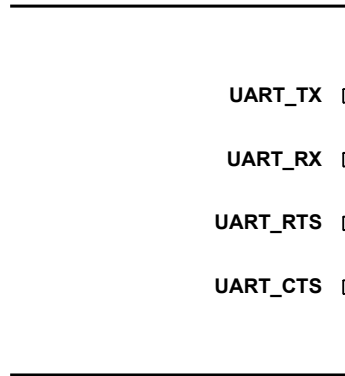


Figure 9.1: Universal Asynchronous Receiver

Four signals implement the UART function, as shown in Figure 9.1. When BlueCore5-Multimedia External is connected to another digital device, UART_RX and UART_TX transfer data between the two devices. The remaining two signals, UART_CTS and UART_RTS, can be used to implement RS232 hardware flow control where both are active low indicators.

UART configuration parameters, such as baud rate and packet format, are set using BlueCore5-Multimedia External firmware.

Note:

To communicate with the UART at its maximum data rate using a standard PC, an accelerated serial port adapter card is required for the PC.

Parameter		Possible Values
Baud rate	Minimum	1200 baud ($\leq 2\%$ Error)
		9600 baud ($\leq 1\%$ Error)
	Maximum	4Mbaud ($\leq 1\%$ Error)
Flow control		RTS/CTS or None
Parity		None, Odd or Even
Number of stop bits		1 or 2
Bits per byte		8

Table 9.1: Possible UART Settings

The UART interface can reset BlueCore5-Multimedia External on reception of a break signal. A break is identified by a continuous logic low (0V) on the UART_RX terminal, as shown in Figure 9.2. If t_{BRK} is longer than the value, defined by the PS Key PSKEY_HOSTIO_UART_RESET_TIMEOUT, (0x1a4), a reset occurs. This feature allows a host to initialise the system to a known state. Also, BlueCore5-Multimedia External can emit a break character that may be used to wake the host.

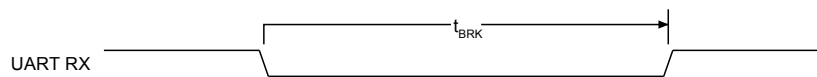


Figure 9.2: Break Signal

Note:

The DFU boot loader must be loaded into the Flash device before the UART or USB interfaces can be used. This initial flash programming can be done via the SPI.

Table 9.2 shows a list of commonly used baud rates and their associated values for the PS Key PSKEY_UART_BAUDRATE (0x1be). There is no requirement to use these standard values. Any baud rate within the supported range can be set in the PS Key according to the formula in Equation 9.1.

$$\text{Baud Rate} = \frac{\text{PSKEY_UART_BAUDRATE}}{0.004096}$$

Equation 9.1: Baud Rate

Baud Rate	Persistent Store Value		Error
	Hex	Dec	
1200	0x0005	5	1.73%
2400	0x000a	10	1.73%
4800	0x0014	20	1.73%
9600	0x0027	39	-0.82%
19200	0x004f	79	0.45%
38400	0x009d	157	-0.18%
57600	0x00ec	236	0.03%
76800	0x013b	315	0.14%
115200	0x01d8	472	0.03%
230400	0x03b0	944	0.03%
460800	0x075f	1887	-0.02%
921600	0x0ebf	3775	0.00%
1382400	0x161e	5662	-0.01%
1843200	0x1d7e	7550	0.00%
2764800	0x2c3d	11325	0.00%

Table 9.2: Standard Baud Rates

9.1.1 UART Configuration While Reset is Active

The UART interface for BlueCore5-Multimedia External is tri-state while the chip is being held in reset. This allows the user to daisy chain devices onto the physical UART bus. The constraint on this method is that any devices connected to this bus must tri-state when BlueCore5-Multimedia External reset is de-asserted and the firmware begins to run.

9.1.2 UART Bypass Mode

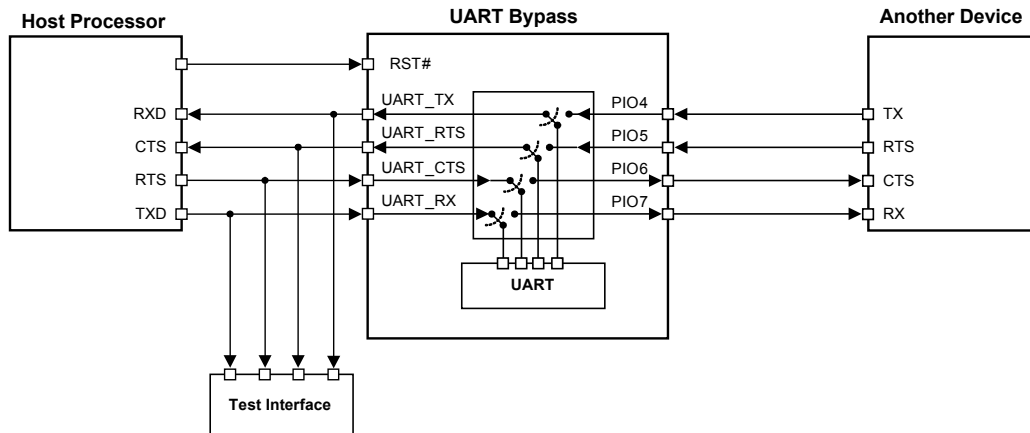


Figure 9.3: UART Bypass Architecture

Alternatively, for devices that do not tri-state the UART bus, the UART bypass mode on BlueCore5-Multimedia External can be used. The default state of BlueCore5-Multimedia External after reset is de-asserted; this is for the host UART bus to be connected to the BlueCore5-Multimedia External UART, thereby allowing communication to BlueCore5-Multimedia External via the UART. All UART bypass mode connections are implemented using CMOS technology and have signalling levels of 0V and VDD_PADS.

To apply the UART bypass mode, a BCCMD command is issued to BlueCore5-Multimedia External. Upon this issue, it switches the bypass to PIO[7:4] as Figure 9.3 shows. When the bypass mode has been invoked, BlueCore5-Multimedia External enters the Deep Sleep state indefinitely.

To re-establish communication with BlueCore5-Multimedia External, the chip must be reset so that the default configuration takes effect.

It is important for the host to ensure a clean Bluetooth disconnection of any active links before the bypass mode is invoked. Therefore, it is not possible to have active Bluetooth links while operating the bypass mode.

9.1.3 Current Consumption in UART Bypass Mode

The current consumption for a device in UART bypass mode is equal to the values quoted for a device in standby mode.

9.2 USB Interface

This is a full speed (12Mbits/s) Universal Serial Bus (USB) interface for communicating with other compatible digital devices. BlueCore5-Multimedia External acts as a USB peripheral, responding to requests from a master host controller such as a PC.

The USB interface is capable of driving a USB cable directly. No external USB transceiver is required. The device operates as a USB peripheral, responding to requests from a master host controller such as a PC. Both the OHCI and the UHCI standards are supported.

Note:

The set of USB endpoints implemented can behave as specified in the USB section of the Bluetooth v2.1 + EDR specification or alternatively can appear as a set of endpoints appropriate to USB audio devices such as speakers.

As USB is a master/slave oriented system (in common with other USB peripherals), BlueCore5-Multimedia External only supports USB Slave operation.

9.2.1 USB Data Connections

The USB data lines emerge as pins USB_DP and USB_DN. These terminals are connected to the internal USB I/O buffers of the BlueCore5-Multimedia External, therefore, have a low output impedance. To match the connection to the characteristic impedance of the USB cable, resistors must be placed in series with USB_DP/USB_DN and the cable.

9.2.2 USB Pull-up Resistor

BlueCore5-Multimedia External features an internal USB pull-up resistor. This pulls the USB_DP pin weakly high when BlueCore5-Multimedia External is ready to enumerate. It signals to the PC that it is a full-speed (12-Mbits/s) USB device.

The USB internal pull-up is implemented as a current source, and is compliant with section 7.1.5 of the USB specification v1.2. The internal pull-up pulls USB_DP high to at least 2.8V when loaded with a $15k\Omega \pm 5\%$ pull-down resistor (in the hub/host) when $VDD_USB=3.1V$. This presents a Thevenin resistance to the host of at least 900Ω . Alternatively, an external $1.5k\Omega$ pull-up resistor can be placed between a PIO line and D+ on the USB cable, see Section 9.2.4. The firmware must be alerted to which mode is used by setting PS Key PSKEY_USB_PIO_PULLUP appropriately. The default setting uses the internal pull-up resistor.

9.2.3 USB Power Supply

The USB specification dictates that the minimum output high voltage for USB data lines is 2.8V. To safely meet the USB specification, the voltage on the VDD_USB supply terminals must be an absolute minimum of 3.1V. CSR recommends 3.3V for optimal USB signal quality.

9.2.4 Self-powered Mode

In self-powered mode, the circuit is powered from its own power supply and not from the VBUS (5V) line of the USB cable. It draws only a small leakage current (below 0.5mA) from VBUS on the USB cable. This is the easier mode for which to design, as the design is not limited by the power that can be drawn from the USB hub or root port. However, it requires that VBUS be connected to BlueCore5-Multimedia External via a resistor network (R_{vb1} and R_{vb2}), so BlueCore5-Multimedia External can detect when VBUS is powered up. BlueCore5-Multimedia External will not pull USB_DP high when VBUS is off.

Self-powered USB designs (powered from a battery or PSU) must ensure that a PIO line is allocated for USB pull-up purposes. A $1.5k\Omega \pm 5\%$ pull-up resistor between USB_DP and the selected PIO line should be fitted to the design. Failure to fit this resistor may result in the design failing to be USB compliant in self-powered mode. The internal pull-up in BlueCore5-Multimedia External is only suitable for bus-powered USB devices, e.g. dongles.

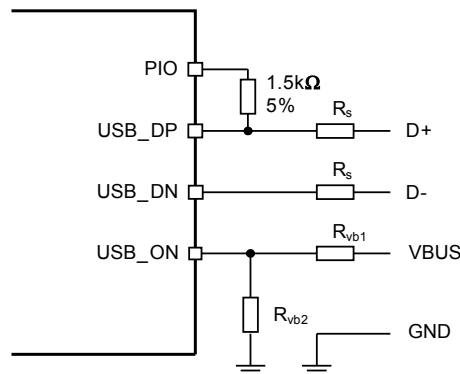


Figure 9.4: USB Connections for Self-Powered Mode

The terminal marked USB_ON can be any free PIO pin. The PIO pin selected must be registered by setting PSKEY_USB_PIO_VBUS to the corresponding pin number.

Note:

For the self-powered mode described in this section to function correctly, the PIO terminals selected in Figure 9.4 must be configured for 3.3V operation on the BlueCore5-Multimedia External.

USB_ON is shared with BlueCore5-Multimedia External PIO terminals.

Identifier	Value	Function
R_s	27 Ω nominal	Impedance matching to USB cable
R_{vb1}	22k Ω \pm 5%	VBUS ON sense divider
R_{vb2}	47k Ω \pm 5%	VBUS ON sense divider

Table 9.3: USB Interface Component Values

9.2.5 Bus-powered Mode

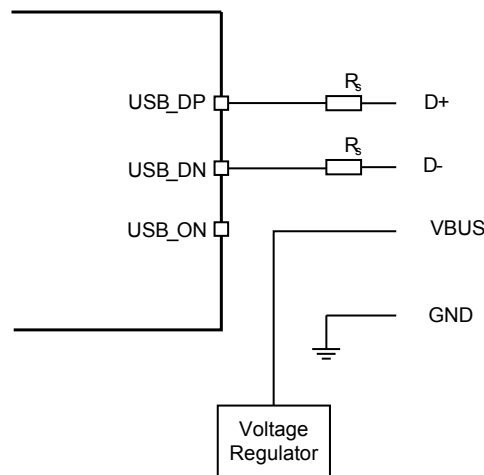
In bus-powered mode, the application circuit draws its current from the 5V VBUS supply on the USB cable. BlueCore5-Multimedia External negotiates with the PC during the USB enumeration stage about how much current it is allowed to consume.

For Class 2 Bluetooth applications, CSR recommends that the regulator used to derive 3.3V from VBUS is rated at 100mA average current and should be able to handle peaks of 120mA without foldback or limiting. In bus-powered mode, BlueCore5-Multimedia External requests 100mA during enumeration.

For Class 1 Bluetooth applications, the USB power descriptor should be altered to reflect the amount of power required. This is accomplished by setting the PS Key PSKEY_USB_MAX_POWER (0x2c6). This is higher than for a Class 2 application due to the extra current drawn by the Transmit RF PA.

When selecting a regulator, be aware that VBUS may go as low as 4.4V. The inrush current (when charging reservoir and supply decoupling capacitors) is limited by the USB specification. See USB Specification v1.1, section 7.2.4.1. Some applications may require soft start circuitry to limit inrush current if more than 10 μ F is present between VBUS and GND.

The 5V VBUS line emerging from a PC is often electrically noisy. As well as regulation down to 3.3V and 1.8V, applications should include careful filtering of the 5V line to attenuate noise that is above the voltage regulator bandwidth. Excessive noise on the 1.8V supply to the analogue supply pins of BlueCore5-Multimedia External results in reduced receive sensitivity and a distorted RF transmit signal.


Figure 9.5: USB Connections for Bus-Powered Mode

9.2.6 Suspend Current

All USB devices must permit the USB controller to place them in a USB suspend mode. While in USB Suspend, bus-powered devices must not draw more than 0.5mA from USB VBUS (self-powered devices may draw more than 0.5mA from their own supply). This current draw requirement prevents operation of the radio by bus-powered devices during USB Suspend.

The voltage regulator circuit itself should draw only a small quiescent current (typically less than 100 μ A) to ensure adherence to the suspend current requirement of the USB specification. This is not normally a problem with modern regulators. Ensure that external LEDs and/or amplifiers can be turned off by BlueCore5-Multimedia External. The entire circuit must be able to enter the suspend mode. Refer to separate CSR documentation for more details on USB Suspend.

9.2.7 Detach and Wake_Up Signalling

BlueCore5-Multimedia External can provide out-of-band signalling to a host controller by using the control lines called USB_DETACH and USB_WAKE_UP. These are outside the USB specification (no wires exist for them inside the USB cable), but can be useful when embedding BlueCore5-Multimedia External into a circuit where no external USB is visible to the user. Both control lines are shared with PIO pins and can be assigned to any PIO pin by setting the PS Keys PSKEY_USB_PIO_DETACH and PSKEY_USB_PIO_WAKEUP to the selected PIO number.

USB_DETACH is an input which, when asserted high, causes BlueCore5-Multimedia External to put USB_DN and USB_DP in a high impedance state and turns off the pull-up resistor on DP. This detaches the device from the bus and is logically equivalent to unplugging the device. When USB_DETACH is taken low, BlueCore5-Multimedia External will connect back to USB and await enumeration by the USB host.

USB_WAKE_UP is an active high output (used only when USB_DETACH is active) to wake up the host and allow USB communication to recommence. It replaces the function of the software USB WAKE_UP message (which runs over the USB cable) and cannot be sent while BlueCore5-Multimedia External is effectively disconnected from the bus.

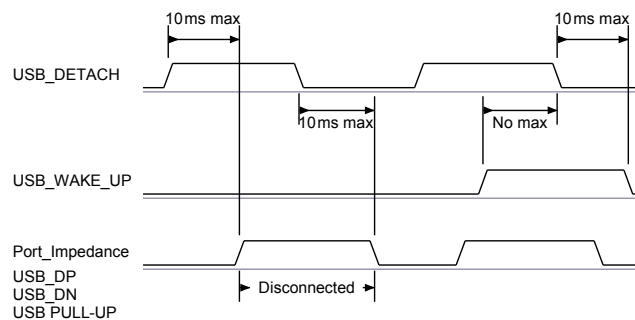


Figure 9.6: USB_DETACH and USB_WAKE_UP Signal

9.2.8 USB Driver

A USB device driver is required to provide a software interface between BlueCore5-Multimedia External and the software running on the host computer. Suitable drivers are available from www.csrsupport.com.

9.2.9 USB 1.1 Compliance

BlueCore5-Multimedia External is qualified to the USB specification v1.1, details of which are available from www.usb.org. The specification contains valuable information on aspects such as PCB track impedance, supply inrush current and product labelling.

Although BlueCore5-Multimedia External meets the USB specification, CSR cannot guarantee that an application circuit designed around the chip is USB compliant. The choice of application circuit, component choice and PCB layout all affect USB signal quality and electrical characteristics. The information in this document is intended as a guide and should be read in association with the USB specification, with particular attention being given to Chapter 7. Independent USB qualification must be sought before an application is deemed USB compliant and can display the USB logo.

Terminals USB_DP and USB_DN adhere to the USB specification v2.0 (Chapter 7) electrical requirements.

9.2.10 USB 2.0 Compatibility

BlueCore5-Multimedia External is compatible with USB v2.0 host controllers; under these circumstances the two ends agree the mutually acceptable rate of 12Mbits/s according to the USB v2.0 specification.

9.3 Serial Peripheral Interface

BlueCore5-Multimedia External uses a 16-bit data and 16-bit address serial peripheral interface, where transactions may occur when the internal processor is running or is stopped. This section describes the considerations required when interfacing to BlueCore5-Multimedia External.

9.3.1 Instruction Cycle

The BlueCore5-Multimedia External is the slave and receives commands on SPI_MOSI and outputs data on SPI_MISO. Table 9.4 shows the instruction cycle for an SPI transaction.

1	Reset the SPI interface	Hold SPI_CS# high for two SPI_CLK cycles
2	Write the command word	Take SPI_CS# low and clock in the 8-bit command
3	Write the address	Clock in the 16-bit address word
4	Write or read data words	Clock in or out 16-bit data word(s)
5	Termination	Take SPI_CS# high

Table 9.4: Instruction Cycle for an SPI Transaction

With the exception of reset, SPI_CS# must be held low during the transaction. Data on SPI_MOSI is clocked into the BlueCore5-Multimedia External on the rising edge of the clock line SPI_CLK. When reading, BlueCore5-Multimedia External replies to the master on SPI_MISO with the data changing on the falling edge of the SPI_CLK. The master provides the clock on SPI_CLK. The transaction is terminated by taking SPI_CS# high.

Sending a command word and the address of a register for every time it is to be read or written is a significant overhead, especially when large amounts of data are to be transferred. To overcome this BlueCore5-Multimedia External offers increased data transfer efficiency via an auto increment operation. To invoke auto increment, SPI_CS# is kept low, which auto increments the address, while providing an extra 16 clock cycles for each extra word to be written or read.

9.3.2 Writing to the Device

To write to BlueCore5-Multimedia External, the 8-bit write command (0000010) is sent first (C[7:0]) followed by a 16-bit address (A[15:0]). The next 16-bits (D[15:0]) clocked in on SPI_MOSI are written to the location set by the address (A). Thereafter for each subsequent 16-bits clocked in, the address (A) is incremented and the data written to consecutive locations until the transaction terminates when SPI_CS# is taken high.

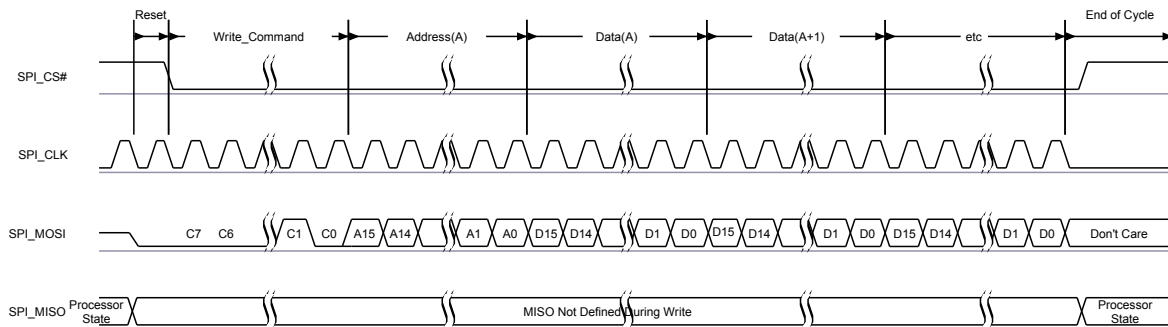


Figure 9.7: SPI Write Operation

9.3.3 Reading from the Device

Reading from BlueCore5-Multimedia External is similar to writing to it. An 8-bit read command (0000011) is sent first (C[7:0]), followed by the address of the location to be read (A[15:0]). BlueCore5-Multimedia External then outputs on SPI_MISO a check word during T[15:0] followed by the 16-bit contents of the addressed location during bits D[15:0].

The check word is composed of {command, address [15:8]}. The check word may be used to confirm a read operation to a memory location. This overcomes the problems encountered with typical serial peripheral interface slaves, whereby it is impossible to determine whether the data returned by a read operation is valid data or the result of the slave device not responding.

If SPI_CS# is kept low, data from consecutive locations is read out on SPI_MISO for each subsequent 16 clocks, until the transaction terminates when SPI_CS# is taken high.

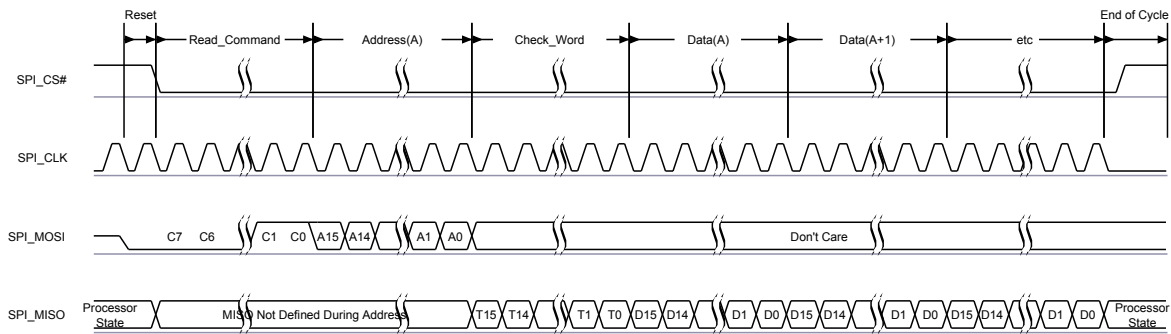


Figure 9.8: SPI Read Operation

9.3.4 Multi-slave Operation

BlueCore5-Multimedia External should not be connected in a multi-slave arrangement by simple parallel connection of slave MISO lines. When BlueCore5-Multimedia External is deselected ($SPI_CS\# = 1$), the SPI_MISO line does not float. Instead, BlueCore5-Multimedia External outputs 0 if the processor is running or 1 if it is stopped.

9.4 I²C Interface

9.4.1 Software I²C Interface

PIO[8:6] can be used to form a Master I²C interface. The interface is formed using software to drive these lines. Therefore it is suited only to relatively slow functions such as driving a dot matrix *liquid crystal display* (LCD), keyboard scanner or EEPROM.

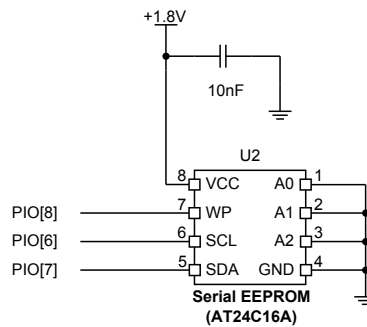


Figure 9.9: Example EEPROM Connection

9.4.2 Bit-serialiser Interface

In addition to the software I²C interface outlined in Section 9.4.1, the BlueCore5-Multimedia External includes a configurable hardware bit-serialiser interface. Any three PIOs can be used as a serial master interface by configuring the hardware bit-serialiser. The I²C master interface available supports address, direction and ACK handling, but does not support multi-master I²C bus systems.

The I²C interface can be directly controlled by the MCU or the Kalimba DSP.

Note:

Suitable firmware is required to support the hardware bit-serialiser interface.

I²C and SPI are supported.

10 Audio Interfaces

10.1 Audio Interface

The audio interface circuit consists of:

- Stereo audio CODEC
- Dual audio inputs and outputs
- A configurable PCM, I²S or SPDIF interface

Figure 10.1 shows the functional blocks of the interface. The CODEC supports stereo playback and recording of audio signals at multiple sample rates with a resolution of 16-bit. The ADC and the DAC of the CODEC each contain two independent channels. Any ADC or DAC channel can be run at its own independent sample rate.

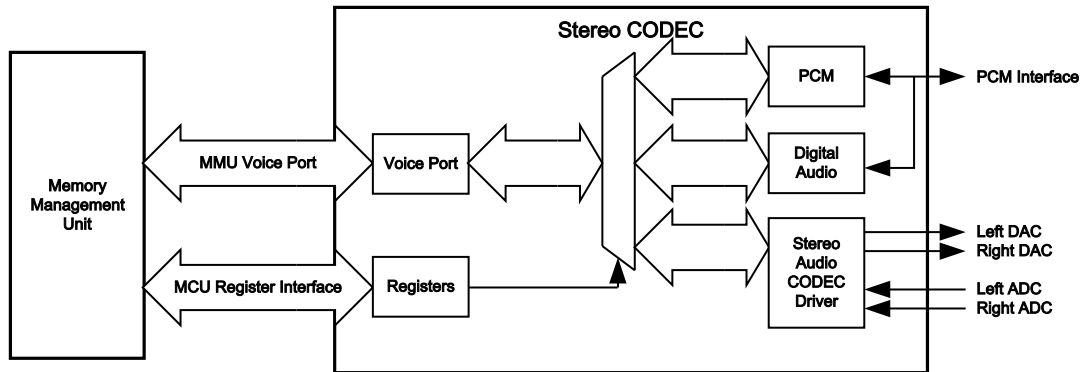


Figure 10.1: Audio Interface

The interface for the digital audio bus shares the same pins as the PCM CODEC interface described in Section 10.3 which means each of the audio buses are mutually exclusive in their usage. Table 10.1 lists these alternative functions.

PCM Interface	SPDIF Interface	I ² S Interface
PCM_OUT	SPDIF_OUT	SD_OUT
PCM_IN	SPDIF_IN	SD_IN
PCM_SYNC	-	WS
PCM_CLK	-	SCK

Table 10.1: Alternative Functions of the Digital Audio Bus Interface on the PCM Interface

10.1.1 Audio Input and Output

The audio input circuitry consists of a dual audio input that can be configured to be either single-ended or fully differential and programmed for either microphone or line input. It has an analogue and digital programmable gain stage for optimisation of different microphones.

The audio output circuitry consists of a dual differential class A-B output stage.

10.2 Stereo Audio CODEC Interface

The main features of the interface are:

- Stereo and mono analogue input for voice band and audio band
- Stereo and mono analogue output for voice band and audio band
- Support for stereo digital audio bus standards such as I²S
- Support for IEC-60958 standard stereo digital audio bus standards, e.g. S/PDIF and AES3/EBU
- Support for PCM interfaces including PCM master CODECs that require an external system clock

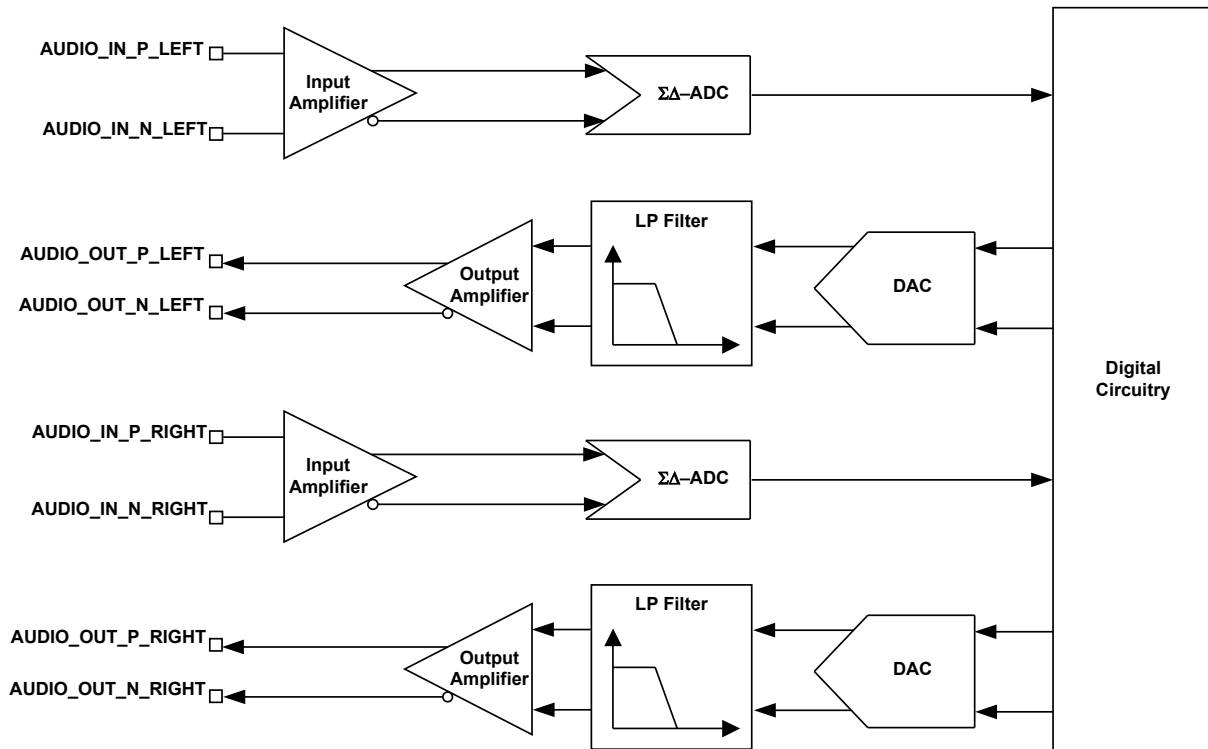


Figure 10.2: Stereo CODEC Audio Input and Output Stages

The stereo audio CODEC uses a fully differential architecture in the analogue signal path, which results in low noise sensitivity and good power supply rejection while effectively doubling the signal amplitude. It operates from a single power-supply of 1.5V and uses a minimum of external components.

Important Note:

To avoid any confusion regarding stereo operation this data sheet explicitly states which is the left and right channel for audio input and output. With respect to software and any registers, channel 0 or channel A represents the left channel and channel 1 or channel B represents the right channel for both input and output.

For mono operation this data sheet uses the left channel for standard mono operation for audio input and output and with respect to software and any registers, channel 0 or channel A represents the standard mono channel for audio input and output. In mono operation the second channel which is the right channel, channel 1 or channel B could be used as a second mono channel if required and this channel is referred to as the auxiliary mono channel for audio input and output.

10.2.1 Stereo CODEC Set-up

The configuration and control of the ADC is through VM functions which are described in appropriate BlueLab Multimedia documentation. This section is an overview of the parameters that can be set up using the VM functions.

The Kalimba DSP can communicate its requirements of the CODEC to the MCU, and therefore also the VM, by exchange of messages. The messages used between the Kalimba DSP and the embedded MCU are based on interrupts:

- 1 interrupt between the MCU and Kalimba DSP
- 1 interrupt between the Kalimba DSP and the MCU

Message content is transmitted using shared memory. There are VM and DSP library functions to send and receive messages; refer to BlueLab Multimedia documentation for further details.

10.2.2 ADC

The ADC consists of two second-order Sigma Delta converters allowing two separate channels that are identical in functionality, as shown in Figure 10.2.

10.2.3 ADC Sample Rate Selection

Each ADC supports the following sample rates:

- 8kHz
- 11.025kHz
- 16kHz
- 22.05kHz
- 24kHz
- 32kHz
- 44.1kHz

10.2.4 ADC Gain

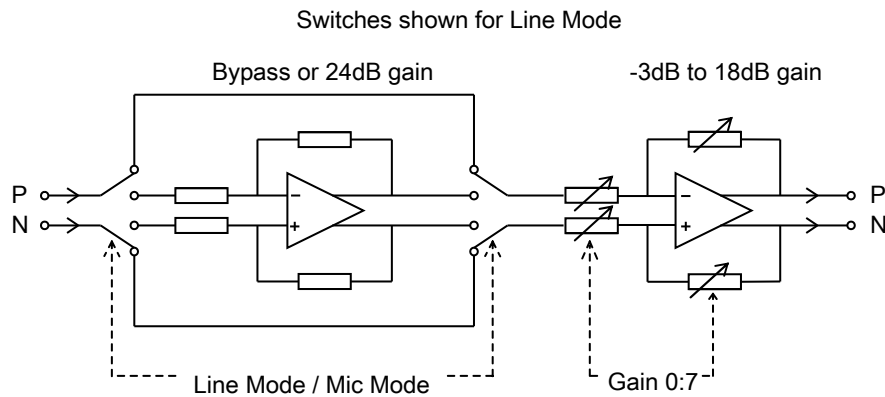
The ADC contains two gain stages for each channel, an analogue and a digital gain stage.

The digital gain stage has a programmable selection value in the range of 0 to 15 with the associated ADC gain settings summarised in Table 10.2. There is also a high resolution digital gain mode that allows the gain to be changed in 1/32dB steps. Contact CSR for more information.

Gain Selection Value	ADC Digital Gain Setting (dB)
0	0
1	3.5
2	6
3	9.5
4	12
5	15.5
6	18
7	21.5
8	-24
9	-20.5
10	-18
11	-14.5
12	-12
13	-8.5
14	-6
15	-2.5

Table 10.2: ADC Digital Gain Rate Selection

The ADC analogue amplifier is a two-stage amplifier. The first stage of the analogue amplifier is responsible for selecting the correct gain for either microphone input or line input and therefore has two gain settings, one for the microphone and one for the line input. See Section 10.2.9 and Section 10.2.10 for details on the microphone and line inputs, respectively. The first stage amplifier has a selectable 24dB gain stage for the microphone and this creates the dual programmable gain required for the microphone or the line input. The equivalent block diagram for the two stage is shown in Figure 10.3.



Microphone Mode input impedance = $6k\Omega$

Line mode input impedance = $6k\Omega$ to $30k\Omega$

Figure 10.3: ADC Analogue Amplifier Block Diagram

The second stage of the analogue amplifier shown in Figure 10.3 has a programmable gain with seven individual 3dB steps. By combining the 24dB gain selection of the microphone input with the seven individual 3dB gain steps, the overall range of the analogue amplifier is approximately -3dB to 42dB in 3dB steps. The overall gain control of the ADC is controlled by the a VM function.

10.2.5 DAC

The DAC consists of two third-order Sigma Delta converters allowing two separate channels that are identical in functionality as shown in Figure 10.2.

10.2.6 DAC Sample Rate Selection

Each DAC supports the following samples rates:

- 8kHz
- 11.025kHz
- 12kHz
- 16kHz
- 22.050kHz
- 24kHz
- 32kHz
- 44.1kHz
- 48kHz

10.2.7 DAC Gain

The DAC contains two gain stages for each channel: a digital and an analogue gain stage.

The digital gain stage has a programmable selection value in the range of 0 to 15 with associated DAC gain settings. This is summarised in Table 10.3. There is also a high resolution digital gain mode that allows the gain to be changed in 1/32dB steps. Contact CSR for more information.

Digital Gain Selection Value	DAC Digital Gain Setting (dB)
0	0
1	3.5
2	6
3	9.5

Digital Gain Selection Value	DAC Digital Gain Setting (dB)
4	12
5	15.5
6	18
7	21.5
8	-24
9	-20.5
10	-18
11	-14.5
12	-12
13	-8.5
14	-6
15	-2.5

Table 10.3: DAC Digital Gain Rate Selection

The overall gain control of the DAC is controlled by a VM function. This setting is a combined function of the digital and analogue amplifier settings, therefore, for a 1V rms nominal digital output signal from the digital gain stage of the DAC, the following approximate output values of the analogue amplifier of the DAC can be expected:

Analogue Gain Selection Value	DAC Analogue Gain Setting (dB)
7	3
6	0
5	-3
4	-6
3	-9
2	-12
1	-15
0	-18

Table 10.4: DAC Analogue Gain Rate Selection

10.2.8 IEC 60958 Interface

The IEC 60958 interface is a digital audio interface that uses bi-phase coding to minimise the DC content of the transmitted signal and allows the receiver to decode the clock information from the transmitted signal. The IEC 60958 specification is based on the two industry standards:

- AES/EBU
- Sony and Philips interface specification SPDIF

The interface is compatible with IEC 60958-1, IEC 60958-3 and IEC 60958-4.

The SPDIF interface signals are SPDIF_IN and SPDIF_OUT and are shared on the PCM interface pins. The input and output stages of the SPDIF pins can interface to:

- A 75Ω coaxial cable with an RCA connector, see Figure 10.4
- An optical link that uses Toslink optical components, see Figure 10.5.

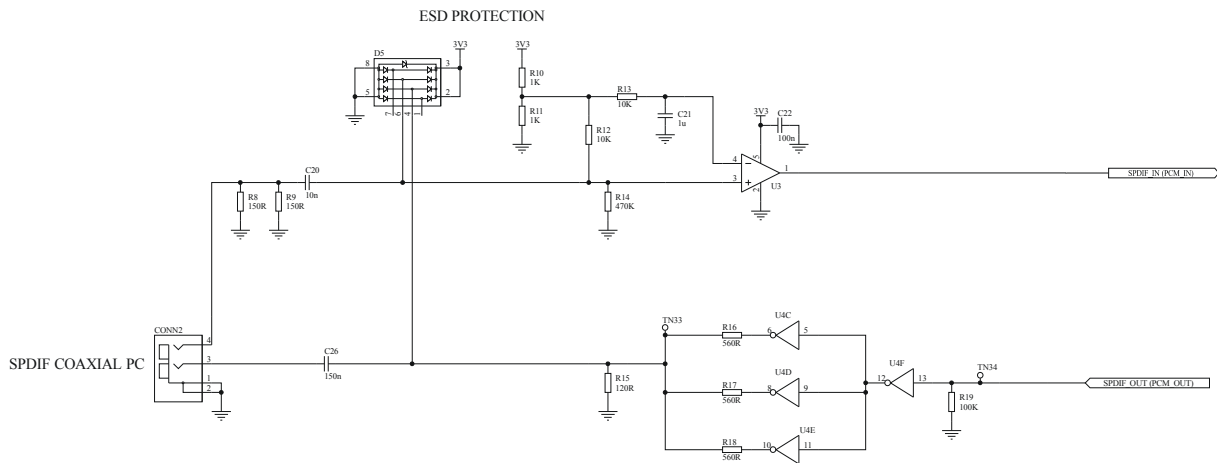


Figure 10.4: Example Circuit for SPDIF Interface (Co-Axial)

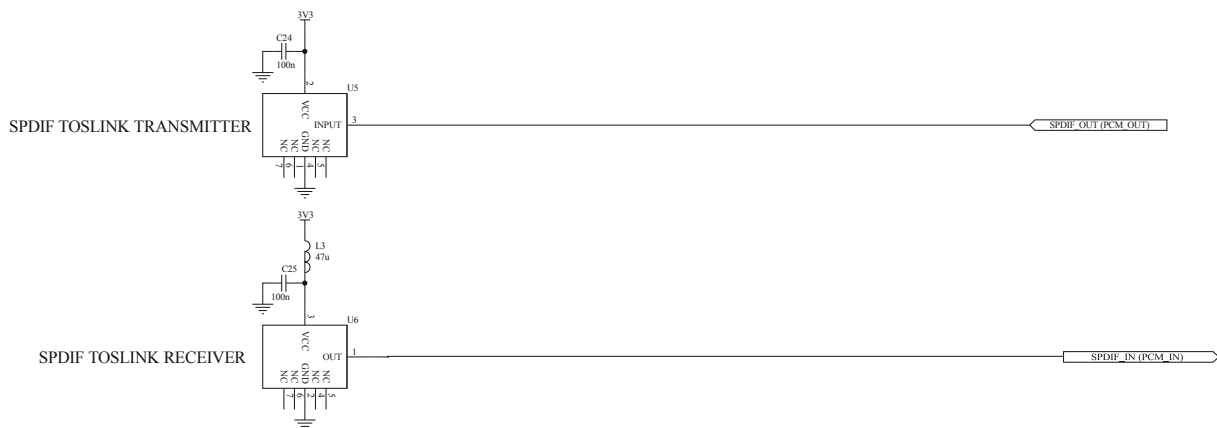


Figure 10.5: Example Circuit for SPDIF Interface (Optical)

10.2.9 Microphone Input

The audio input is intended for use from $1\mu\text{A}@94\text{dB SPL}$ to about $10\mu\text{A}@94\text{dB SPL}$. With biasing resistors R1 and R2 equal to $1\text{k}\Omega$, this requires microphones with sensitivity between about -40dBV and -60dBV . The microphone for each channel should be biased as shown in Figure 10.6. The microphone bias, MIC_BIAS, derives its power from the BAT_P and also requires a $1\mu\text{F}$ capacitor on its output.

The MIC_BIAS is like any voltage regulator and requires a minimum load to maintain regulation. The MIC_BIAS maintains regulation within the limits $0.199 - 1.229\text{mA}$. This means, if a microphone is used that sits below these limits, then the microphone output must be pre-loaded with a large value resistor to ground.

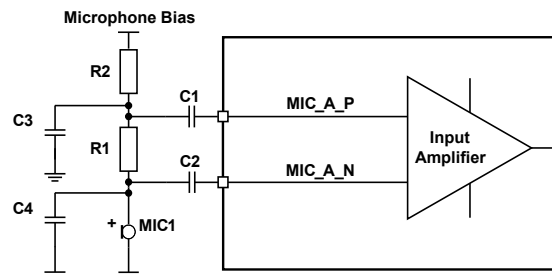


Figure 10.6: Microphone Biasing (Left Channel Shown)

The input impedance at AUDIO_IN_N_LEFT, AUDIO_IN_P_LEFT, AUDIO_IN_N_RIGHT and AUDIO_IN_P_RIGHT is typically $6.0\text{k}\Omega$. C1 and C2 should be 150nF if bass roll-off is required to limit wind noise on the microphone. R1 sets the microphone load impedance and is normally in a range of $1 - 2\text{k}\Omega$. R2, C3 and C4 improve the supply rejection by decoupling supply noise from the microphone. Values should be selected as required. R2 may be

connected to a convenient supply, in which case the bias network is permanently enabled, or to the MIC_BIAS output (which is ground referenced and provides good rejection of the supply), which may be configured to provide bias only when the microphone is required.

The microphone bias provides a 4-bit programmable output voltage, shown in Table 10.5, with a 4-bit programmable output current, shown in Table 10.6.

The basic specifications of the microphone bias include:

- Power supply, BAT_P: the minimum input battery voltage should be “Output voltage” + “Drop-out voltage”, and the maximum input voltage is 4.9V. VDD_AUDIO - 1.5V typical.
- Drop-out voltage: 300mV (minimum) guaranteed for all voltage/current output setup
- Output voltage: 4-bit programmable between 1.8 - 3.6V, tolerance 90 - 110%
- Output current: 200uA – 1.229mA, maximum current guaranteed to be >1mA
- Load capacitance: unconditionally stable for 1uF ±20% and 2.2uF ±20% pure C

Output Step	VOL_SET[3:0]	Min	Typ	Max	Units
0	0000	-	1.71	-	V
1	0001	-	1.76	-	V
2	0010	-	1.82	-	V
3	0011	-	1.87	-	V
4	0100	-	1.95	-	V
5	0101	-	2.02	-	V
6	0110	-	2.10	-	V
7	0111	-	2.18	-	V
8	1000	-	2.32	-	V
9	1001	-	2.43	-	V
10	1010	-	2.56	-	V
11	1011	-	2.69	-	V
12	1100	-	2.90	-	V
13	1101	-	3.08	-	V
14	1110	-	3.33	-	V
15	1111	-	3.57	-	V

Table 10.5: Voltage Output Steps

Output Step	CUR_SET[3:0]	Min	Typ	Max	Units
0	0000	-	0.199	-	mA
1	0001	-	0.284	-	mA
2	0010	-	0.336	-	mA
3	0011	-	0.419	-	mA
4	0100	-	0.478	-	mA
5	0101	-	0.529	-	mA

Output Step	CUR_SET[3:0]	Min	Typ	Max	Units
6	0110	-	0.613	-	mA
7	0111	-	0.672	-	mA
8	1000	-	0.754	-	mA
9	1001	-	0.809	-	mA
10	1010	-	0.862	-	mA
11	1011	-	0.948	-	mA
12	1100	-	1.004	-	mA
13	1101	-	1.091	-	mA
14	1110	-	1.142	-	mA
15	1111	-	1.229	-	mA

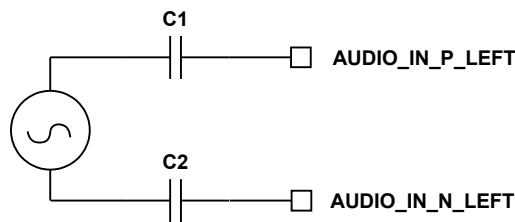
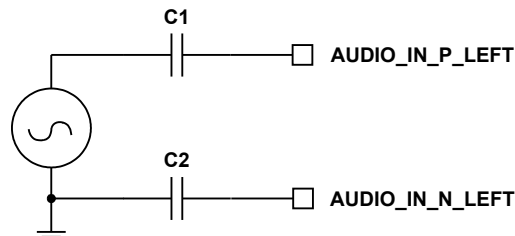
Table 10.6: Current Output Steps
Note:

For BAT_P, the PSRR @ 100Hz - 22KHz, with >300mV supply headroom, decoupling capacitor of 1.1µF, is typically 58.9dB and worst case 53.4dB.

For VDD_AUDIO, the PSRR @ 100Hz to 22KHz, decoupling capacitor of 1.1µF, is typically 88dB and worst case 60dB.

10.2.10 Line Input

If the input analogue gain is set to less than 21dB, BlueCore5-Multimedia External automatically selects line input mode. In line input mode the first stage of the amplifier is automatically disabled, providing additional power saving. In line input mode the input impedance varies from 6kΩ-30kΩ, depending on the volume setting. Figure 10.7 and Figure 10.8 show two circuits for line input operation and show connections for either differential or single-ended inputs.


Figure 10.7: Differential Input (Left Channel Shown)

Figure 10.8: Single-Ended Input (Left Channel Shown)

10.2.11 Output Stage

The output digital circuitry converts the signal from 16-bit per sample, linear PCM of variable sampling frequency to bit stream, which is fed into the analogue output circuitry.

The output circuit comprises a DAC with gain setting and class AB output stage amplifier. The output is available as a differential signal between AUDIO_OUT_N_LEFT and AUDIO_OUT_P_LEFT for the left channel, as Figure 10.9 shows, and between AUDIO_OUT_N_RIGHT and AUDIO_OUT_P_RIGHT for the right channel. The output is capable of driving a speaker directly if its impedance is at least 8Ω at reduced output swing and if only one channel is connected or an external regulator is used.

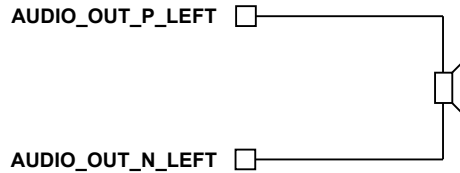


Figure 10.9: Speaker Output (Left Channel Shown)

The analogue gain of the output stage is controlled by a 3-bit programmable resistive divider, which sets the gain in steps of approximately 3dB.

10.2.12 Mono Operation

Mono operation is a single-channel operation of the stereo CODEC. The left channel represents the single mono channel for audio in and audio out. In mono operation the right channel is auxiliary mono channel that may be used in dual mono channel operation. See Section 10.2 for stereo and mono definitions.

With single mono, the power consumption can be reduced by disabling the other channel.

10.2.13 Side Tone

In some applications it is necessary to implement side tone. This involves feeding an attenuated version of the microphone signal to the earpiece. The BlueCore5-Multimedia External CODEC contains side tone circuitry to do this. The side tone hardware is configured through the the following PS Keys:

- PSKEY_SIDE_TONE_ENABLE
- PSKEY_SIDE_TONE_GAIN
- PSKEY_SIDE_TONE_AFTER_ADC
- PSKEY_SIDE_TONE_AFTER_DAC

10.2.14 Integrated Digital Filter

BlueCore5-Multimedia External has a programmable digital filter integrated into each ADC channel of the stereo CODEC. The filter is a two stage, second order *infinite impulse response* (IIR) and can be used for functions such as custom wind noise rejection. The filter also has optional DC blocking.

The filter has 10 configuration words used as follows:

- 1 for gain value
- 8 for coefficient values
- 1 for enabling and disabling the DC blocking

The gain and coefficients are all 12-bit 2's complement signed integer with the format `XX.XXXXXXXXXX`

Note:

The position of the binary point

For example:

01.1111111111 = most positive number, close to +2

01.0000000000 = 1

00.0000000000 = 0

11.0000000000 = -1

10.0000000000 = -2, most negative number

The equation for the IIR filter is shown in Equation 10.1. When the DC blocking is enabled the equation is shown in Equation 10.2.

The filter can be configured, enabled and disabled from the VM via the `CodecSetIIRFilterA` and `CodecSetIIRFilterB` traps¹. The configuration function takes 10 variables in the order shown below:

- 0 : Gain
- 1 : b_{01}
- 2 : b_{02}
- 3 : a_{01}
- 4 : a_{02}
- 5 : b_{11}
- 6 : b_{12}
- 7 : a_{11}
- 8 : a_{12}
- 9 : DC Block (1 = enable, 0 = disable)

$$\text{Filter, } H(z) = \text{Gain} \times \frac{(1 + b_{01} z^{-1} + b_{02} z^{-2})}{(1 + a_{01} z^{-1} + a_{02} z^{-2})} \times \frac{(1 + b_{11} z^{-1} + b_{12} z^{-2})}{(1 + a_{11} z^{-1} + a_{12} z^{-2})}$$

Equation 10.1: IIR Filter Transfer Function, $H(z)$

$$\text{Filter with DC Blocking, } H_{DC}(z) = H(z) \times (1 - z^{-1})$$

Equation 10.2: IIR Filter plus DC Blocking Transfer Function, $H_{DC}(z)$

10.3 PCM Interface

The audio *pulse code modulation* (PCM) interface supports continuous transmission and reception of PCM encoded audio data over Bluetooth.

PCM is a standard method used to digitise audio (particularly voice) for transmission over digital communication channels. Through its PCM interface, BlueCore5-Multimedia External has hardware support for continual transmission and reception of PCM data, so reducing processor overhead for wireless headset applications. BlueCore5-Multimedia External offers a bi-directional digital audio interface that routes directly into the baseband layer of the on-chip firmware. It does not pass through the HCI protocol layer.

Hardware on BlueCore5-Multimedia External allows the data to be sent to and received from a SCO connection.

Up to three SCO connections can be supported by the PCM interface at any one time.

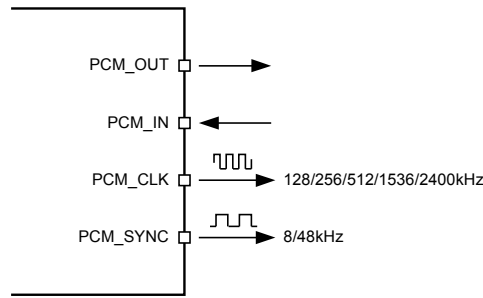
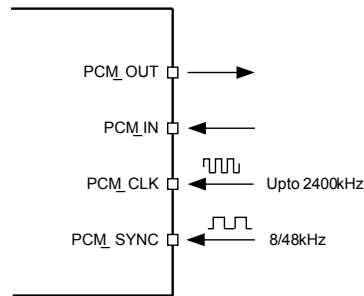
BlueCore5-Multimedia External can operate as the PCM interface master generating `PCM_SYNC` and `PCM_CLK` or as a PCM interface slave accepting externally generated `PCM_SYNC` and `PCM_CLK`. BlueCore5-Multimedia External is compatible with various clock formats, including Long Frame Sync, Short Frame Sync and GCI timing environments.

It supports 13-bit or 16-bit linear, 8-bit μ -law or A-law companded sample formats, and can receive and transmit on any selection of three of the first four slots following `PCM_SYNC`. The PCM configuration options are enabled by setting the PS Key `PS_KEY_PCM_CONFIG32` (0x1b3).

10.3.1 PCM Interface Master/Slave

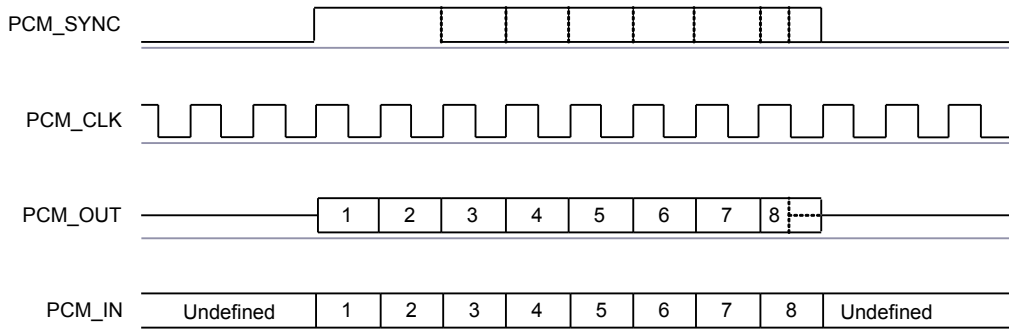
When configured as the master of the PCM interface, BlueCore5-Multimedia External generates `PCM_CLK` and `PCM_SYNC`.

¹ Requires firmware support


Figure 10.10: PCM Interface Master

Figure 10.11: PCM Interface Slave

10.3.2 Long Frame Sync

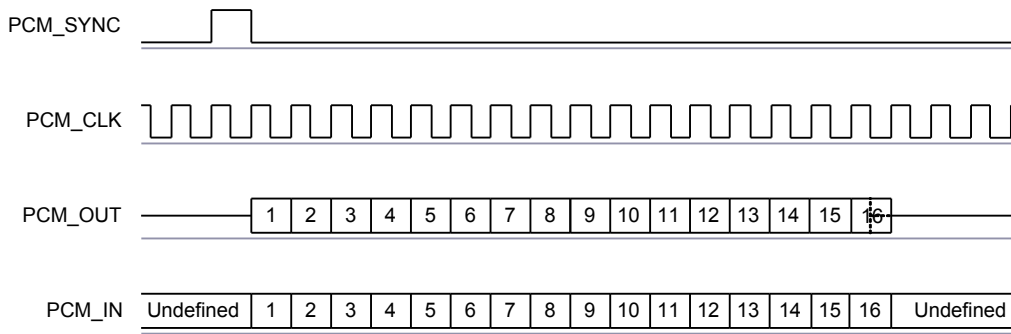
Long Frame Sync is the name given to a clocking format that controls the transfer of PCM data words or samples. In Long Frame Sync, the rising edge of PCM_SYNC indicates the start of the PCM word. When BlueCore5-Multimedia External is configured as PCM master, generating PCM_SYNC and PCM_CLK, then PCM_SYNC is 8-bits long. When BlueCore5-Multimedia External is configured as PCM Slave, PCM_SYNC may be from one cycle PCM_CLK to half the PCM_SYNC rate.


Figure 10.12: Long Frame Sync (Shown with 8-bit Companded Sample)

BlueCore5-Multimedia External samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT may be configured to be high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge.

10.3.3 Short Frame Sync

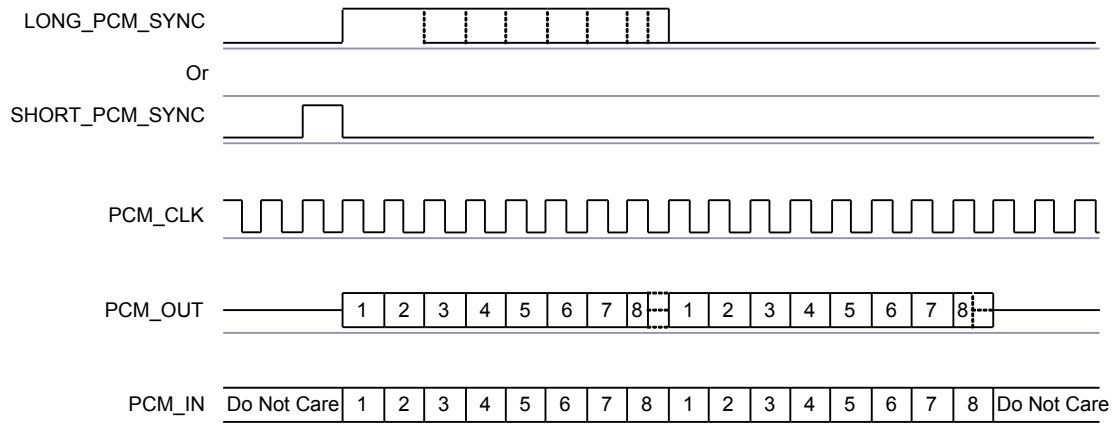
In Short Frame Sync, the falling edge of PCM_SYNC indicates the start of the PCM word. PCM_SYNC is always one clock cycle long.


Figure 10.13: Short Frame Sync (Shown with 16-bit Sample)

As with Long Frame Sync, BlueCore5-Multimedia External samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT may be configured to be high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge.

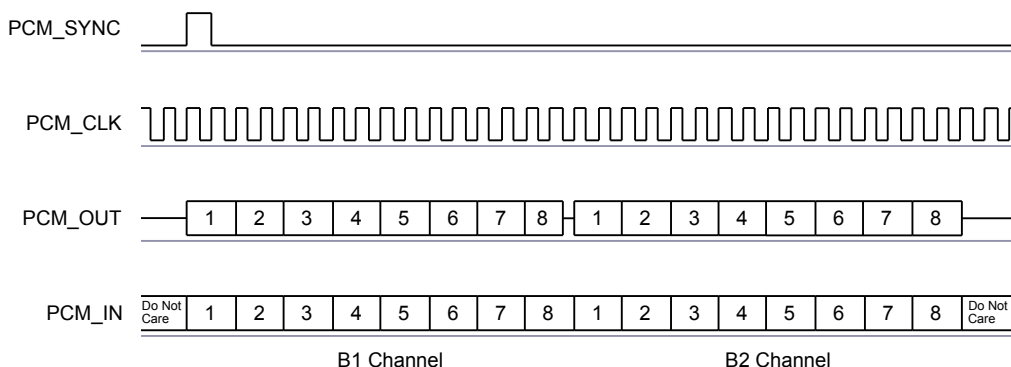
10.3.4 Multi-slot Operation

More than one SCO connection over the PCM interface is supported using multiple slots. Up to three SCO connections can be carried over any of the first four slots.


Figure 10.14: Multi-slot Operation with Two Slots and 8-bit Companded Samples

10.3.5 GCI Interface

BlueCore5-Multimedia External is compatible with the *General Circuit Interface (GCI)*, a standard synchronous 2B+D ISDN timing interface. The two 64kbps B channels can be accessed when this mode is configured.


Figure 10.15: GCI Interface

The start of frame is indicated by the rising edge of PCM_SYNC and runs at 8kHz.

10.3.6 Slots and Sample Formats

BlueCore5-Multimedia External can receive and transmit on any selection of the first four slots following each sync pulse. Slot durations can be either 8 or 16 clock cycles. Durations of 8 clock cycles may only be used with 8-bit sample formats. Durations of 16 clocks may be used with 8-bit, 13-bit or 16-bit sample formats.

BlueCore5-Multimedia External supports 13-bit linear, 16-bit linear and 8-bit μ -law or A-law sample formats. The sample rate is 8ksamples/s. The bit order may be little or big endian. When 16-bit slots are used, the 3 or 8 unused bits in each slot may be filled with sign extension, padded with zeros or a programmable 3-bit audio attenuation compatible with some Motorola CODECs.

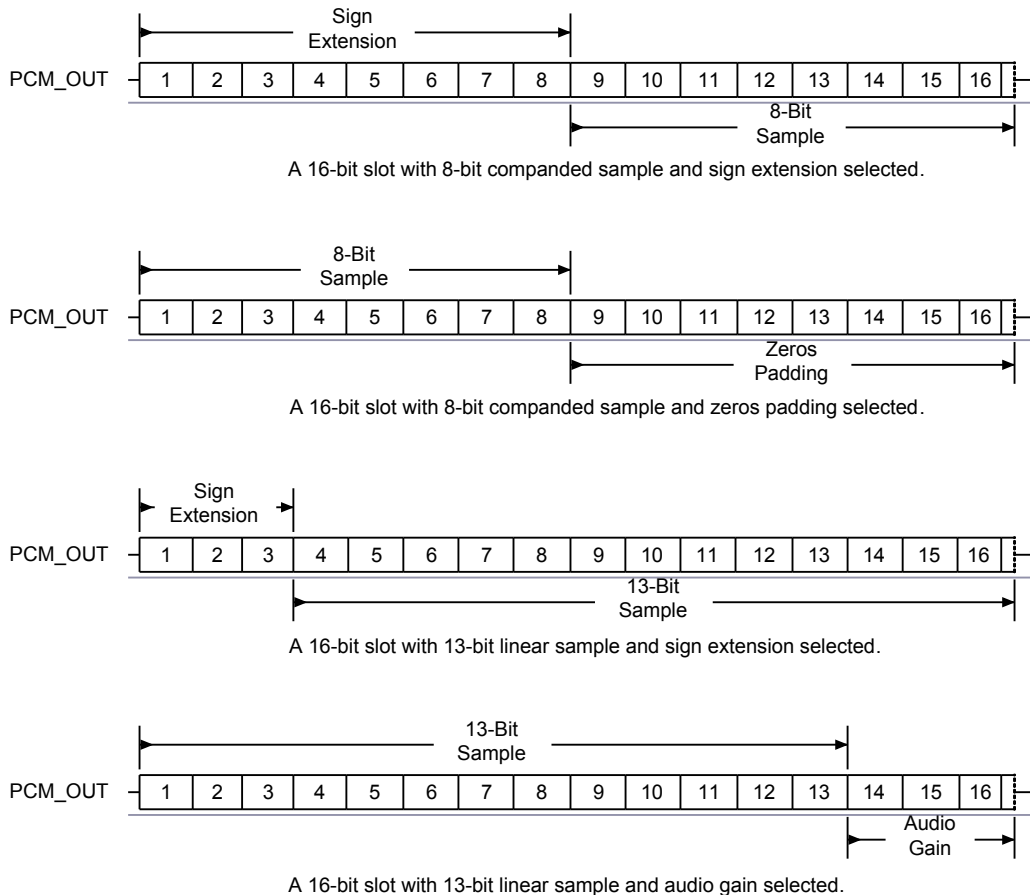


Figure 10.16: 16-Bit Slot Length and Sample Formats

10.3.7 Additional Features

BlueCore5-Multimedia External has a mute facility that forces PCM_OUT to be 0. In master mode, PCM_SYNC may also be forced to 0 while keeping PCM_CLK running which some CODECS use to control power down.

10.3.8 PCM Timing Information

Symbol	Parameter		Min	Typ	Max	Unit
f_{mclk}	PCM_CLK frequency	4MHz DDS generation. Selection of frequency is programmable. See Table 10.10.	-	128	-	kHz
				256		
				512		
		48MHz DDS generation. Selection of frequency is programmable. See Table 10.9 and Section 10.3.9.	2.9	-	-	kHz
-	PCM_SYNC frequency for SCO connection		-	8	-	kHz
$t_{mclkh}^{(a)}$	PCM_CLK high	4MHz DDS generation	980	-	-	ns
$t_{mckl}^{(a)}$	PCM_CLK low	4MHz DDS generation	730	-	-	ns
-	PCM_CLK jitter	48MHz DDS generation	-	-	21	ns pk-pk
$t_{dmclksynch}$	Delay time from PCM_CLK high to PCM_SYNC high		-	-	20	ns
$t_{dmclkpout}$	Delay time from PCM_CLK high to valid PCM_OUT		-	-	20	ns
$t_{dmcklsyncl}$	Delay time from PCM_CLK low to PCM_SYNC low (Long Frame Sync only)		-	-	20	ns
$t_{dmcklksyncl}$	Delay time from PCM_CLK high to PCM_SYNC low		-	-	20	ns
$t_{dmcklhpoutz}$	Delay time from PCM_CLK low to PCM_OUT high impedance		-	-	20	ns
$t_{dmcklhpoutz}$	Delay time from PCM_CLK high to PCM_OUT high impedance		-	-	20	ns
$t_{supinckl}$	Set-up time for PCM_IN valid to PCM_CLK low		30	-	-	ns
$t_{hpinckl}$	Hold time for PCM_CLK low to PCM_IN invalid		10	-	-	ns

Table 10.7: PCM Master Timing

^(a) Assumes normal system clock operation. Figures will vary during low power modes, when system clock speeds are reduced.

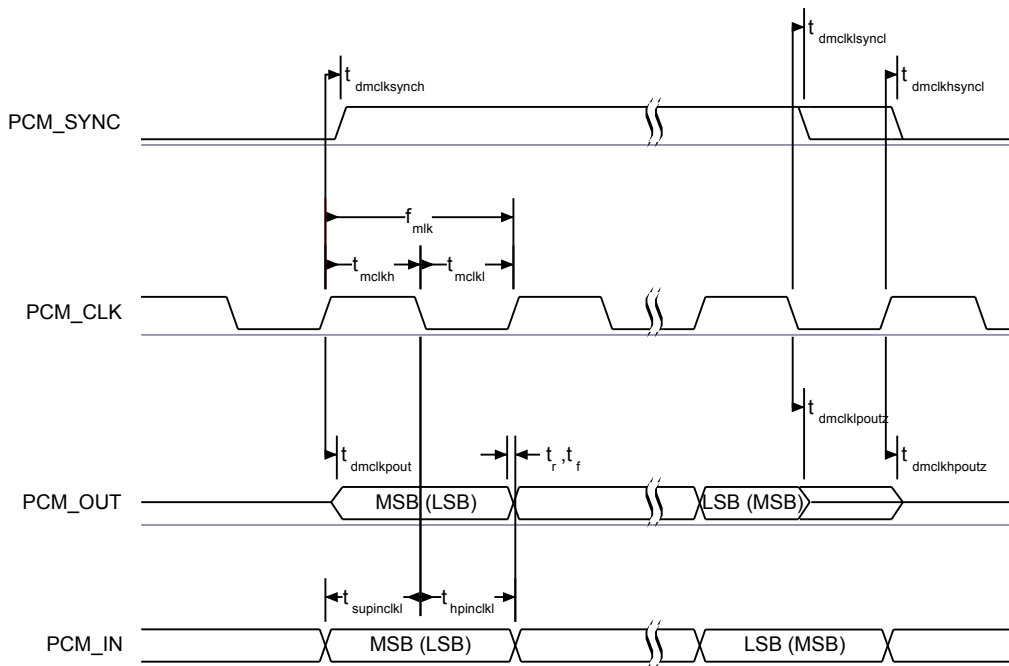


Figure 10.17: PCM Master Timing Long Frame Sync

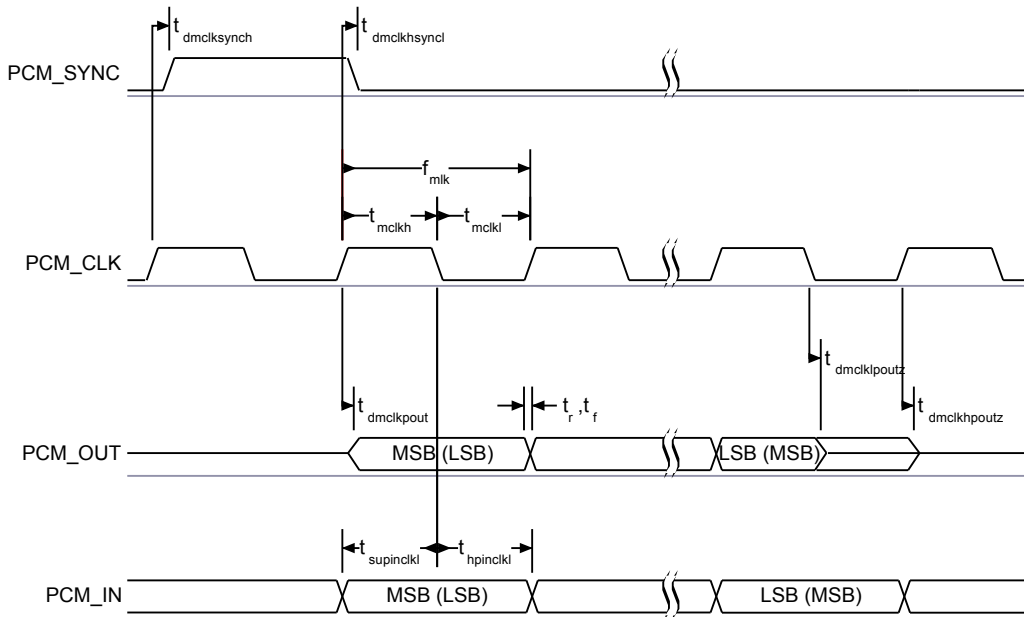


Figure 10.18: PCM Master Timing Short Frame Sync

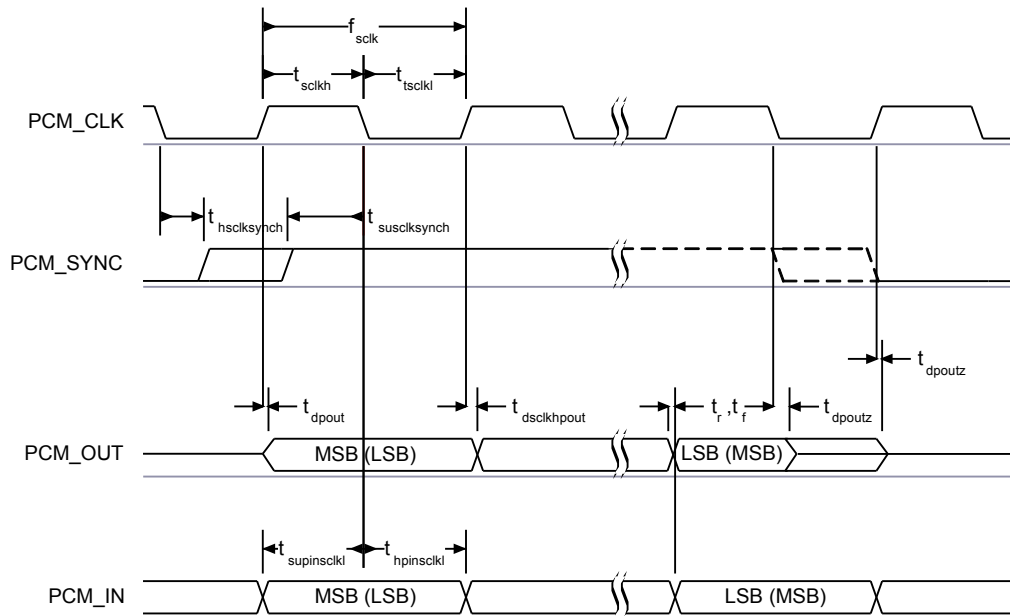
Symbol	Parameter	Min	Typ	Max	Unit
f_{sclk}	PCM clock frequency (Slave mode: input)	64	-	(a)	kHz
f_{sclk}	PCM clock frequency (GCI mode)	128	-	(b)	kHz
t_{sckl}	PCM_CLK low time	80	-	-	ns
t_{scklh}	PCM_CLK high time	80	-	-	ns
$t_{\text{hscklsynch}}$	Hold time from PCM_CLK low to PCM_SYNC high	20	-	-	ns

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{susclksynch}}$	Set-up time for PCM_SYNC high to PCM_CLK low	20	-	-	ns
t_{dpout}	Delay time from PCM_SYNC or PCM_CLK whichever is later, to valid PCM_OUT data (Long Frame Sync only)	-	-	20	ns
$t_{\text{dscclkhout}}$	Delay time from CLK high to PCM_OUT valid data	-	-	20	ns
t_{dpoutz}	Delay time from PCM_SYNC or PCM_CLK low, whichever is later, to PCM_OUT data line high impedance	-	-	20	ns
$t_{\text{supinsckl}}$	Set-up time for PCM_IN valid to CLK low	20	-	-	ns
t_{hpinsckl}	Hold time for PCM_CLK low to PCM_IN invalid	20	-	-	ns

Table 10.8: PCM Slave Timing

(a) Max frequency is the frequency defined by PSKEY_PCM_MIN_CPU_CLOCK

(b) Max frequency is twice the frequency defined by PSKEY_PCM_MIN_CPU_CLOCK


Figure 10.19: PCM Slave Timing Long Frame Sync

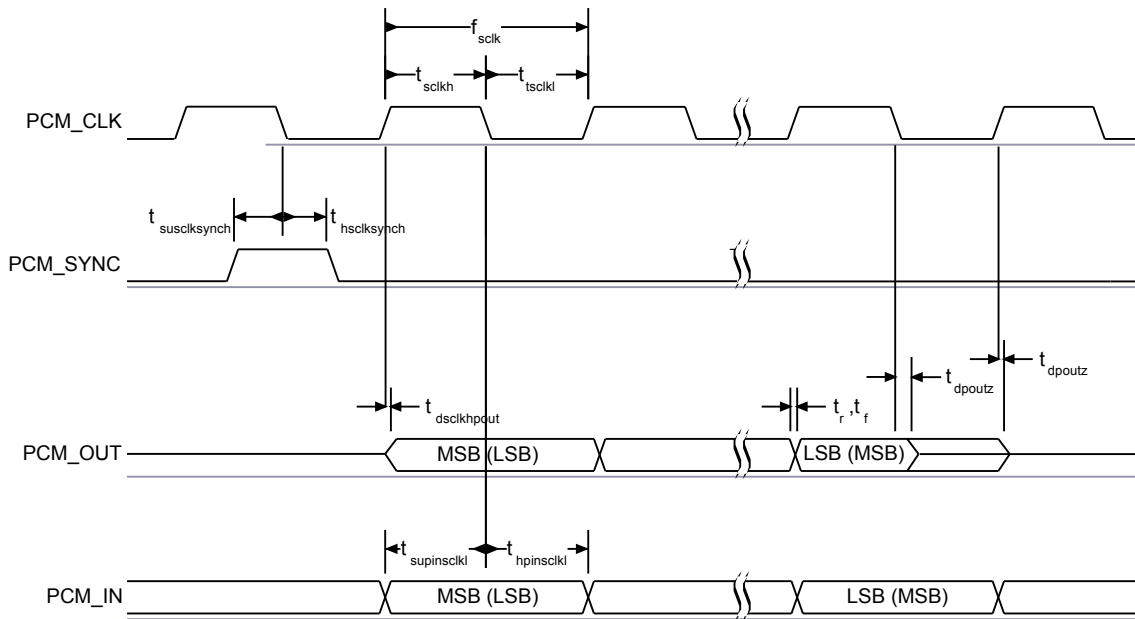


Figure 10.20: PCM Slave Timing Short Frame Sync

10.3.9 PCM_CLK and PCM_SYNC Generation

BlueCore5-Multimedia External has two methods of generating PCM_CLK and PCM_SYNC in master mode:

- Generating these signals by *Direct Digital Synthesis* (DDS) from BlueCore5-Multimedia External internal 4MHz clock. Using this mode limits PCM_CLK to 128, 256 or 512kHz and PCM_SYNC to 8kHz.
- Generating these signals by DDS from an internal 48MHz clock (which allows a greater range of frequencies to be generated with low jitter but consumes more power). This second method is selected by setting bit 48M_PCM_CLK_GEN_EN in PSKEY_PCM_CONFIG32. When in this mode and with long frame sync, the length of PCM_SYNC can be either 8 or 16 cycles of PCM_CLK, determined by LONG_LENGTH_SYNC_EN in PSKEY_PCM_CONFIG32.

Equation 10.3 describes PCM_CLK frequency when being generated using the internal 48MHz clock:

$$f = \frac{\text{CNT_RATE}}{\text{CNT_LIMIT}} \times 24\text{MHz}$$

Equation 10.3: PCM_CLK Frequency When Being Generated Using the Internal 48MHz Clock

Set the frequency of PCM_SYNC relative to PCM_CLK using Equation 10.4:

$$f = \frac{\text{PCM_CLK}}{\text{SYNC_LIMIT} \times 8}$$

Equation 10.4: PCM_SYNC Frequency Relative to PCM_CLK

CNT_RATE, CNT_LIMIT and SYNC_LIMIT are set using PSKEY_PCM_LOW_JITTER_CONFIG. As an example, to generate PCM_CLK at 512kHz with PCM_SYNC at 8kHz, set PSKEY_PCM_LOW_JITTER_CONFIG to 0x08080177.

10.3.10 PCM Configuration

The PCM configuration is set using the PS Keys, PSKEY_PCM_CONFIG32 described in Table 10.10 and PSKEY_PCM_LOW_JITTER_CONFIG in Table 10.9. The default for PSKEY_PCM_CONFIG32 is 0x00800000, i.e., first slot following sync is active, 13-bit linear voice format, long frame sync and interface master generating 256kHz PCM_CLK from 4MHz internal clock with no tri-state of PCM_OUT.

Name	Bit Position	Description
CNT_LIMIT	[12:0]	Sets PCM_CLK counter limit
CNT_RATE	[23:16]	Sets PCM_CLK count rate
SYNC_LIMIT	[31:24]	Sets PCM_SYNC division relative to PCM_CLK

Table 10.9: PSKEY_PCM_LOW_JITTER_CONFIG Description

Name	Bit Position	Description
-	0	Set to 0.
SLAVE_MODE_EN	1	0 = master mode with internal generation of PCM_CLK and PCM_SYNC. 1 = slave mode requiring externally generated PCM_CLK and PCM_SYNC.
SHORT_SYNC_EN	2	0 = long frame sync (rising edge indicates start of frame). 1 = short frame sync (falling edge indicates start of frame).
-	3	Set to 0.
SIGN_EXTEND_EN	4	0 = padding of 8 or 13-bit voice sample into a 16-bit slot by inserting extra LSBs. When padding is selected with 13-bit voice sample, the 3 padding bits are the audio gain setting; with 8-bit sample the 8 padding bits are zeroes. 1 = sign-extension.
LSB_FIRST_EN	5	0 = MSB first of transmit and receive voice samples. 1 = LSB first of transmit and receive voice samples.
TX_TRISTATE_EN	6	0 = drive PCM_OUT continuously. 1 = tri-state PCM_OUT immediately after falling edge of PCM_CLK in the last bit of an active slot, assuming the next slot is not active.
TX_TRISTATE_RISING_EDGE_EN	7	0 = tri-state PCM_OUT immediately after falling edge of PCM_CLK in last bit of an active slot, assuming the next slot is also not active. 1 = tri-state PCM_OUT after rising edge of PCM_CLK.
SYNC_SUPPRESS_EN	8	0 = enable PCM_SYNC output when master. 1 = suppress PCM_SYNC while keeping PCM_CLK running. Some CODECS use this to enter a low power state.
GCI_MODE_EN	9	1 = enable GCI mode.
MUTE_EN	10	1 = force PCM_OUT to 0.

Name	Bit Position	Description
48M_PCM_CLK_GEN_EN	11	0 = set PCM_CLK and PCM_SYNC generation via DDS from internal 4MHz clock. 1 = set PCM_CLK and PCM_SYNC generation via DDS from internal 48MHz clock.
LONG_LENGTH_SYNC_EN	12	0 = set PCM_SYNC length to 8 PCM_CLK cycles. 1 = set length to 16 PCM_CLK cycles. Only applies for long frame sync and with 48M_PCM_CLK_GEN_EN set to 1.
-	[20:16]	Set to 0b00000.
MASTER_CLK_RATE	[22:21]	Selects 128 (0b01), 256 (0b00), 512 (0b10) kHz PCM_CLK frequency when master and 48M_PCM_CLK_GEN_EN (bit 11) is low.
ACTIVE_SLOT	[26:23]	Default is 0001. Ignored by firmware.
SAMPLE_FORMAT	[28:27]	Selects between 13 (0b00), 16 (0b01), 8 (0b10) bit sample with 16-cycle slot duration or 8 (0b11) bit sample with 8-cycle slot duration.

Table 10.10: PSKEY_PCM_CONFIG32 Description

10.4 Digital Audio Interface (I²S)

The digital audio interface supports the industry standard formats for I²S, *left-justified* (LJ) or *right-justified* (RJ). The interface shares the same pins as the PCM interface, which means each audio bus is mutually exclusive in its usage. Table 10.11 lists these alternative functions. Figure 10.21 shows the timing diagram.

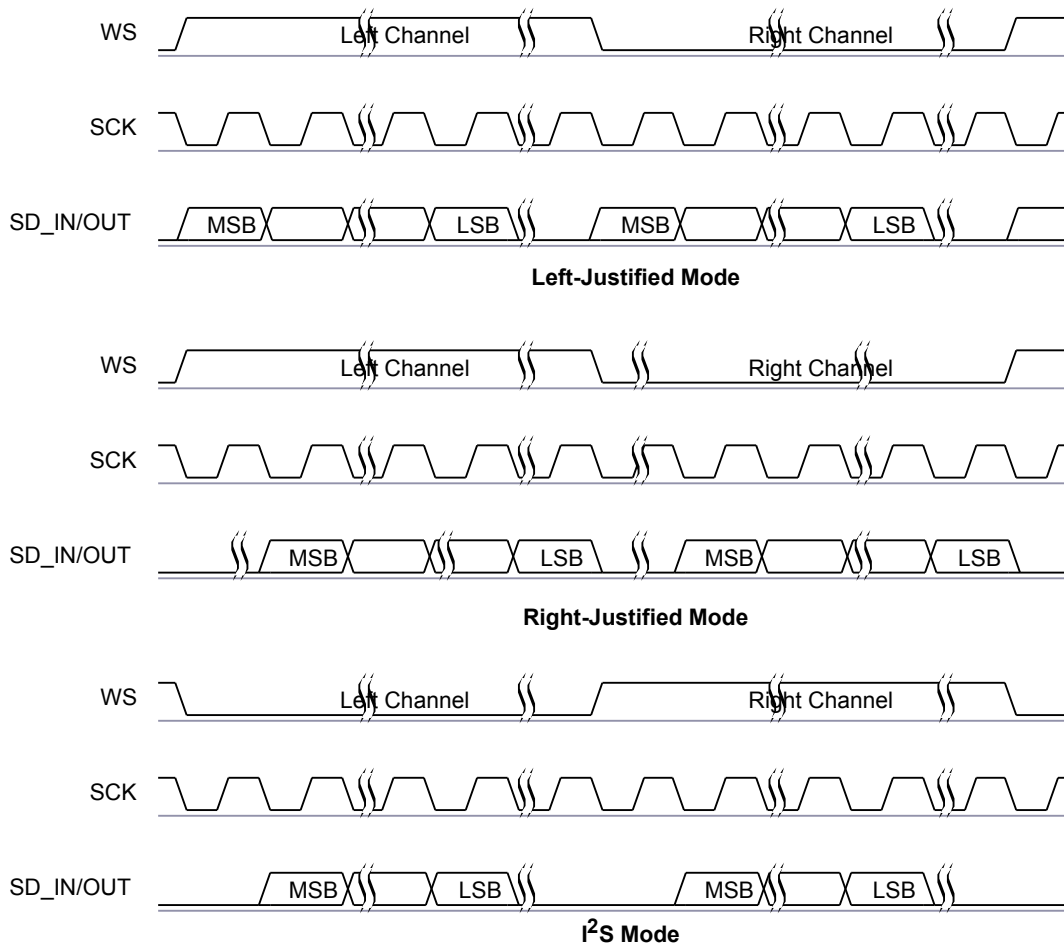
PCM Interface	I ² S Interface
PCM_OUT	SD_OUT
PCM_IN	SD_IN
PCM_SYNC	WS
PCM_CLK	SCK

Table 10.11: Alternative Functions of the Digital Audio Bus Interface on the PCM Interface

Table 10.12 describes the values for the PS Key (PSKEY_DIGITAL_AUDIO_CONFIG) that is used to set-up the digital audio interface. For example, to configure an I²S interface with 16-bit SD data set PSKEY_DIGITAL_CONFIG to 0x0406.

Bit	Mask	Name	Description
D[0]	0x0001	CONFIG_JUSTIFY_FORMAT	0 for left justified, 1 for right justified.
D[1]	0x0002	CONFIG_LEFT_JUSTIFY_DELAY	For left justified formats: 0 is MSB of SD data occurs in the first SCLK period following WS transition. 1 is MSB of SD data occurs in the second SCLK period.
D[2]	0x0004	CONFIG_CHANNEL_POLARITY	For 0, SD data is left channel when WS is high. For 1 SD data is right channel.
D[3]	0x0008	CONFIG_AUDIO_ATTEN_EN	For 0, 17 bit SD data is rounded down to 16 bits. For 1, the audio attenuation defined in CONFIG_AUDIO_ATTEN is applied over 24 bits with saturated rounding. Requires CONFIG_16_BIT_CROP_EN to be 0.
D[7:4]	0x00F0	CONFIG_AUDIO_ATTEN	Attenuation in 6 dB steps.
D[9:8]	0x0300	CONFIG_JUSTIFY_RESOLUTION	Resolution of data on SD_IN, 00=16 bit, 01=20 bit, 10=24 bit, 11=Reserved. This is required for right justified format and with left justified LSB first.
D[10]	0x0400	CONFIG_16_BIT_CROP_EN	For 0, 17 bit SD_IN data is rounded down to 16 bits. For 1 only the most significant 16 bits of data are received.

Table 10.12: PSKEY_DIGITAL_AUDIO_CONFIG


Figure 10.21: Digital Audio Interface Modes

The internal representation of audio samples within BlueCore5-Multimedia External is 16-bit and data on SD_OUT is limited to 16-bit per channel.

Symbol	Parameter	Min	Typ	Max	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz
t_{ch}	SCK high time	80	-	-	ns
t_{cl}	SCK low time	80	-	-	ns
t_{opd}	SCK to SD_OUT delay	-	-	30	ns
t_{ssu}	WS to SCK set-up time	20	-	-	ns
t_{sh}	WS to SCK hold time	20	-	-	ns
t_{isu}	SD_IN to SCK set-up time	20	-	-	ns
t_{ih}	SD_IN to SCK hold time	20	-	-	ns

Table 10.13: Digital Audio Interface Slave Timing

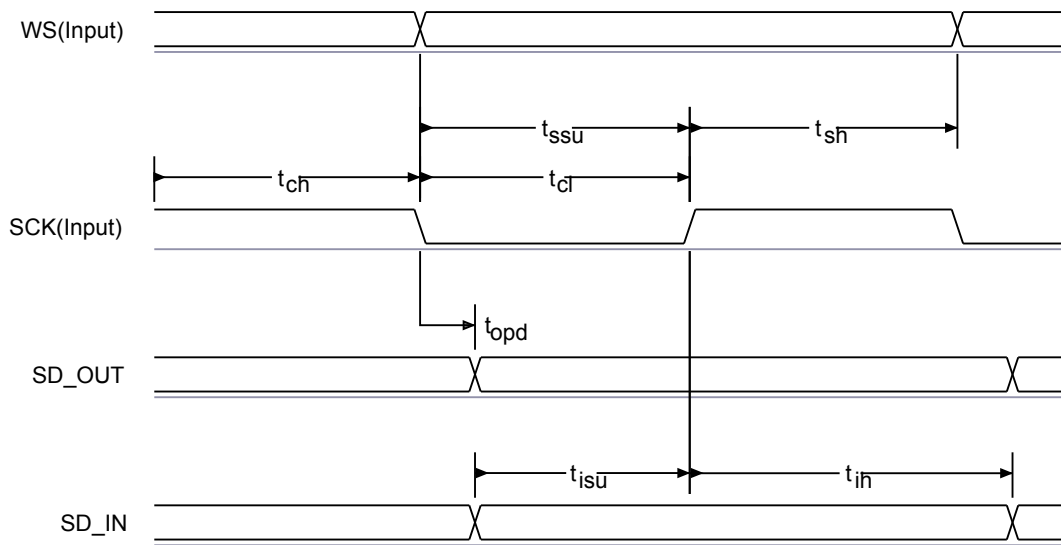


Figure 10.22: Digital Audio Interface Slave Timing

Symbol	Parameter	Min	Typ	Max	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz
t_{opd}	SCK to SD_OUT delay	-	-	30	ns
t_{spd}	SCK to WS delay	-	-	30	ns
t_{isu}	SD_IN to SCK set-up time	20	-	-	ns
t_{ih}	SD_IN to SCK hold time	10	-	-	ns

Table 10.14: Digital Audio Interface Master Timing

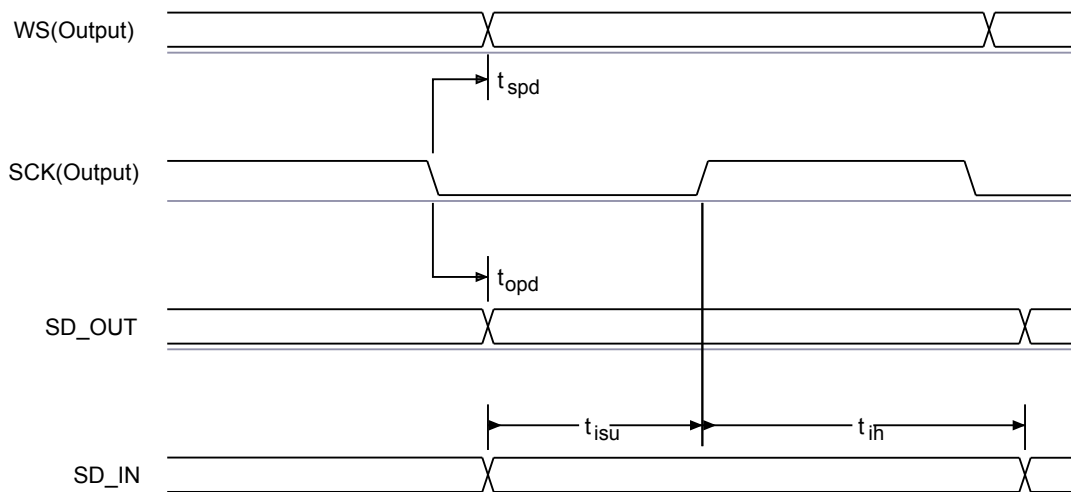


Figure 10.23: Digital Audio Interface Master Timing

11 Power Control and Regulation

11.1 Power Control and Regulation

BlueCore5-Multimedia External contains four regulators:

- Two high-voltage regulators, either of which may be used to generate a 1.8V rail for the chip I/Os
- Two low-voltage regulators which run in parallel to supply the 1.5V core supplies from the 1.8V rail.

The chip can be powered from a high voltage rail running a high voltage regulator and the low-voltage regulators in series, as shown in Figure 11.1. Alternatively, the chip can be powered directly from an external 1.8V rail, bypassing the high-voltage regulator, or from an external 1.5V rail omitting all regulators.

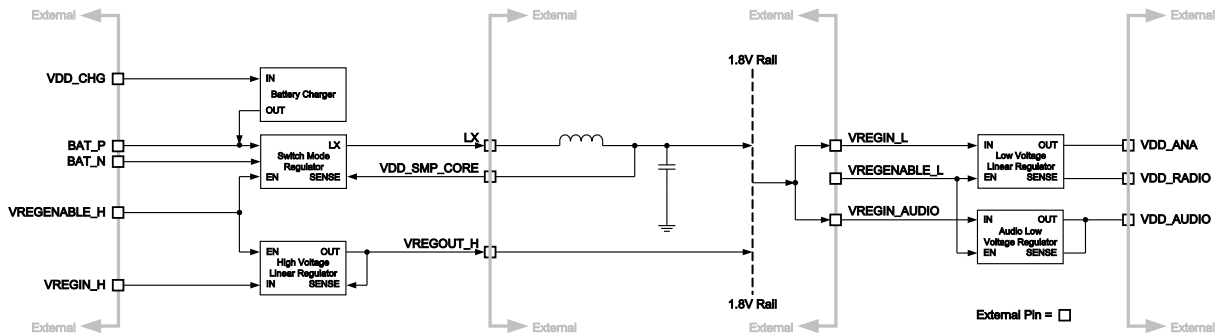


Figure 11.1: Voltage Regulator Configuration

11.2 Sequencing

The 1.5V supplies are VDD_ANA, VDD_LO, VDD_RADIO, VDD_AUDIO and VDD_CORE. CSR recommends that the 1.5V supplies are all powered at the same time. The order of powering the 1.5V supplies relative to the other I/O supplies (VDD_PIO, VDD_PADS and VDD_MEM) is not important. If the I/O supplies are powered before the 1.5V supplies all digital I/Os will have a weak pull-down irrespective of the reset state.

VDD_ANA, VDD_LO, VDD_RADIO and VDD_AUDIO should be connected directly to a 1.5V supply; a simple RC filter is recommended for VDD_CORE to reduce transients fed back onto the power supply rails.

The I/O supplies may be connected together or independently to supplies at an appropriate voltage. They should be decoupled.

11.3 External Voltage Source

If the 1.5V rails of BlueCore5-Multimedia External are supplied from an external voltage source, CSR recommends that VDD_LO, VDD_RADIO and VDD_AUDIO should have less than 10mV rms noise levels between 0 to 10MHz. Single tone frequencies are also to be avoided.

The transient response of any regulator used should be 20µs or less. It is essential that the power rail recovers quickly at the start of a packet, where the power consumption jumps to high levels (refer to the average current consumption specification of the regulator).

11.4 Switch-mode Regulator

The on-chip switch-mode 1.8V regulator, may be used to power a 1.8V rail which can drive the chip I/O supplies, and the input to the low-voltage regulators. An external filter circuit of a low-resistance 22µH series inductor with an effective series resistance in the range 0.4-0.8Ω, followed by a low ESR 4.7µF shunt capacitor is required between the LX terminal and the 1.8V supply rail, which should also be connected to the pin VDD_SMP_CORE. A decoupling capacitor of at least 2.2µF is required between BAT_P and BAT_N. It is essential that the series resistance of tracks between the BAT_P and BAT_N terminals, the filter and decoupling components, and the external voltage source are minimised to maintain high-efficiency power conversion, and low supply ripple.

The regulator may be enabled by the VREGENABLE_H pin, by the device firmware, or by the internal battery charger. The regulator is switched into a low-power pulse skipping mode when the device is sent into deep-sleep mode, or in reset.

When this regulator is not used the terminals BAT_P and LX must be grounded or left unconnected.

11.5 High-voltage Linear Regulator

As an alternative to the switch-mode regulator the on-chip high-voltage regulator may be used to power the 1.8V rail. A smoothing circuit using a low *equivalent-series resistor* (ESR) capacitor (2.2μF) and a resistor to ground (2.2Ω), should be connected to the output of the regulator, VREGOUT_H. Alternatively use a 2.2μF capacitor with an ESR of at least 2Ω.

The regulator may be enabled by the VREGENABLE_H pin, by the device firmware, or by the internal battery charger. The regulator is switched into a low power mode when the device is in deep-sleep mode, or in reset.

When this regulator is not used the terminals VREGOUT_H and VREGOUT_H must be left unconnected, or tied to ground.

11.6 Low-voltage Linear Regulator

The on-chip low-voltage regulator may be used to power all the chip 1.5V supplies except for VDD_AUDIO. The output of this regulator is connected internally to VDD_ANA, and must be connected externally to the other 1.5V supply pads. A smoothing circuit using a low ESR capacitor (2.2μF) and a resistor (2.2Ω) to ground should be connected to the output of the regulator. Alternatively use a 2.2μF capacitor with an ESR of at least 2Ω.

This regulator may be enabled by the VREGENABLE_L pin, by the device firmware, or by the internal battery charger.

The regulator is switched into a low power mode when the device is in deep-sleep mode, or in reset.

When this regulator is not used the terminal VREGIN_L must be left unconnected, or tied to VDD_ANA.

11.7 Low-voltage Audio Linear Regulator

The on-chip low-voltage audio regulator may be used to power VDD_AUDIO. The output of this regulator is connected internally to VDD_AUDIO. A smoothing circuit using a series connected 2.2μF low ESR capacitor and a 2.2Ω resistor to ground should be connected to the output of the regulator. Alternatively a 2.2μF capacitor with at least 2Ω ESR may be used.

This regulator may be enabled by the VREGENABLE_L pin or by the device firmware. The regulator is switched into a low power mode when no audio cells are enabled, or when the chip is in reset.

When this regulator is not used the terminal VREGIN_AUDIO must be left unconnected or tied to VDD_AUDIO.

11.8 Voltage Regulator Enable Pins

The regulator enable pins, VREGENABLE_H and VREGENABLE_L, are used to enable the BlueCore5-Multimedia External device if the on-chip regulators are being used. VREGENABLE_H enables both of the high-voltage regulators; VREGENABLE_L enables both of the low-voltage regulators.

Both pins are active high, with a logic threshold of around 1V, and both have weak pull-downs. They can tolerate voltages up to 4.9V, so both pins may be connected directly to a battery to enable the device.

When the voltage regulator enable pins are pulled high the active regulators are enabled, allowing the device to boot-up. The firmware is can then latch the regulators on and the regulator enable pins may be released.

The status of the VREGENABLE_H pin is available to firmware through an internal connection. VREGENABLE_H also works as an input line.

11.9 Battery Charger

The battery charger is a constant current / constant voltage charger circuit, and is suitable for lithium ion/polymer batteries only. It shares a connection to the battery terminal, BAT_P, with the switch-mode regulator. However it may be used in conjunction with either of the high-voltage regulators on the device.

The constant current level can be varied to allow charging of different capacity batteries.

The charger enters various states of operation as it charges a battery, as listed below. A full operational description is in *BlueCore5 Charger Description and Calibration Application Note*:

- Off : entered when charger disconnected.
- Trickle charge: entered when battery is below 2.9V.
- Fast charge constant current: entered when battery is above 2.9V.
- Fast charge constant voltage: entered when battery has reached selected V_{float} voltage, the charger switches mode to maintain the cell voltage at the V_{float} voltage by adjusting the constant charge current.
- Standby: this is the state when the battery is fully charged and no charging takes place.

When a voltage is applied to the charger input terminal VDD_CHG, and the battery is not fully charged, the charger operates and an LED connected to the terminal LED[0] illuminates. By default, until the firmware is running, the LED pulses at a low-duty cycle to minimise current consumption.

The battery charger circuitry auto-detects the presence of a power source, allowing the firmware to detect, using an internal status bit, when the charger is powered. Therefore when the charger supply is not connected to VDD_CHG, the terminal must be left open-circuit. The VDD_CHG pin when not connected must be allowed to float and not pulled to a power rail. When the battery charger is not enabled this pin may float to a low undefined voltage. Any DC connection increases current consumption of the device. Capacitive components may be connected such as diodes, FETs and ESD protection.

The battery charger is designed to operate with a permanently connected battery. If the application enables the charger input to be connected while the battery is disconnected, then the BAT_P pin voltage may become unstable. This in turn may cause damage to the internal switch-mode regulator. Connecting a 470µF capacitor to BAT_P limits these oscillations so preventing damage.

11.10 LED Drivers

BlueCore5-Multimedia External includes two pads dedicated to driving LED indicators. Both terminals may be controlled by firmware, while LED[0] can also be set by the battery charger.

The terminals are open-drain outputs, so the LED must be connected from a positive supply rail to the pad in series with a current limiting resistor.

It is recommended that the LED pad (LED[0] or LED[1] pins) are operated with a pad voltage below 0.5V. In this case the pad can be thought of as a resistor, R_{ON} . The resistance together with the external series resistor sets the current, I_{LED} , in the LED. The current is also dependent on the external voltage, VDD, shown in Figure 11.2.

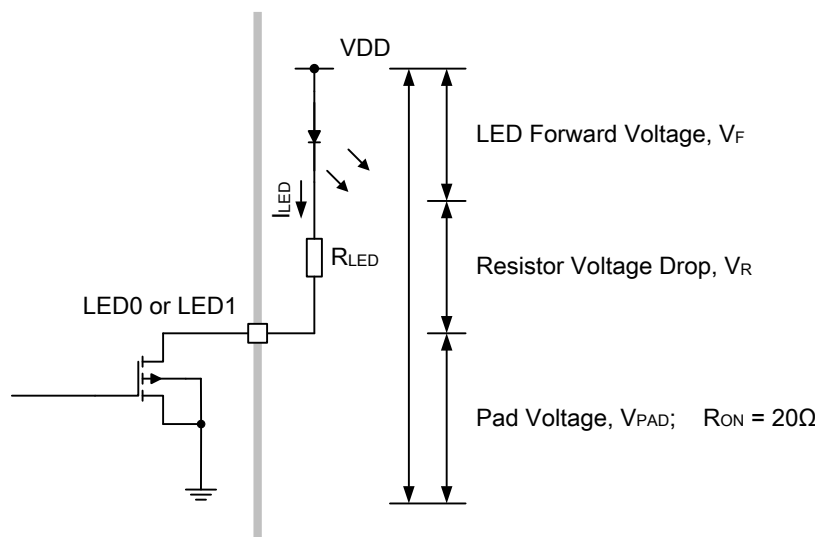


Figure 11.2: LED Equivalent Circuit

From Figure 11.2 it is possible to derive Equation 11.1 to calculate I_{LED} or if a known value of is required through the LED to give a specific luminous intensity then the value of R_{LED} can be calculated from Equation 11.2. Remember that for the LED[0] or LED[1] pad to act as resistance, the external series resistor, R_{LED} , needs to be such that the voltage drop across it, V_R , keeps V_{PAD} below 0.5V. Therefore Equation 11.3 also applies.

$$I_{LED} = \frac{VDD - V_F}{R_{LED} + R_{ON}}$$

Equation 11.1: LED Current

$$R_{LED} = \frac{VDD - V_F}{I_{LED}} - R_{ON}$$

Equation 11.2: LED Series Resistor

$$VDD = V_F + V_R + V_{PAD}$$

Equation 11.3: LED PAD Voltage

11.11 Reset (RST#)

BlueCore5-Multimedia External can be reset from several sources:

- RST# pin
- Power-on reset
- UART break character
- Software configured watchdog timer

The RST# pin is an active low reset and is internally filtered using the internal low frequency clock oscillator. A reset is performed between 1.5 and 4.0ms following RST# being active. CSR recommends that RST# be applied for a period greater than 5ms.

The power-on reset typically occurs when the VDD_CORE supply falls below 1.26V and is released when VDD_CORE rises above typically 1.31V. At reset the digital I/O pins are set to inputs for bi-directional pins and outputs are tri-state. Following a reset, BlueCore5-Multimedia External assumes the maximum XTAL_IN frequency, which ensures that the internal clocks run at a safe (low) frequency until BlueCore5-Multimedia External is configured for the actual XTAL_IN frequency. If no clock is present at XTAL_IN, the oscillator in BlueCore5-Multimedia External free runs, again at a safe frequency.

11.11.1 Digital Pin States on Reset

Table 11.1 shows the pin states of BlueCore5-Multimedia External on reset. Pull-up (PU) and pull-down (PD) default to weak values unless specified otherwise.

Pin Name / Group	I/O Type	No Core Voltage Reset	Full Chip Reset
USB_DP	Digital bi-directional	N/a	N/a
USB_DN	Digital bi-directional	N/a	N/a
UART_RX	Digital input with PD	PD	PD
UART_CTS	Digital input with PD	PD	PD
UART_TX	Digital bi-directional with PU	PU	PU
UART_RTS	Digital bi-directional with PU	PU	PU
SPI_MOSI	Digital input with PD	PD	PD
SPI_CLK	Digital input with PD	PD	PD
SPI_CS#	Digital input with PU	PU	PU
SPI_MISO	Digital tri-state output with PD	PD	PD
PCM_IN	Digital input with PD	PD	PD
PCM_CLK	Digital bi-directional with PD	PD	PD
PCM_SYNC	Digital bi-directional with PD	PD	PD
PCM_OUT	Digital tri-state output with PD	PD	PD
RST#	Digital input with PU	PU	PU
TEST_EN	Digital input with PD	PD	PD
PIO[15:0]	Digital bi-directional with PU/ PD	PD	PD

Table 11.1: Pin States on Reset

11.11.2 Status after Reset

The chip status after a reset is as follows:

- Warm reset: data rate and RAM data remain available
- Cold reset: data rate and RAM data not available

12 Example Application Schematic

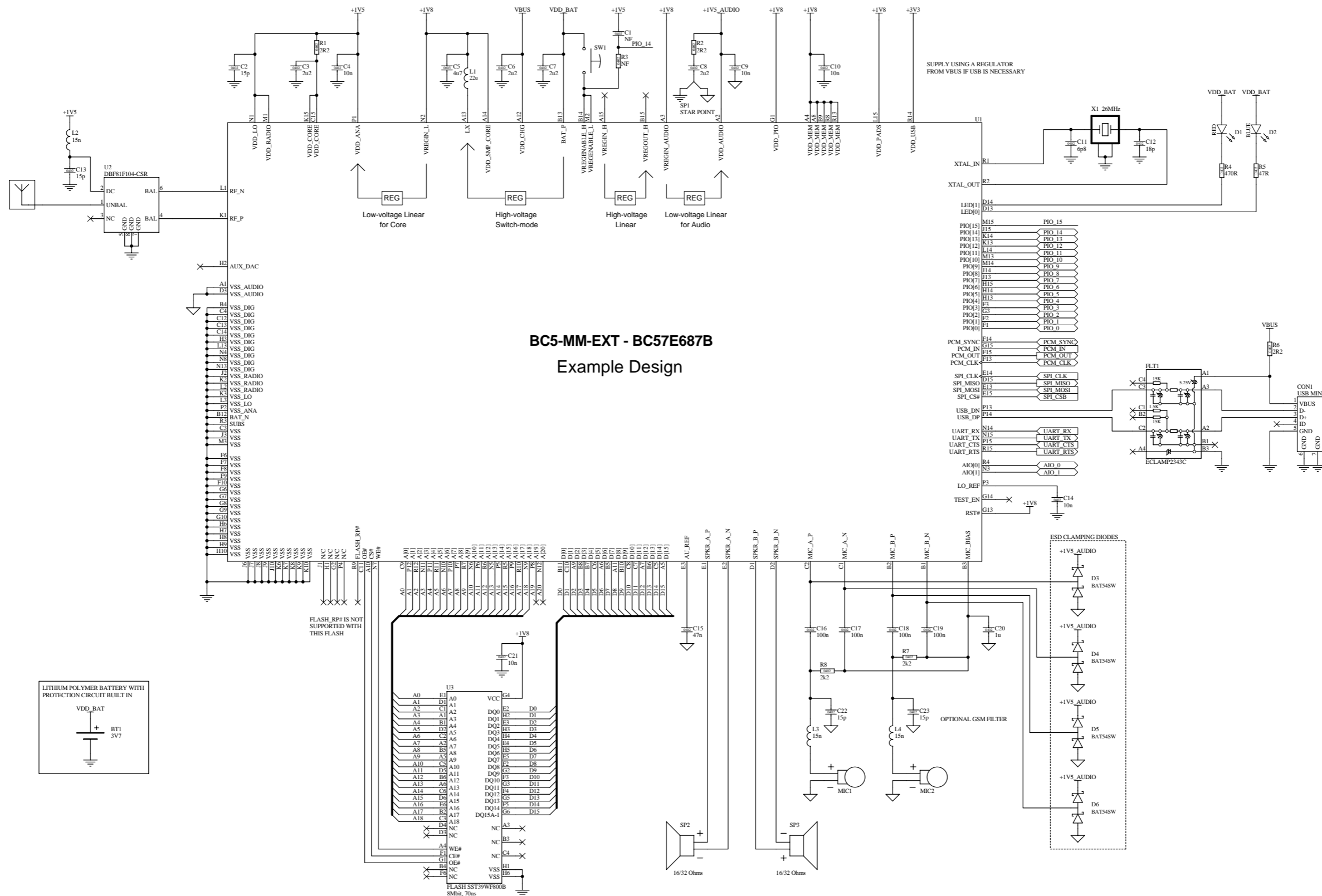


Figure 12.1: Example Application Schematic for BlueCore5-Multimedia External

13 Electrical Characteristics

13.1 Absolute Maximum Ratings

Rating		Min	Max	Unit
Storage Temperature		-40°C	+105°C	°C
Core supply voltage	VDD_LO, VDD_RADIO, VDD_ANA, VDD_CORE and VDD_AUDIO	-0.4	1.65	V
I/O voltage	VDD_PIO, VDD_PADS, VDD_MEM and VDD_USB	-0.4	3.6	V
Supply voltage	VREGIN_L_ANA and VREGIN_L_AUDIO	-0.4	2.7	V
	VREGIN_H, VREGENABLE_H and VREGENABLE_L	-0.4	4.9	V
	BAT_P, LED[0] and LED[1]	-0.4	4.4	V
	VDD_CHG	-0.4	6.5	V
Other terminal voltages		VSS-0.4	VDD+0.4	V

13.2 Recommended Operating Conditions

Operating Condition		Min	Typ	Max	Unit
Operating temperature range ^(a)		-30°C	-	+85°C	°C
Core supply voltage	VDD_LO, VDD_RADIO, VDD_ANA, VDD_CORE VDD_AUDIO	1.42	-	1.57	V
I/O supply voltage	VDD_PIO, VDD_PADS, VDD_MEM and VDD_USB	1.7	3.3	3.6	V

^(a) For radio performance over temperature refer to *BlueCore5-Multimedia External Performance Specification*

13.3 Input/Output Terminal Characteristics

Note:

For all I/O Terminal Characteristics:

- VDD_ANA, VDD_LO, VDD_RADIO, VDD_AUDIO and VDD_CORE are at 1.5V unless shown otherwise.
- VDD_PIO, VDD_PADS and VDD_MEM are at 1.8V unless shown otherwise.
- Current drawn into a pin is defined as positive; current supplied out of a pin is defined as negative.

13.3.1 Linear Regulator, High Voltage

Normal Operation	Min	Typ	Max	Unit
Input voltage	2.7	-	5.5 ^(a)	V
Output voltage ($I_{load} = 100\text{mA}$ / VREGIN_H = 3.0V)	1.70	1.80	1.95	V
Temperature coefficient	-300	0	300	ppm/°C
Output Noise ^{(b) (c)}	-	-	1	mV rms
Load regulation ($100\mu\text{A} < I_{load} < 200\text{mA}$), ΔV_{out}	-	-	5	mV
Settling time ^{(b) (d)}	-	-	50	μs
Maximum output current	200	-	-	mA
Minimum load current	5	-	-	μA
Drop-out voltage ($I_{load} = 200\text{mA}$)	-	-	900	mV
Quiescent current (excluding load, $I_{load} < 1\text{mA}$)	30	50	60	μA
Low Power Mode ^(e)				
Quiescent current (excluding load, $I_{load} < 100\mu\text{A}$)	11	15	21	μA
Disabled Mode ^(f)				
Quiescent current	-	-	-	μA

^(a) Short-term operation up to 5.5V is permissible without damage and without the output voltage rising sufficiently to damage the rest of BlueCore5-Multimedia External, but output regulation and other specifications are no longer guaranteed at input voltages in excess of 4.9V. 5.5V can only be tolerated for short periods.

^(b) Regulator output connected to 47nF pure and 4.7 μF 2.2 Ω ESR capacitors.

^(c) Frequency range 100Hz - 100kHz.

^(d) 10mA - 200mA pulsed load.

^(e) The regulator is in low power mode when the chip is in deep sleep mode, or in reset.

^(f) Regulator is in stand by mode when it is not enabled.

13.3.2 Linear Regulator, Low Voltage - ANA_REG

Normal Operation	Min	Typ	Max	Unit
Input voltage	1.70	1.80	1.95	V
Output voltage ($I_{load} = 70\text{mA}$ / $V_{REGIN_L} = 1.7\text{V}$)	1.42	1.50	1.57	V
Temperature coefficient	-300	0	300	ppm/°C
Output noise ^{(a) (b)}	-	-	1	mV rms
Load regulation ($100\mu\text{A} < I_{load} < 90\text{mA}$), ΔV_{out}	-	-	5	mV
Load regulation ($100\mu\text{A} < I_{load} < 115\text{mA}$), ΔV_{out}	-	-	25	mV
Settling time ^{(a) (c)}	-	-	50	μs
Maximum output current	115	-	-	mA
Minimum load current	5	-	100	μA
Drop-out voltage ($I_{load} = 115\text{mA}$)	-	-	300	mV
Quiescent current (excluding load, $I_{load} < 1\text{mA}$)	50	90	150	μA
Low Power Mode ^(d)				
Quiescent current (excluding load, $I_{load} < 100\mu\text{A}$)	5	8	15	μA
Disabled Mode ^(e)				
Quiescent current	1.5	2.5	3.5	μA

^(a) Regulator output connected to 47nF pure and 4.7 μF 2.2 Ω ESR capacitors

^(b) Frequency range 100Hz to 100kHz

^(c) 1mA to 115mA pulsed load

^(d) The regulator is in low power mode when the chip is in deep sleep mode, or in reset.

^(e) Regulator is in stand by mode when it is not enabled.

13.3.3 Linear Regulator, Low Voltage - AUDIO_REG

Normal Operation	Min	Typ	Max	Unit
Input voltage	1.70	1.80	1.95	V
Output voltage ($I_{load} = 70\text{mA}$ / $V_{REGIN_AUDIO} = 1.7\text{V}$)	1.42	1.50	1.57	V
Temperature coefficient	-300	0	300	ppm/°C
Output noise ^{(a) (b)}	-	-	1	mV rms
Load regulation ($100\mu\text{A} < I_{load} < 70\text{mA}$), ΔV_{out}	-	-	5	mV
Settling time ^{(a) (c)}	-	-	50	μs
Maximum output current	70	-	-	mA
Minimum load current	5	-	100	μA
Dropout voltage ($I_{load} = 70\text{mA}$)	-	-	300	mV
Quiescent current (excluding load, $I_{load} < 1\text{mA}$)	25	30	50	μA
Low Power Mode ^(d)				
Quiescent current (excluding load, $I_{load} < 100\mu\text{A}$)	5	8	15	μA
Disabled Mode ^(e)				
Quiescent current	1.5	2.5	3.5	μA

^(a) Regulator output connected to 47nF pure and 4.7 μF 2.2 Ω ESR capacitors

^(b) Frequency range 100Hz to 100kHz

^(c) 1mA to 70mA pulsed load

^(d) The regulator is in low power mode when when no audio circuits are enabled.

^(e) Regulator is in stand by mode when it is not enabled

13.3.4 Reset

Power-on Reset	Min	Typ	Max	Unit
VDD_CORE falling threshold	1.13	1.25	1.30	V
VDD_CORE rising threshold	1.20	1.30	1.35	V
Hysteresis	0.05	0.10	0.15	V

13.3.5 Regulator Enable

Switching Threshold	Min	Typ	Max	Unit
VREGENABLE_H				
Rising threshold	0.50	-	0.95	V
Falling threshold	0.35	-	0.80	V
Hysteresis	0.14	-	0.28	V
VREGENABLE_L				
Rising threshold	0.50	-	0.95	V
Falling threshold	0.35	-	0.80	V
Hysteresis	0.14	-	0.28	V

13.3.6 Switch-mode Regulator

Switch-mode Regulator	Min	Typ	Max	Unit
Input voltage	2.5	-	4.4	V
Output voltage ($I_{load} = 70 \text{ mA}$)	1.70	1.78	1.85	V
Temperature coefficient	-250	-	+250	ppm/°C
Normal Operation				
Output ripple	-	-	10	mV rms
Transient settling time ^(a)	-	-	50	µs
Maximum load current	200	-	-	mA
Conversion efficiency ($I_{load} = 70 \text{ mA}$)	-	90	-	%
Switching frequency ^(b)	-	1.333	-	MHz
Start-up current limit ^(c)	30	50	80	mA
Low Power Mode ^(d)				
Output ripple	-	-	1	mV rms
Transient settling time ^(e)	-	-	700	µs
Maximum load current	5	-	-	mA
Minimum load current	1	-	-	µA
Conversion efficiency ($I_{load} = 1 \text{ mA}$)	-	80	-	%
Switching frequency ^(f)	50	-	150	kHz
Disabled Mode				
Quiescent Current	-	-	1	µA

^(a) For step changes in load of 30-80mA and 80-30mA.

^(b) Locked to crystal frequency.

^(c) Current is limited on start-up to prevent excessive stored energy in the filter inductor.

^(d) Low power mode is entered and exited automatically when the chip enters/leaves Deep Sleep mode, or is in reset

^(e) 100µA to 1mA pulsed load

^(f) Defines minimum period between pulses. Pulses are skipped at low current loads.

Note:

The external inductor used with the switch-mode regulator must have an ESR in the range 0.3 - 0.7Ω:

- Low ESR < 0.3Ω causes instability.
- High ESR > 0.7Ω derates the maximum current.

13.3.7 Battery Charger

Battery Charger		Min	Typ	Max	Unit
Input voltage		4.5	-	6.5	V
Charging Mode (BAT_P rising to 4.2V)					
Supply current ^(a)		-	4.5	6	mA
Battery trickle charge current ^(b) ^(c)	Maximum setting (I-CTRL = 15)	-	14	-	mA
	Minimum setting (I-CTRL = 0)	-	4	-	mA
Maximum battery fast charge current (I-CTRL = 15) ^(d) ^(c)	Headroom ^(e) > 0.7V	-	140	-	mA
	Headroom = 0.3V	-	120	-	mA
Minimum battery fast charge current (I-CTRL = 0) ^(d) ^(c)	Headroom > 0.7V	-	40	-	mA
	Headroom = 0.3V	-	35	-	mA
Fast charge step size (I-CTRL = 0 to 15)	Spread ±17%	-	6.3	-	mA
Trickle charge voltage threshold		-	2.9	-	V
Float voltage (with correct trim value set), V _{FLOAT} ^(f)		4.17	4.2	4.23	V
Float voltage trim step size ^(f)		-	50	-	mV
Battery charge termination current, as a percentage of the fast charge current.		5	10	20	%
Standby Mode (BAT_P falling from 4.2V)					
Supply current ^(a)		-	1.5	2	mA
Battery current		-	-5	-	µA
Battery recharge hysteresis ^(g)		100	-	200	mV
Shutdown Mode (VDD_CHG too low or disabled by firmware)					
VDD_CHG under-voltage threshold	VDD_CHG rising	-	3.90	-	V
	VDD_CHG falling	-	3.70	-	V
VDD_CHG - BAT_P lockout threshold	VDD_CHG rising	-	0.22	-	V
	VDD_CHG falling	-	0.17	-	V
Supply current		-	1.5	2	mA
Battery current		-1	-	0	µA

^(a) Current into VDD_CHG - does not include current delivered to battery ($I_{VDD_CHG} - I_{BAT_P}$)

^(b) $BAT_P < \text{Float voltage}$

^(c) Charge current can be set in 16 equally spaced steps.

^(d) Trickle charge threshold $< BAT_P < \text{Float voltage}$

^(e) Where headroom = $VDD_CHG - BAT_P$.

^(f) Float voltage can be adjusted in 15 steps. Trim setting is determined in production test and must be loaded into the battery charger by firmware during boot-up sequence

^(g) Hysteresis of $(V_{FLOAT} - BAT_P)$ for charging to restart

13.3.8 Digital Terminals

Supply Voltage Levels		Min	Typ	Max	Unit
VDD _{PRE}	Pre-driver supply voltage	1.4	1.5	1.6	V
VDD	I/O supply voltage (post-driver), full spec.	3.0	3.3	3.6	V
	I/O supply voltage (post-driver), reduced spec.	1.7	-	3.0	V
Input Voltage Levels					
V _{IL} input logic level low		-0.3	-	0.25xVDD	V
V _{IH} input logic level high		0.625xVDD	-	VDD+0.3	V
V _{SCHMITT} Schmitt voltage		0.25xVDD	-	0.625xVDD	V
Output Voltage Levels					
V _{OL} output logic level low, I _{OL} = 4.0mA		0	-	0.125	V
V _{OH} output logic level high, I _{OH} = -4.0mA		0.75xVDD	-	VDD	V
Input and Tri-state Currents					
I _i input leakage current at V _{in} = VDD or 0V		-100	0	100	nA
I _{oz} tri-state output leakage current at V _o = VDD or 0V		-100	0	100	nA
With strong pull-up		-100	-40	-10	μA
With strong pull-down		10	40	100	μA
With weak pull-up		-5	-1.0	-0.2	μA
With weak pull-down		-0.2	+1.0	5.0	μA
C _I Input Capacitance		1.0	-	5.0	pF
Resistive Strength					
R _{puw} weak pull-up strength at VDD-0.2V		500k	-	2M	Ω
R _{pdw} weak pull-down strength at 0.2V		500k	-	2M	Ω
R _{pus} strong pull-up strength at VDD-0.2V		10k	-	50k	Ω
R _{pds} strong pull-down strength at 0.2V		10k	-	50k	Ω

13.3.9 LED Driver Pads

LED Driver Pads		Min	Typ	Max	Unit
Off current		-	1	2	μA
On resistance	V _{PAD} < 0.5V	-	20	33	Ω
On resistance, pad enabled by battery charger	V _{PAD} < 0.5V	-	20	50	Ω

13.3.10 USB

USB Terminals	Min	Typ	Max	Unit
VDD_USB for correct USB operation	3.1		3.6	V
Input Threshold				
V _{IL} input logic level low	-	-	0.3VDD_USB	V
V _{IH} input logic level high	0.7VDD_USB	-	-	V
Input Leakage Current				
VSS_DIG < VIN < VDD_USB ^(a)	-1	1	5	μA
C _I Input capacitance	2.5	-	10.0	pF
Output Voltage Levels to Correctly Terminated USB Cable				
V _{OL} output logic level low	0.0	-	0.2	V
V _{OH} output logic level high	2.8	-	VDD_USB	V

^(a) Internal USB pull-up disabled

13.3.11 Auxiliary ADC

Auxiliary ADC	Min	Typ	Max	Unit
Resolution	-	-	10	Bits
Input voltage range (LSB size = VDD_ANA/1023)	0	-	VDD_ANA	V
Accuracy (Guaranteed monotonic)	INL	-1	1	LSB
	DNL	0	1	LSB
Offset	-1	-	1	LSB
Gain Error	-0.8	-	0.8	%
Input Bandwidth	-	100	-	kHz
Conversion time	-	2.5	-	μs
Sample rate ^(a)	-	-	700	Samples/s

^(a) ADC is accessed through the VM function. The sample rate given is achieved as part of this function.

13.3.12 Auxiliary DAC

Auxiliary DAC	Min	Typ	Max	Unit
Resolution	-	-	8	Bits
Average output step size ^(a)	12.5	14.5	17.0	mV
Output Voltage		monotonic ^(a)		
Voltage range (I _O =0mA)	VSS_DIG	-	VDD_PIO	V
Current range	-10.0	-	+0.1	mA
Minimum output voltage (I _O =100μA)	0.0	-	0.2	V
Maximum output voltage (I _O =10mA)	VDD_PIO-0.3	-	VDD_PIO	V
High Impedance leakage current	-1	-	+1	μA
Offset	-220	-	+120	mV
Integral non-linearity ^(a)	-2	-	+2	LSB
Settling time (50pF load)	-	-	10	μs

^(a) Specified for an output voltage between 0.2V and VDD_PIO -0.2V. Output is high impedance when chip is in Deep Sleep mode.

13.3.13 Clocks

Clock Source	Min	Typ	Max	Unit
Crystal Oscillator				
Crystal frequency ^(a)	16.0	26.0	26.0	MHz
Digital trim range ^(b)	5.0	6.2	8.0	pF
Trim step size ^(b)	-	0.1	-	pF
Transconductance	2.0	-	-	mS
Negative resistance ^(c)	870	1500	2400	Ω
External Clock				
Input frequency ^(d)	12.0	26.0	52.0	MHz
Clock input level ^(e)	0.4	-	VDD_ANA	V pk-pk
Edge jitter (allowable jitter), at zero crossing	-	-	15	ps rms
XTAL_IN input impedance	-	≥10	-	kΩ
XTAL_IN input capacitance	-	≤4	-	pF

^(a) Integer multiple of 250kHz

^(b) The difference between the internal capacitance at minimum and maximum settings of the internal digital trim.

^(c) XTAL frequency = 16MHz; XTAL C₀ = 0.75pF; XTAL load capacitance = 8.5pF.

^(d) Clock input can be any frequency between 12.0MHz and 52MHz in steps of 250kHz plus CDMA/3G TCXO frequencies of 14.40, 15.36, 16.2, 16.8, 19.2, 19.44, 19.68, 19.8 and 38.4MHz.

^(e) Clock input can be either sinusoidal or square wave. If the peaks of the signal are below VSS_ANA or above VDD_ANA. A DC blocking capacitor is required between the signal and XTAL_IN.

13.3.14 Stereo CODEC - Analogue to Digital Converter

Analogue to Digital Converter						
Parameter	Conditions		Min	Typ	Max	Unit
Resolution			-	-	16	Bits
Input Sample Rate, F_{sample}			8	-	44.1	kHz
Signal to Noise Ratio, SNR	$f_{\text{in}} = 1\text{kHz}$ B/W = 20Hz→20kHz A-Weighted THD+N < 1% 150mV _{pk-pk} input	F_{sample}				
		8kHz	-	82	-	dB
		11.025kHz	-	81	-	dB
		16kHz	-	80	-	dB
		22.050kHz	-	79	-	dB
		32kHz	-	79	-	dB
		44.1kHz	-	78	-	dB
Digital Gain	Digital Gain Resolution = 1/32dB		-24	-	21.5	dB
Analogue Gain	Analogue Gain Resolution = 3dB		-3	-	42	dB
Input full scale at maximum gain (differential)			-	4	-	mV rms
Input full scale at minimum gain (differential)			-	800	-	mV rms
3dB Bandwidth			-	20	-	kHz
Microphone mode input impedance			-	6.0	-	k Ω
THD+N (microphone input) @ 30mV rms input			-	0.04	-	%

13.3.15 Stereo CODEC - Digital to Analogue Converter

Digital to Analogue Converter						
Parameter	Conditions	Min	Typ	Max	Unit	
Resolution		-	-	16	Bits	
Output Sample Rate, F_{sample}		8	-	48	kHz	
Signal to Noise Ratio, SNR	$f_{\text{in}} = 1\text{kHz}$ B/W = 20Hz→20kHz A-Weighted THD+N < 0.01% 0dBFS signal Load = 100k Ω	F_{sample}				
		8kHz	-	95	-	dB
		11.025kHz	-	95	-	dB
		16kHz	-	95	-	dB
		22.050kHz	-	95	-	dB
		32kHz	-	95	-	dB
		44.1kHz	-	95	-	dB
		48kHz	-	95	-	dB
Digital Gain	Digital Gain Resolution = 1/32dB	-24	-	21.5	dB	
Analogue Gain	Analogue Gain Resolution = 3dB	0	-	-21	dB	
Output voltage full scale swing (differential)		-	750	-	mV rms	
Allowed Load	Resistive	16(8)	-	OC	Ω	
	Capacitive	-	-	500	pF	
THD+N 100k Ω load		-	-	0.01	%	
THD+N 16 Ω load		-	-	0.1	%	
SNR (Load = 16 Ω , 0dBFS input relative to digital silence)		-	95	-	dB	

13.4 Power Consumption

13.4.1 16MHz Operation

Role	Connection	Audio Packet Type	Description	Current	Unit
-	Stand-by	-	Host connection	0.06	mA
-	Page Scan	-	Interval = 1280ms	0.45	mA
-	Inquiry and Page Scan	-	Inquiry scan = 1280ms Page scan = 1280ms	0.84	mA
Master	ACL	-	No traffic	4.4	mA
Master	ACL	-	File transfer TX	9.1	mA
Master	ACL	-	Sniff = 40ms	1.8	mA
Master	ACL	-	Sniff = 1280ms	0.19	mA
Master	eSCO	EV3	-	22	mA
Master	eSCO	EV3	Setting S1	24	mA
Master	eSCO	2 EV3	Setting S2	22	mA
Master	eSCO	2 EV3	Setting S3	17	mA
Master	eSCO	EV5	-	16	mA
Master	SCO	HV1	-	40	mA
Master	SCO	HV3	-	22	mA
Master	SCO	HV3	Sniff = 30ms	21	mA
Slave	ACL	-	No Traffic	15	mA
Slave	ACL	-	File transfer Rx	21	mA
Slave	ACL	-	Sniff = 40ms	1.6	mA
Slave	ACL	-	Sniff = 1280ms	0.26	mA
Slave	eSCO	EV3	-	25	mA
Slave	eSCO	EV3	Setting S1	27	mA
Slave	eSCO	2 EV3	Setting S2	27	mA
Slave	eSCO	2 EV3	Setting S3	24	mA
Slave	eSCO	EV5	-	22	mA
Slave	SCO	HV1	-	39	mA
Slave	SCO	HV3	-	26	mA
Slave	SCO	HV3	Sniff = 30ms	22	mA

13.4.2 32MHz Operation

Role	Connection	Audio Packet Type	Description	Current	Unit
-	Stand-by	-	Host connection	0.07	mA
-	Page Scan	-	Interval = 1280ms	0.50	mA
-	Inquiry and Page Scan	-	Inquiry scan = 1280ms Page scan = 1280ms	0.88	mA
Master	ACL	-	No traffic	4.4	mA
Master	ACL	-	File transfer TX	9.2	mA
Master	ACL	-	Sniff = 40ms	1.9	mA
Master	ACL	-	Sniff = 1280ms	0.20	mA
Master	eSCO	EV3	-	23	mA
Master	eSCO	EV3	Setting S1	24	mA
Master	eSCO	2 EV3	Setting S2	22	mA
Master	eSCO	2 EV3	Setting S3	17	mA
Master	eSCO	EV5	-	17	mA
Master	SCO	HV1	-	42	mA
Master	SCO	HV3	-	23	mA
Master	SCO	HV3	Sniff = 30ms	22	mA
Slave	ACL	-	No Traffic	15	mA
Slave	ACL	-	File transfer RX	21	mA
Slave	ACL	-	Sniff = 40ms	1.7	mA
Slave	ACL	-	Sniff = 1280ms	0.26	mA
Slave	eSCO	EV3	-	26	mA
Slave	eSCO	EV3	Setting S1	27	mA
Slave	eSCO	2 EV3	Setting S2	28	mA
Slave	eSCO	2 EV3	Setting S3	25	mA
Slave	eSCO	EV5	-	22	mA
Slave	SCO	HV1	-	42	mA
Slave	SCO	HV3	-	28	mA
Slave	SCO	HV3	Sniff = 30ms	22	mA

13.4.3 Kalimba DSP and CODEC Typical Average Current Consumption

DSP	Average	Unit
DSP core (including PM memory access)	Minimum (NOP)	0.11
	Maximum (MAC)	0.32
DSP memory access (DM1 or DM2)	0.08	mA/MIPS

13.4.4 Typical Peak Current at 20°C

Device Activity / State	Typ	Unit
Peak current during cold boot	45	mA
Master TX peak current	45	mA
Master RX peak current	45	mA
Slave TX peak current	45	mA
Slave RX peak current	45	mA

13.4.5 Conditions

- Host interface = UART
- Baud rate = 115200
- Supply = 1.8V in to VREGIN_L and VREGIN_AUDIO
- AFH switched OFF
- No audio load
- RF output power = 0dBm
- VM OFF
- eSCO settings:
 - EV3 and EV5 = no retry
 - Setting S1 = optimised for power consumption
- Firmware build ID = 4508

14 RoHS Statement with a List of Banned Materials

14.1 RoHS Statement

BlueCore5-Multimedia External where explicitly stated in this Data Sheet meets the requirements of Directive 2002/95/EC of the European Parliament and of the Council on the *Restriction of Hazardous Substance* (RoHS).

14.1.1 List of Banned Materials

The following banned substances are not present in BlueCore5-Multimedia External which is compliant with RoHS:

- Cadmium
- Lead
- Mercury
- Hexavalent chromium
- PBB (Polybrominated Bi-Phenyl)
- PBDE (Polybrominated Diphenyl Ether)

In addition, BlueCore5-Multimedia External is free from the following substances:

- PVC (Poly Vinyl Chloride)

15 CSR Bluetooth Software Stack

BlueCore5-Multimedia External is supplied with Bluetooth v2.1 + EDR specification compliant stack firmware, which runs on the internal RISC microcontroller.

The BlueCore5-Multimedia External software architecture allows Bluetooth processing and the application program to be shared in different ways between the internal RISC microcontroller and an external host processor (if any). The upper layers of the Bluetooth stack, above the *Host Controller Interface (HCI)*, can be run either on-chip or on the host processor.

15.1 BlueCore HCI Stack

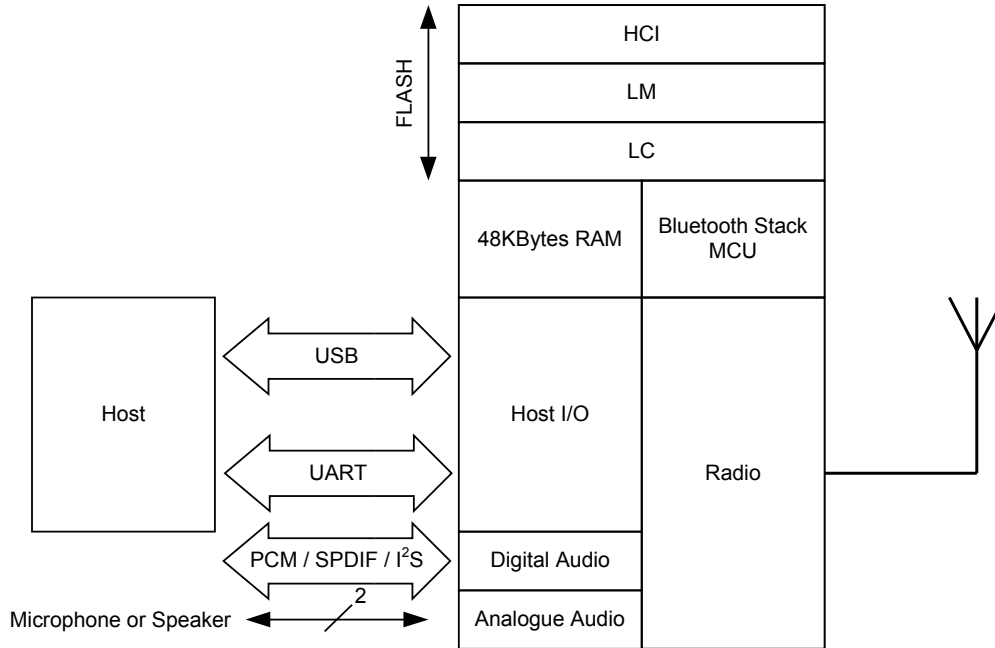


Figure 15.1: BlueCore HCI Stack

In the implementation shown in Section 15.1 the internal processor runs the Bluetooth stack up to the HCI. The Host processor must provide all upper layers including the application.

15.1.1 Key Features of the HCI Stack: Standard Bluetooth Functionality

Bluetooth v2.1 + EDR specification mandatory functionality:

- Secure simple pairing
- Sniff subrating
- Encryption pause resume
- Packet boundary flags
- Encryption

Optional Bluetooth v2.1 + EDR specification functionality supported:

- Extended inquiry response

Bluetooth v2.0 + EDR specification mandatory functionality:

- *Adaptive frequency hopping (AFH)*, including classifier
- Faster connection - enhanced inquiry scan (immediate FHS response)
- LMP improvements
- Parameter ranges

Optional Bluetooth v2.0 + EDR specification functionality supported:

- AFH as Master and Automatic Channel Classification
- Fast Connect - Interlaced Inquiry and Page Scan plus RSSI during Inquiry
- *Extended SCO* (eSCO), eV3 +CRC, eV4, eV5
- SCO handle
- Synchronisation

The firmware was written against the Bluetooth v2.1 + EDR specification:

- Bluetooth components:
 - Baseband (including LC)
 - LM
 - HCI
- Standard UART HCI Transport Layers
- All standard Bluetooth radio packet types
- Full Bluetooth data rate, enhanced data rates of 2 and 3Mbps
- Operation with up to seven active slaves²
- Scatternet v2.5 operation
- Maximum number of simultaneous active ACL connections: 7
- Maximum number of simultaneous active SCO connections: 3³
- Operation with up to three SCO links, routed to one or more slaves
- All standard SCO voice coding, plus transparent SCO
- Standard operating modes: Page, Inquiry, Page-Scan and Inquiry-Scan
- All standard pairing, authentication, link key and encryption operations
- Standard Bluetooth power saving mechanisms: Hold, Sniff and Park modes, including Forced Hold
- Dynamic control of peers' transmit power via LMP
- Master/Slave switch
- Broadcast
- Channel quality driven data rate
- All standard Bluetooth test modes

The firmware's supported Bluetooth features are detailed in the standard *Protocol Implementation Conformance Statement* (PICS) documents, available from <http://www.csr.com>.

15.1.2 Key Features of the HCI Stack: Extra Functionality

The firmware extends the standard Bluetooth functionality with the following features:

- Supports *BlueCore Serial Protocol* (BCSP), a proprietary, reliable alternative to the standard Bluetooth UART Host Transport
- Supports *H4 Deep Sleep* (H4DS), a proprietary alternative to the standard Bluetooth UART Host Transport, supporting Deep Sleep for low-power applications
- Provides a set of approximately 50 manufacturer-specific HCI extension commands. This command set, called *BlueCore Command* (BCCMD), provides:
 - Access to the chip's general-purpose PIO port
 - The negotiated effective encryption key length on established Bluetooth links
 - Access to the firmware's random number generator
 - Controls to set the default and maximum transmit powers; these can help minimise interference between overlapping, fixed-location piconets
 - Dynamic UART configuration
 - Bluetooth radio transmitter enable/disable. A simple command connects to a dedicated hardware switch that determines whether the radio can transmit.
- The firmware can read the voltage on a pair of the chip's external pins. This is normally used to build a battery monitor
- A block of BCCMD commands provides access to the chip's *Persistent Store* (PS) configuration database. The database sets the device's Bluetooth address, Class of Device, Bluetooth radio (transmit class) configuration, SCO routing, *link manager* (LM), etc.
- A UART break condition can be used in three ways:

² This is the maximum allowed by Bluetooth v2.1 + EDR specification.

³ BlueCore5-Multimedia External supports all combinations of active ACL and SCO channels for both master and slave operation, as specified by the Bluetooth v2.1 + EDR specification.

- Presenting a UART break condition to the chip can force the chip to perform a hardware reboot
- Presenting a break condition at boot time can hold the chip in a low power state, preventing normal initialisation while the condition exists
- With BCSP, the firmware can be configured to send a break to the host before sending data. (This is normally used to wake the host from a Deep Sleep state.)
- A block of Bluetooth radio test or BIST commands allows direct control of the chip's radio. This aids the development of modules' radio designs, and can be used to support Bluetooth qualification.
- Hardware low power modes: Shallow Sleep and Deep Sleep. The chip drops into modes that significantly reduce power consumption when the software goes idle.
- SCO channels are normally routed via HCI (over BCSP). However, up to three SCO channels can be routed over the chip's (at the same time as routing any remaining SCO channels over HCI).

Note:

Always refer to the Firmware Release Note for the specific functionality of a particular build.

15.2 Host-Side Software

BlueCore5-Multimedia External can be ordered with companion host-side software:

- BlueCore5-PC includes software for a full Windows 98/ME, Windows 2000 or Windows XP Bluetooth host-side stack together with IC hardware described in this document.
- BlueCore5-Mobile includes software for a full host-side stack designed for modern ARM chip-based mobile handsets together with IC hardware described in this document.

15.3 CSR Development Systems

CSR's BlueLab Multimedia and BlueTunes (BTN-002-2A) development kits are available to allow the evaluation of the BlueCore5-Multimedia External hardware and software, and as toolkits for developing on-chip and host software.

15.4 eXtension

A wide range of software options is available from 3rd parties through the CSR eXtension partner program, see <http://www.csr.com/eXtension>.



16 Ordering Information

Interface Version	Package			Order Number
	Type	Size	Shipment Method	
UART and USB	TFBGA 169-ball (Pb free)	8 x 8 x 1.2mm, 0.5mm pitch	Tape and reel	BC57E687B-ITB-E4 ^(a)

^(a) Until BC57E687B reaches **Production** status, engineering samples order number applies. This is BC57E687B-ES-GTB-E, with no minimum order quantity.

Note:

At **Production** status **Minimum Order Quantity** is 2kpcs taped and reeled.

16.1 Tape and Reel Information

For tape and reel packing and labelling see *IC Packing and Labelling Specification*.

16.1.1 Tape Orientation

The general orientation of the TFBGA in the tape is as shown in Figure 16.1.

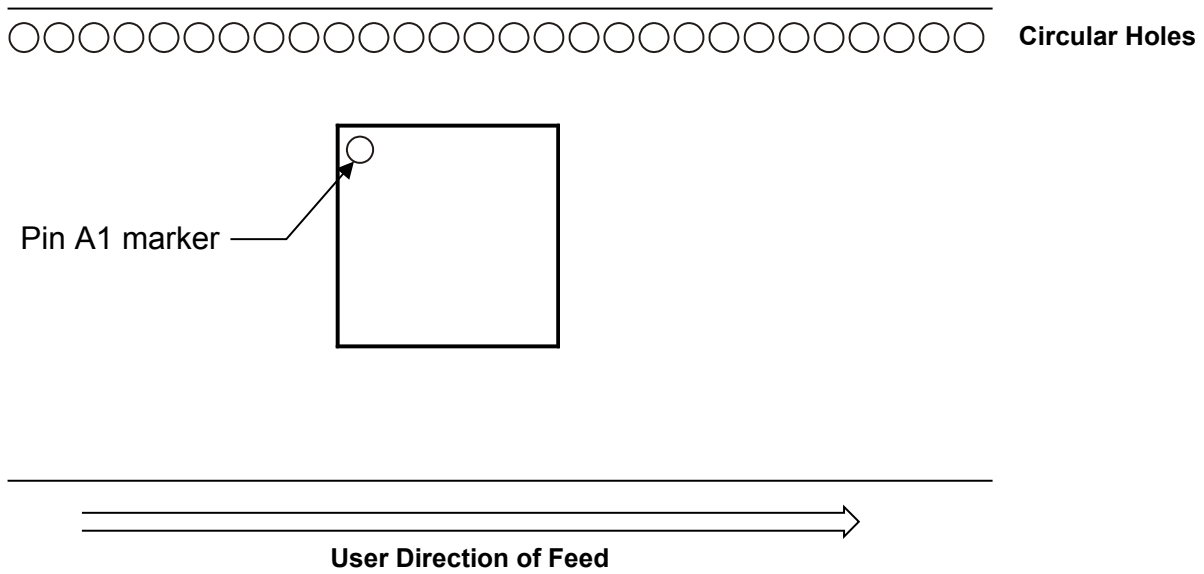
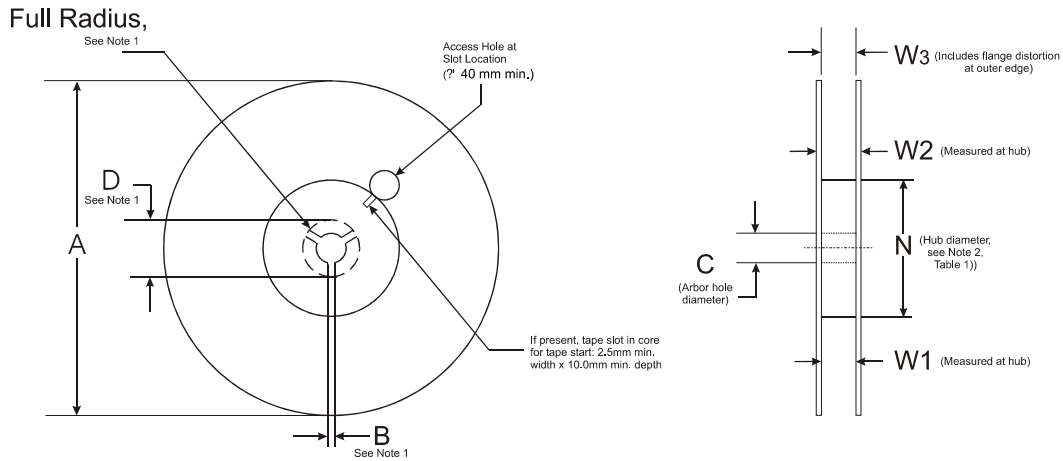


Figure 16.1: Tape and Reel Orientation

16.1.2 Reel Information

Reel dimensions

(All dimensions in millimeters)



Notes:
 1. Drive spokes optional; if used, dimensions B and D shall apply.
 2. Maximum weight of reel and contents 13.6kg.

Figure 16.2: Reel Dimensions

Package Type	Tape Width	A Max	B	C	D Min	N Min	W1	W2 Max	W3		Units
									Min	Max	
8 x 8 x 1.2mm TFBGA	16	332	1.5	13.0 (+0.5/-0.2)	20.2	50	16.4 (+2.0/-0.0)	22.4	16.4	19.1	mm

16.2 Moisture Sensitivity Level (MSL)

BlueCore5-Multimedia External is qualified to MSL3 in accordance with JEDEC J-STD-020.

17 Document References

Document	Reference, Date
<i>Core Specification of the Bluetooth System</i>	v2.1 + EDR, 26 July 2007
<i>Test Suite Structure (TSS) and Test Purposes (TP) System Specification 1.2/2.0/2.0 + EDR/ 2.1/2.1 + EDR</i>	RF.TS/2.1.E.0, 27 December 2006
<i>Universal Serial Bus Specification</i>	v2.0, 27 April 2000
<i>Selection of PC EEPROMS for Use with BlueCore</i>	bcore-an-008P, 30 September 2003
<i>IC Packing and Labelling Specification</i>	CS-112584-SPP, January 2007
<i>Moisture / Reflow Sensitivity Classification for Nonhermitic Solid State Surface Mount Devices</i>	IPC / JEDEC J-STD-020
<i>BlueCore5-Multimedia External Performance Specification</i>	CS-114110-SPP, 2007
<i>BlueCore5 Charger Description and Calibration Procedure Application Note</i>	CS-113282-ANP, 2007
<i>BlueCore5-Multimedia External Recommendations for ESD Protection</i>	CS-114058-ANP, 2007
<i>Typical Solder Reflow Profile for Lead-free Device</i>	CS-116434-ANP, 2007
<i>Bluetooth and IEEE 802.11 b/g Co-existence Solutions Overview</i>	bcore-an-066P, May 2005

Terms and Definitions

Term	Definition
ADC	Analogue to Digital Converter
AFH	Adaptive Frequency Hopping
AGC	Automatic Gain Control
BCCMD	BlueCore Command
BCSP	BlueCore Serial Protocol
BIST	Built-In Self Test
BlueCore™	Group term for CSR's range of Bluetooth wireless technology chips
Bluetooth®	Set of technologies providing audio and data transfer over short-range radio connections
BMC	Burst Mode Controller
CDMA	Code Division Multiple Access
CODEC	COder DECoder
CRC	Cyclic Redundancy Check
CSR	Cambridge Silicon Radio
CVSD	Continuous Variable Slope Delta Modulation
DAC	Digital to Analogue Converter or Device Access Code
dBm	Decibels relative to 1mW
DC	Direct Current
DDS	Direct Digital Synthesis
DSP	Digital Signal Processor
EDR	Enhanced Data Rate
EMC	Electromagnetic Compatibility
EMI	Electromagnetic Interference
eSCO	Extended SCO
ESD	Electro-Static Discharge
ESR	Equivalent Series Resistance
FHS	Frequency Hop Synchronisation
GCI	General Circuit Interface
GFSK	Gaussian Frequency Shift Keying
GSM	Global System for Mobile communications
H4DS	H4 Deep Sleep
HCI	Host Controller Interface
IC	Integrated Circuit
IIR	Infinite Impulse Response (filter)
I/O	Input/Output
I ² C	Inter-Integrated Circuit
I ² S	Inter-Integrated Circuit Sound
IF	Intermediate Frequency
LCD	Liquid-Crystal Display
LED	Light Emitting Diode
LJ	Left-Justified
LM	Link Manager

Term	Definition
LMP	Link Manager Protocol
LNA	Low Noise Amplifier
LSB	Least-Significant Bit
MAC	Medium Access Control
MCU	Micro Controller Unit
MIPS	Million Instructions Per Second
MMU	Memory Management Unit
NSMD	Non Solder Mask Defined
PA	Power Amplifier
PCM	Pulse Code Modulation
PIO	Programmable Input Output
PS	Persistent Store
PS Key	Persistent Store Key
RAM	Random Access Memory
RF	Radio Frequency
RISC	Reduced Instruction Set Computer
RJ	Right-Justified
RSSI	Received Signal Strength Indication
SBC	Sub-band Coding
SCO	Synchronous Connection-Oriented
SNR	Signal-to-Noise Ratio
SPI	Serial Peripheral Interface
SPDIF	Sony/Philips Digital InterFace (also IEC 958 type II, part of IEC-60958). An interface designed to transfer stereo digital audio signals between various devices and stereo components with minimal loss.
TCXO	Temperature Compensated crystal Oscillator
UART	Universal Asynchronous Receiver Transmitter
USB	Universal Serial Bus
VCO	Voltage Controlled Oscillator
VM	Virtual Machine
VoIP	Voice over Internet Protocol
W-CDMA	Wideband Code Division Multiple Access

Document History

Revision	Date	Change Reason
Issue 1	08 NOV 05	Original publication of this document.
Issue 2	09 MAY 06	Updated information. Structure changed.
Issue 3	09 AUG 06	Updated application schematic. Internal Release Only
Issue 4	11 OCT 06	Part number moved to REV B i.e. BC57E687A to BC57E687B. Document Number becomes CS-101568-DS (Issue 4)
Issue 5	06 FEB 07	Removal of erroneous content in I ² C section that is only available on BlueCore5 devices containing a FM Radio module. Updated block diagram Table footnote additions in RF characteristics Stereo CODEC updates Added Tape and Reel information references
Issue 6	05 APR 07	Change in VDD_PIO, VDD_PADS and VDD_MEM Absolute and Recommended values. RF Characterisation transferred in to CSR document <i>BlueCore5-Multimedia External Performance Specification</i> Updates to Audio section including addition of sidetone information Modifications to Electrical Characteristics which includes regulators IIR Filter information added RX_N and RX_P ports removed Updated example application schematic
Issue 7	24 AUG 07	Updated example application schematic. Updated Tape and Reel information. Added power consumption. Added microphone bias description. Various parameter updates including I ² S and regulator enables. Updated syntax and structure. Support for Bluetooth Specification v2.1 + EDR
Issue 8	25 SEP 07	Document number corrected and editorial updates Updated description of pull-up and pull-down resistor on Digital Terminals in Electrical Characteristics Updated Power Control and Regulation section, incorrectly used VSS_ANA changed to VDD_ANA. Reset table updated for correct direction of PIOs at reset. Corrected power consumption table, Deep Sleep should be Stand-by. Updated CSR Software Stacks to include Bluetooth Specification v2.1 + EDR options Updated example application schematic. Solder profile now references external document Send feedback on this document to Comments@csr.com